

FT7150

Super In-Cell IC Integrates TFT LCD Driver and Touch Panel Controller Into a Single Chip. Cascade Function for Amorphous TFT-LCDs and Touch Controller Support Real Multi-Touch Capability.

Preliminary

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1. GENERAL DESCRIPTION

FT7150 highly integrates TFT LCD driver and Super in-cell Touch controller. Combined with Super in-cell panel technology, FT7150 provides high performance and high-quality human-machine interactive solutions for tablet display terminals.

FT7150 also support cascade function to achieve higher resolution and smaller sensing pitch, the LCD driver in FT7150 supports 1-chip function maximum resolutions WQXGA MUX 1:1 800RGBx2560 ; MUX 1:2/Dual-gate 1280RGBx1600(DP 60Hz) resolution, and the LCD driver in FT7150 also supports 2-chip cascade function maximum resolutions WQXGA MUX 1:1 1600RGBx2560 ; MUX 1:2/Dual-gate 2560RGBx1600(DP 60Hz) resolution, provides the number of colors up to 16.7M. In addition, FT7150 uses RGB colors each with independently adjustable Gamma correction, 1-dot / 2-dot / 1+2-dot / 1-Column / 2-Column / Zigzag liquid crystal reversion mode and CABC / CE image processing technology, so that it can achieve high resolution, multi-color, high-quality display characteristics.

The touch panel controller of FT7150 uses a 32-bit high-performance single-cycle instruction-set MCU. With its built-in high-speed high-performance hardware-accelerated computing modules, it provides superior data processing capabilities. FT7150 AFE can support up to 800 channels for touch sensing. Combined with Time-Division and Area-Division scanning technology, it greatly reduces the scanning time of touch panel, so that the maximum of point reporting rate could up to 120Hz. With Focaltech's patented drive technology and algorithms, the touch controller has excellent waterproof performance, strong anti-noise-and-interference ability and high signal to noise ratio. Its touch experience can achieve up to 10 points..

In addition, the external Flash of FT7150 can store not only the firmware used for Touch controller, but also the Initial code of LCD driver. After loading the initial code through the external Flash, the HOST only needs to send out "Sleep out" and "Display on" to turn on the LCD. This will greatly simplify the operation of the HOST to LCD, making the configuration process both flexible and simple. Furthermore, when ESD occurs, HOST reloads Initial code directly from Flash, greatly improving the IC's ESD capability.

2. FEATURES

2.1. Touch Function feature list

- **32-bit embedded single-cycle instruction-set MCU**
 - Built-in hardware acceleration module
 - Program storage size: 112K Byte SRAM
 - Data storage size: 96K Byte SRAM
- **Super self-capacitance detection technology**
- **Supports up to 800 SX channels**
- **Supports up to 10pF capacitive sensing per channel**
- **10-point Real Touch**
- **Anti-floating**
- **Anti-power interference**
- **Anti-stress from external**
- **Anti-RF interference**
- **Point reporting rate up to 120Hz**
- **I2C data communication interface**
- **SPI data communication interface**
- **Support THP(Touch Host Processing)**

2.2. Display Function feature list

- **Support HD+ a-Si TFT LCD Driver without GRAM**
- **Support Flash initialization with initial code inside**
- **Support 120Hz/90Hz/60Hz/30Hz/15Hz frame rate & VESA DSC 3X decode**
- **Support Resolution :**
 - 2-chip with cascade : 2560RGBx1600(DP 60Hz, MUX 1:2/Dual-gate) ; 1600RGB x (2560, others) ; 1536RGB x (2048, others) ; 1440RGB x (2560, others) ; 1280RGB x (2048, others) ; 1200RGB x (1920, others) ; 1080RGB x (1920, others)
 - 1 chip : 1280RGBx1600(DP 60Hz, MUX 1:2/Dual-gate) ; 800RGB x (1280, others) ; 768RGB x (1366, others) ; 720RGB x (1280, others) ; 600RGB x (1024, others) ; 540RGB x (960, others)

*Note: Please contact our sales for further help if your resolution is not listed here.
- **Color Display**
 - Full color mode : 16.7M (24-bit, 8(R):8(G):8(B))
- **Support the features that refresh the display function for N-lines with an adjusted pause of 0 ~ 400us (for touch scan) and then continue to refresh the display function for N lines**
- **Display features**
 - Supports independently adjustable RGB gamma correction
 - Support 1-dot / 2-dot and 1-Column / 2-Column / Zigzag LCD reversion modes
 - Support Slew Rate control on Source driver
- **Built-in Focal CleverColor Image processing functions**
 - CleverColor – Color Enhancement_{opt1.0}
 - CleverColor – CABC_{opt1.0}
 - CleverColor – AIE_{opt1.0}
 - CleverColor – Digital Gamma_{opt1.0}
 - CleverColor – Contrast_{opt1.0}
 - CleverColor – WA_{opt1.0}
 - CleverColor – Sharpness Enhancement_{opt1.0} (Not Support in Cascade Mode)
- **Interface**
 - MIPI DPHY Interface (DPHY V1.1 with 2/3/4 Lane), Max Speed 1.1Gbps
 - MIPI Display Serial Interface (DSI-2 V1.0)
 - MIPI Display Command Set (DCS V1.3)
 - LVDS interface (RGB24bit data format) , Max Speed 770 Mbps
- **On Chip function**
 - Built-in VCOM Generator
 - Provide OTP to store VCOM/ID1/ID2/ID3
 - Save command setting in external flash memory
 - Built-in Oscillator for display clock generation
 - On module checksum checking
 - Built-in 22 GOUT signals (GOUT1 ~ GOUT22) on each side of the chip, providing the drive signals to the GIP circuit on the LCD panel

- Temperature Compensation for VGHO/VGLO/VCOM
- **Output voltage levels**
 - Source output voltage level: (GVDDP~+0.1V) and (-0.1V~GVDDN)
 - Gamma voltage range: GVDDP: 3.75V ~ 6.3V, GVDDN: -3.75V~-6.3V
 - Positive gate driver output voltage range: 5.8V~6.2V;7.8V~20V
 - Negative gate driver output voltage range: -5.3V~-18V
 - Common electrode output voltage level VCOM: +0.3V ~ -3.85V
- **Supply Voltage Range**
 - I/O and logical circuit power: 1.65V ~ 1.95V (MIPI), 2.7V~3.6V(LVDS)
 - Positive Analog supply voltage range: 4.5V ~ 6.5V
 - Negative Analog supply voltage range: -4.5V ~ -6.5V
- **Support OTP Multiple Program Times**
 - ID for 5 times programmable
 - GVDD for 2 times programmable
 - Gamma for 2 times programmable
 - VCOM for 8 times programmable
 - User Info for 5 times programmable
 - Please refer to the application note to get detailed information about multiple program times.
- **Support Power Mode:**
 - 3 Power Mode: VDDI / AVDD / AVEE
 - 4 power Mode: VDDI / AVDD / AVEE / VDD

3.1.3. Embedded MCU

MCU and SOC subsystems complete the control, data processing, LCD operation and coordination, HOST communication and other functions of the whole touch systems. Firmware, stored in external flash memory, can be loaded into the internal SRAM by HOST via the I2C or SPI interface. Firmware can also be download from HOST through SPI interface without external FLASH required.

3.1.4. I2C/SPI Serial Interface

FT7150 can support I2C or SPI for touch communication with HOST. The control interface is consisted of two signals, INT and TP_EXT_RSTN. Whenever there is an effective touch sensed on the touch screen, touch controller will send data transfer request to the HOST via INT port, and complete the point report to the HOST. HOST can communicate with FT7150 via I2C. HOST can also reset Touch controller through TP_EXT_RSTN port.

3.1.5. LCD/TP I2C Interface

FT7150 can support LCD/TP I2C to set LCD initial code to the FT7150 IC.

3.1.6. External Flash

External Flash, used to store the Firmware, internal voltage regulator generates 1.8V power supply, which is to provide power to an external 1.8V Flash. In non-Flash application, Firmware could be downloaded from HOST through SPI interface.

3.1.7. Watch Dog

Watchdog clock is used to ensure the stability of the chip when in operation

3.1.8. Timing controller

The timing controller generates timing signals for the operations of internal circuits such as gate/source/vcom/ touch scan output timing.

3.1.9. Source driver circuit

The source driver circuit is consisted of 2400-channels source driver (S1 ~ S2400). The RGB Data from MIPI interface are latched when a single line data has been accumulated. The latched data generates the liquid crystal drive voltage from the source based on the grayscale settings in gamma correction function.

3.1.10. Gate driver circuit

The gate driver circuit outputs gate driver signals at either VGHO or VGLO level while LCD driving.

3.1.11. SX driver circuit

Supply VCOM level when LCD driving. Generates TP sensing pulse when TP driving.

3.1.12. Oscillator (OSC)

FT7150 also features an internal oscillator to generate RC oscillation with an internal resistor.

3.1.13. Grayscale voltage generating circuit

FT7150 has true 8-bit resolution D/A converter, which generates 256 Gamma-corrected values and cooperates with OP-AMP structure to enhance display quality. The grayscale voltage can be adjusted by grayscale data set in the γ -correction register and RGB can be adjusted separately.

3.1.14. LCD driving power supply circuit

The LCD driving power supply circuit generates the voltage levels AVDD, AVEE, VGH, VGL and VCOM for driving an LCD. All these voltages can be adjusted by register setting.

4. PIN DESCRIPTIONS

4.1. Pin Definition

Signal	I/O	PAD Type (Voltage Level)	Function
Power Supply Pad			
AVDD	I	Analog Power	4.5V~6.5V Connect a capacitor for stabilization
AVEE	I	Analog Power	-4.5V~-6.5V Connect a capacitor for stabilization
AVDDR	I	Analog Power	4.5V~6.5V for MV regulator FPC Connect together with AVDD
AVEER	I	Analog Power	-4.5V~-6.5V for MV regulator FPC Connect together with AVEE
VDDI	I	Analog Power	Power Supply for IO, 1.65V~1.95V(MIPI application) / 2.7V~3.6V(LVDS application) Connect a capacitor for stabilization
VDDAM	I	Analog Power	Power Supply for MIPI LDO, 1.65V~1.95V(MIPI application) / 2.7V~3.6V(LVDS application) FPC Connect together with VDDI
AVSS	I	Analog Ground	Ground for Analog Circuits.
VSS	I	Digital Ground	Ground for Digital Circuits.
LVDSVSS	I	Digital Ground	Ground for MIPI Circuits.
AVSSR	I	Analog Ground	Ground for MV Regulator.
DC-DC Converter Pad			
VGH_L VGH_R	O	Internal Power	Positive Charge Pump Power. FPC Connect together. Connect a capacitor for stabilization between VGH_L/VGH_R and VGHB.
VGHB	O	Internal Power	Connect a capacitor for stabilization between VGH_L/VGH_R and VGHB.
VGL	O	Internal Power	Negative Charge Pump Power. Connect a capacitor for stabilization.
C21P/C21N C22P/C22N	I/O	Step-up capacitor	Flying cap for VGH Charge Pump. Connected to a capacitor as requirement.
C31P/C31N	I/O	Step-up capacitor	Flying cap for VGL Charge Pump. Connected to a capacitor as requirement.
Regulator Pad			
VGHO_L VGHO_R	O	Internal Power	Switch output voltage for GIP circuit. FPC Connect together. Connect a capacitor for stabilization between VGHO and VGHO1B.
VGHO1B	O	Internal Power	Connect a capacitor for stabilization between VGHO and VGHO1B.
VGH1_L/R VGH2_L/R	O	Power Input	This pin is used to discharge function. FPC Connect together. If not used, please let these pins short to VGHO
VGLO_L VGLO_R	O	Internal Power	Regulator output voltage generated from VGL. FPC Connect together. Connect a capacitor for stabilization between VGLO and VGLO1B.
VGLO1B	O	Internal Power	Connect a capacitor for stabilization between VGLO and VGLO1B.
VCL	O	Internal Power	Regulator output voltage. Connect a capacitor for stabilization.
VDD	O	Internal Power	Regulator output voltage, Connect a capacitor for stabilization.
LVDSVDD	O	Internal Power	Regulator output voltage,

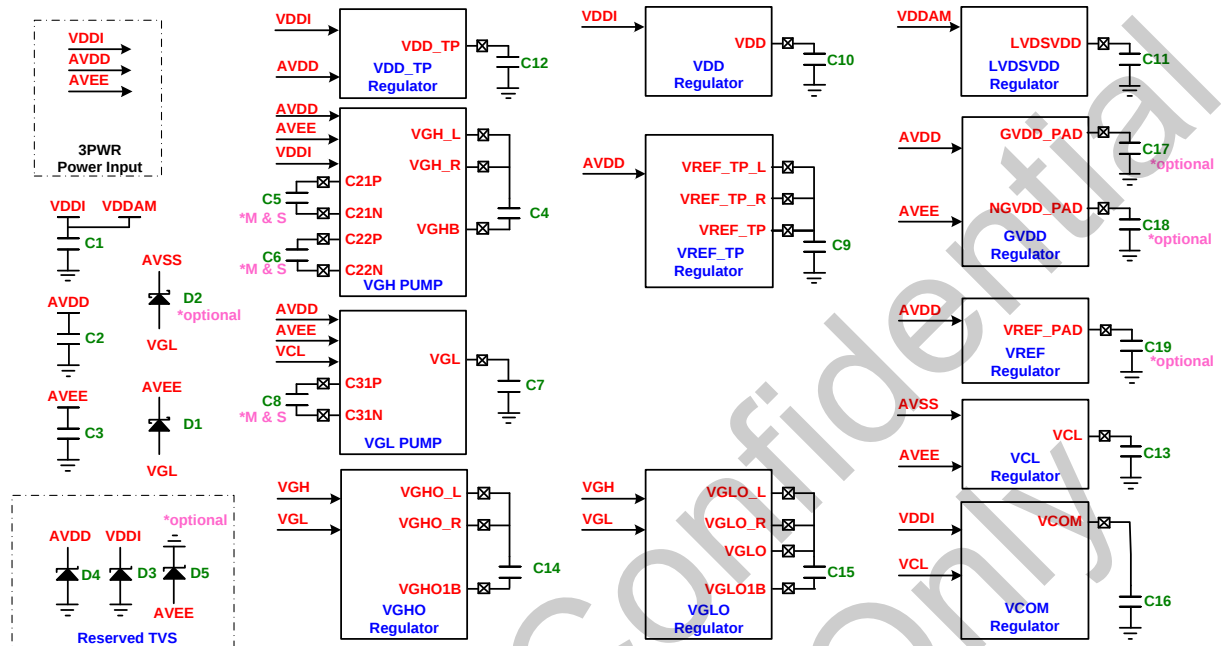
Signal	I/O	PAD Type (Voltage Level)	Function																																																																																																																																																																																																																
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VDD_TP	O	Internal Power	Regulator output voltage, Connect a capacitor for stabilization.																																																																																																																																																																																																																
VREF_TP VREF_TP_L VREF_TP_R	O	Internal Power	Regulator output voltage. FPC Connect together Connect a capacitor for stabilization.																																																																																																																																																																																																																
VDD5_L VDD5_R	O	Internal Power	Regulator output voltage. FPC Connect together Connect a capacitor for stabilization.																																																																																																																																																																																																																
VCOM	O	Internal Power	Regulator output voltage. Connect a capacitor for stabilization. Capacitor must be in the middle of FPC.																																																																																																																																																																																																																
VCOM_FB	I	Internal Power	Feedback for VCOM circuit																																																																																																																																																																																																																
LCD Interface Logic Pad																																																																																																																																																																																																																			
RESX	I	Digital (VDDI)	Global Reset Signal. Active Low.																																																																																																																																																																																																																
DSWAP[1:0]	I	Digital (VDDI)	when IM=0, please see DPHY swap table MIPI lane swap control. MIPI data lane swap and polarity swap table (4 Data Lane)																																																																																																																																																																																																																
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WHEN IM=1, please see LVDS Lanes swap table note: reg_lvds_dswap_M/S[2] setting by register, please see FT7150 AN “LVDS SET”																																																																																																																																																																																																																			
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PNSWAP	I	Digital (VDDI)	MIPI polarity control. IC Internal pull High.																																																																																																																																																																																																																
IM	I	Digital (VDDI)	Interface selection table 0 : MIPI (D-PHY) 1: LVDSRX IC Internal pull Low.																																																																																																																																																																																																																
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IC Internal pull High.																																																																																																																																																																																																																			

Signal	I/O	PAD Type (Voltage Level)	Function
			When IM =1, this is no function
BIST_EN	I/O	Digital (VDDI)	BIST mode enable, High Active. If not used, leave this pin open. IC Internal pull Low.
LCD_GPIO[2:0]	O	Digital (VDDI)	LCD_GPIO can be set as TE, LEDPWM, ...etc. If not used, leave this pin open. IC Internal pull Low.
LCD_SCL	I/O	Digital (VDDI)	I2C control signal for LCD controller. IC Internal pull High. Leave it open if not used.
LCD_SDA	I/O	Digital (VDDI)	I2C control signal for LCD controller. IC Internal pull High. Leave it open if not used.
FCS	I	Digital (VDDI)	When IM =1, Function control by Hardware / Software selection for Display Interface Pad, else "Software register setting". 0 : Software register setting. 1 : Hardware pin setting. IC Internal pull Low.
PON	I	Digital (VDDI)	When FCS = 1, PON = 0 : Sleep in mode PON = 1 : Sleep out mode When FCS = 0, Software register setting.
DISP	I	Digital (VDDI)	Display On. Display mode setting pin. Active high. When FCS = 1, 0/1 : Black display mode / Normal display mode. When FCS = 0, Software register setting.
RL	I	Digital (VDDI)	Horizontal shift direction selection for source output. When FCS = 1, 0 : Reverse (S1 → S2400) (Bump side down view) 1 : Forward (S2400 → S1) (Bump side down view) When FCS = 0, Software register setting.
MIPI-DSI / LVDS Interface input Signals			
CLKP/N	I	MIPI (LVDSVDD)	MIPI-DSI / LVDS CLOCK differential signal input pins. If not used, Please connect to LVDSVSS.
DATA0P/N	I/O	MIPI (LVDSVDD)	MIPI-DSI / LVDS Data differential signal input pins. (Data lane 0) If not used, Please connect to LVDSVSS.
DATA1P/N	I/O	MIPI (LVDSVDD)	MIPI-DSI / LVDS Data differential signal input pins. (Data lane 1) If not used, Please connect to LVDSVSS.
DATA2P/N	I/O	MIPI (LVDSVDD)	MIPI-DSI / LVDS Data differential signal input pins. (Data lane 2) If not used, Please connect to LVDSVSS.
DATA3P/N	I/O	MIPI (LVDSVDD)	MIPI-DSI / LVDS Data differential signal input pins. (Data lane 3) If not used, Please connect to LVDSVSS.
TP Interface Logic Pad			
TP_EXT_RSTN	I	Digital(VDDI)	TP External reset signal., active LOW. If not used, leave this pin open. IC Internal pull High.
TP_BOOTDEVICE	I/O	Digital(VDDI)	Interface select. "0" : I2C (boot with flash) ; "1" : SPI (boot without flash) If not used, leave this pin open.
TP_AFE_SCAN_MODE	I	Digital(VDDI)	Afe scan mode selection signal, 1 : afe scan mode ; 0 : afe normal mode If not used, leave this pin open. IC Internal pull Low.
TP_HOLD	I/O	Digital(VDDI)	HOLD signal to Flash, active LOW. If not used, leave this pin open.
TP_WP	I/O	Digital(VDDI)	write protect signal to Flash, active LOW. If not used, leave this pin open.

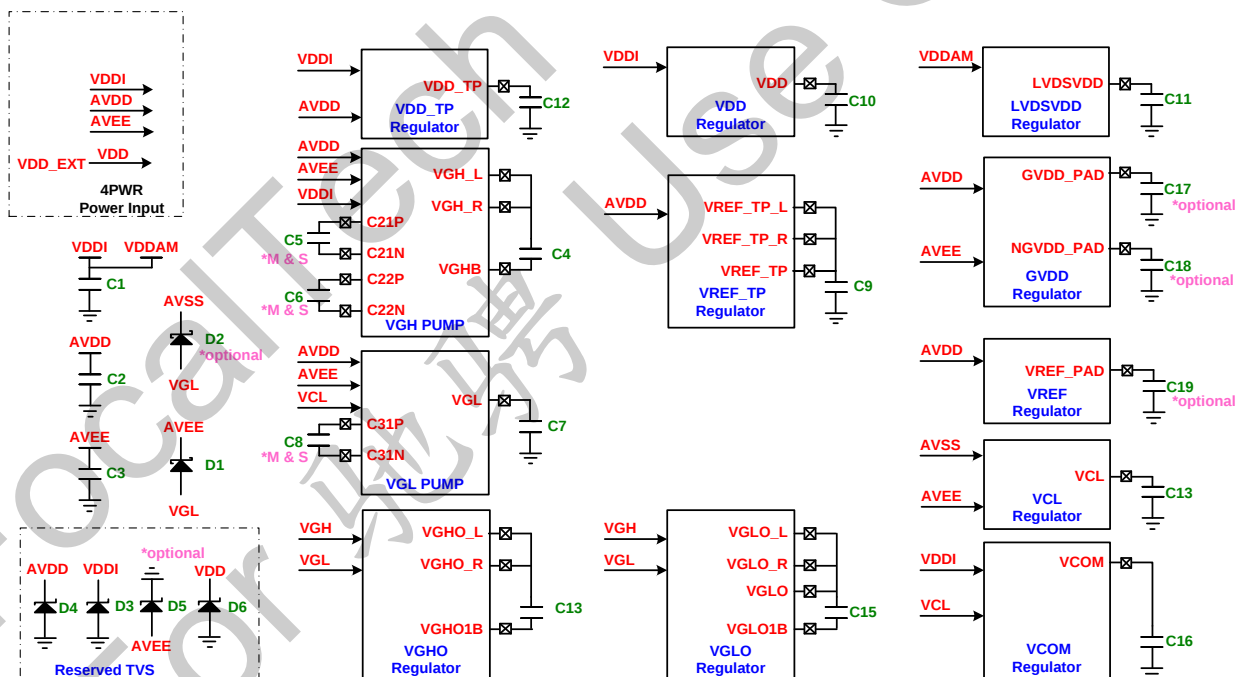
Signal	I/O	PAD Type (Voltage Level)	Function
TP_CS	I/O	Digital(VDDI)	SPI Chip select signal to Flash. If not used, leave this pin open.
TP_SCLK	I/O	Digital(VDDI)	SPI serial clock to Flash. If not used, leave this pin open.
TP_MOSI	I/O	Digital(VDDI)	SPI data output to Flash. If not used, leave this pin open.
TP_MISO	I/O	Digital(VDDI)	SPI data input from Flash. If not used, leave this pin open.
TP_WAKE	I/O	Digital(VDDI)	External wake pin, for Host wake up Touch. If not used, leave this pin open.
TP_SCL	I/O	Digital(VDDI)	I2C interface clock pin for touch. If not used, leave this pin open.
TP_SDA	I/O	Digital(VDDI)	I2C interface data pin for touch. If not used, leave this pin open.
TP_INT	I/O	Digital(VDDI)	External interrupt pin, for Touch interrupt Host. If not used, leave this pin open.
TP_GPIO[1:0]	I/O	Digital(VDDI)	Test pin or I2C master. If not used, leave this pin open.
EMR_GPIO[2:0]	I/O	Digital(VDDI)	Test pin for TP performance.
Test Pad			
VREF_PAD	O	Internal Power	Regulator output voltage, (for LCD internal reference voltage) Connect a capacitor for stabilization (option).
GVDD_PAD	O	Internal Power	Regulator output voltage (for positive gamma voltage generator). Connect a capacitor for stabilization (option).
NGVDD_PAD	O	Internal Power	Regulator output voltage (for negative gamma voltage generator). Connect a capacitor for stabilization (option).
DCHG1	O	Analog Output	For gate signal(Group1:GOUT[4:1], GOUT[22:17]) slope control usage. If user wants to use, please connect a resistor. If not used, please tie it to open.
DCHG2	O	Analog Output	For gate signal(Group2: GOUT[16:5]) slope control usage. If user wants to use, please connect a resistor. If not used, please tie it to open.
EXT_LV	I	Digital(VDDI)	Test pin for the function of external VDD(1.2V) power supply. “H” : 1.2V is generated from external power “L” : 1.2V is generated from internal regulator If not used, leave this pin open. IC Internal pull Low.
LCD_EXT_OSC	I	Digital(VDDI)	LCD test mode, external clock input. If not used, leave this pin open.
TEST[14:0]	I/O	Digital(VDDI)	LCD test pin. If not used, leave this pin open. IC Internal pull Low.
POR12_T	O	Digital(VDDI)	TP POR PAD, for test only. If not used, leave this pin open.
POR18_T	O	Digital(VDDI)	TP POR PAD, for test only. If not used, leave this pin open.
AFE_TEST_L[1:0]	O	Analog (AVDD)	TP analog test pin, not accessible to user. If not used, leave this pin open.
AFE_TEST_R[1:0]	O	Analog (AVDD)	TP analog test pin, not accessible to user. If not used, leave this pin open.
S[2400:1]	O	Analog (AVDD)	Source Output
SDUM[3:0]	O	Analog (AVDD)	Source Dummy Pin (For ZigZag Panel)
RX[800:1]	O	Analog (AVDD)	Analog touch signal pins to touch panel. (TP Sensor Pins)
SXDUM1 SXDUM2	O	Analog (AVDD)	TP Dummy Pin
VCOM_OPT0	O	Internal Power	For panel outline ring use
VCOM_OPT1	O	Internal Power	For panel outline ring use
GOUT_L[22:1] GOUT_R[22:1]	O	Analog (VGHO/ VGLO)	GOA Output. Please use GOUT[13:6] for CLK application.
Dummy Pad			
VCOM_PASS_L VCOM_PASS_R	--	--	Pass line for VCOM from ILB to OLB
TEST[16:15]	--	--	Dummy pin. Must be left open.
DUMMY_OL	--	--	Dummy pin. Must be left open.
DUMMY_OR	--	--	Dummy pin. Must be left open.
DUMMYB	--	--	Dummy pin. Must be left open.

Signal	I/O	PAD Type (Voltage Level)	Function
DUMMYPHYCK	--	--	leave it floating
DUMMYPHY0	--	--	leave it floating
DUMMYPHY1	--	--	leave it floating
DUMMYPHY2	--	--	leave it floating
DUMMYPHY3	--	--	leave it floating
Cascade Pad			
TP_MS	I	Digital(VDDI)	Master / Slave Select pin. (Internal pull high) 1 : Cascade Master IC or single chip 0 : Cascade Slave IC. IC Internal pull High.
EN_EXT_VCOM	I	Digital(VDDI)	Enable external VCOM. (Internal pull low) 1 : VCOM power form external power IC. 0 : VCOM generated by internal VCOM buffer. IC Internal pull Low.
ENB_CASCADE	I	Digital(VDDI)	Cascade enable. (Internal pull high) 0 : Single chip. 1 : Dual chip IC Internal pull High.
SYNC_CTRL_L[7:0] SYNC_CTRL_R[7:0]	I/O	Digital(VDDI)	LCD cascade signals for synchronization control
SYNC_DAT_L[7:0] SYNC_DAT_R[7:0]	I/O	Digital(VDDI)	LCD cascade signals for display data
TP_CASCADE_L[14:0] TP_CASCADE_R[14:0]	I/O	Digital(VDDI)	TP cascade signals for synchronization control and TP raw data
SYNC_GAM_L[5:0] SYNC_GAM_R[5:0]	I/O	Analog	LCD gamma cascade signals. If not used, leave this pin open.

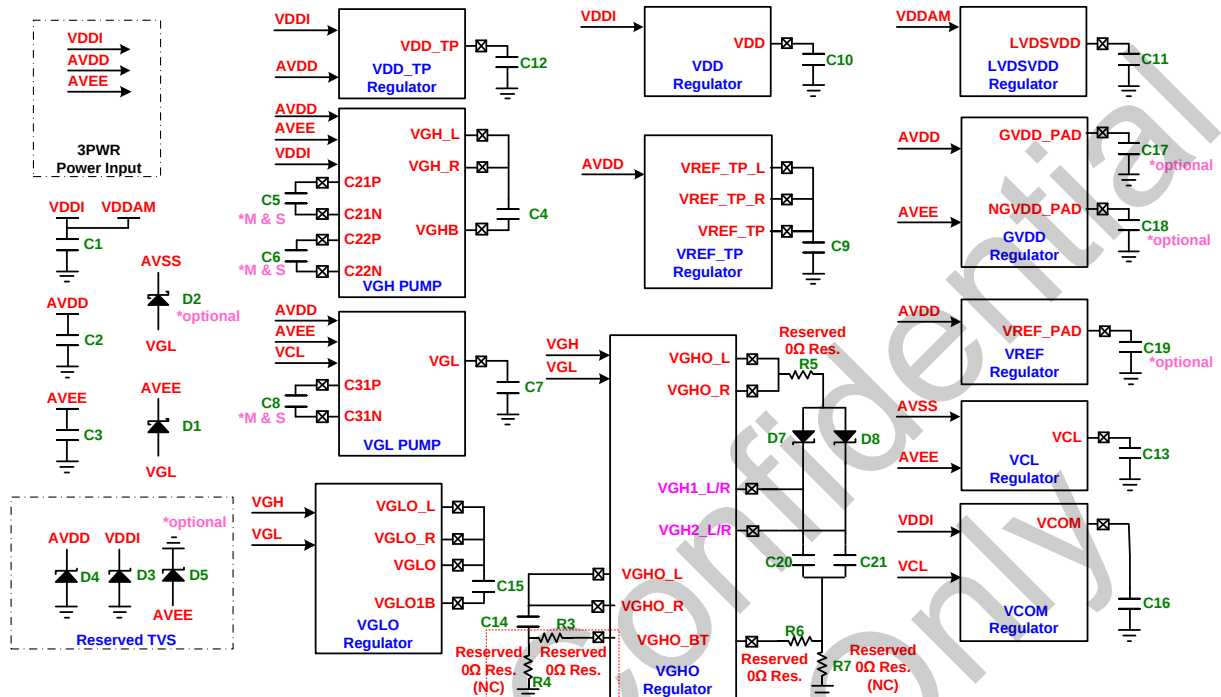
4.2. Power Block Diagram



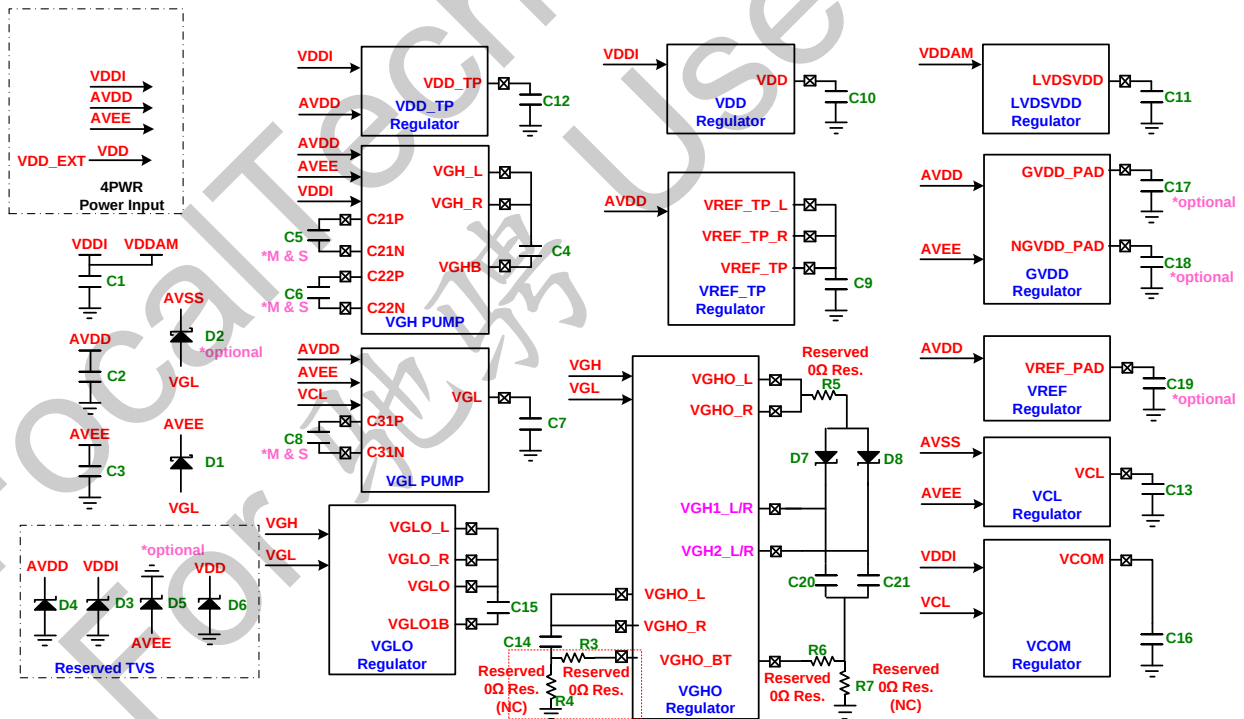
FT7150 Non IGZO



FT7150 Non IGZO

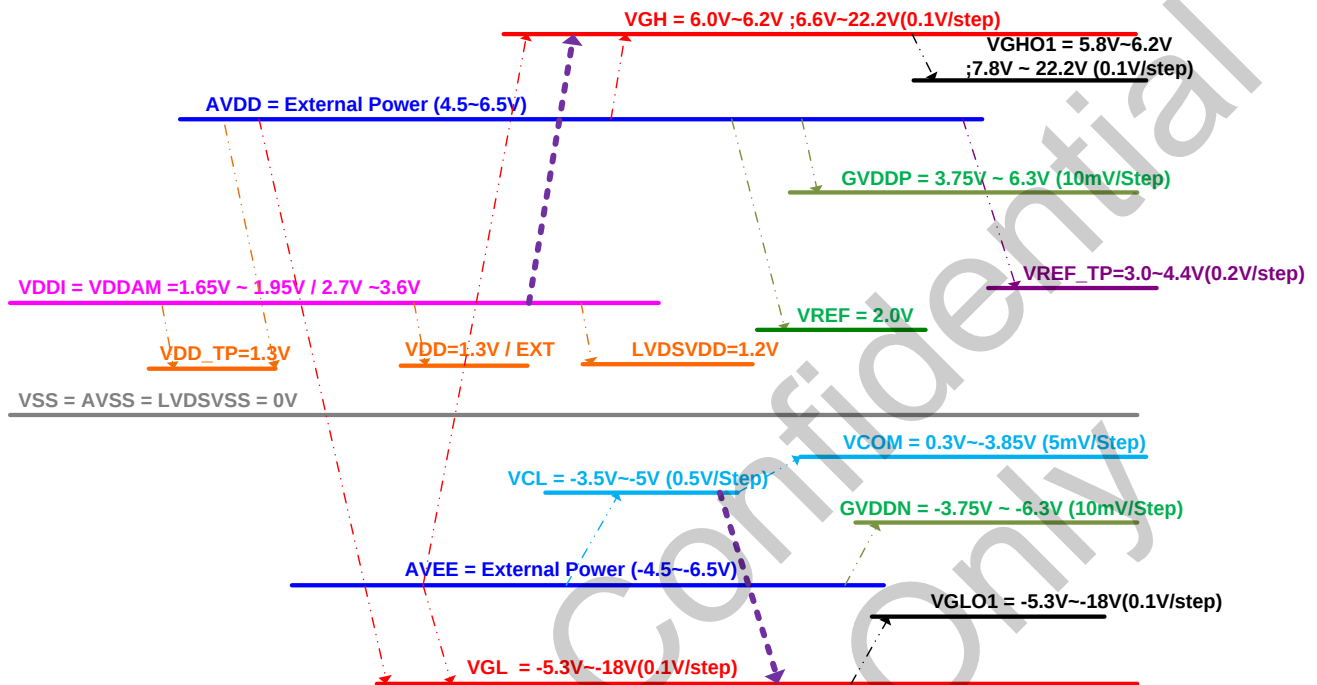


FT7150 IGZO



FT7150 IGZO

4.3. Power Supply Configuration

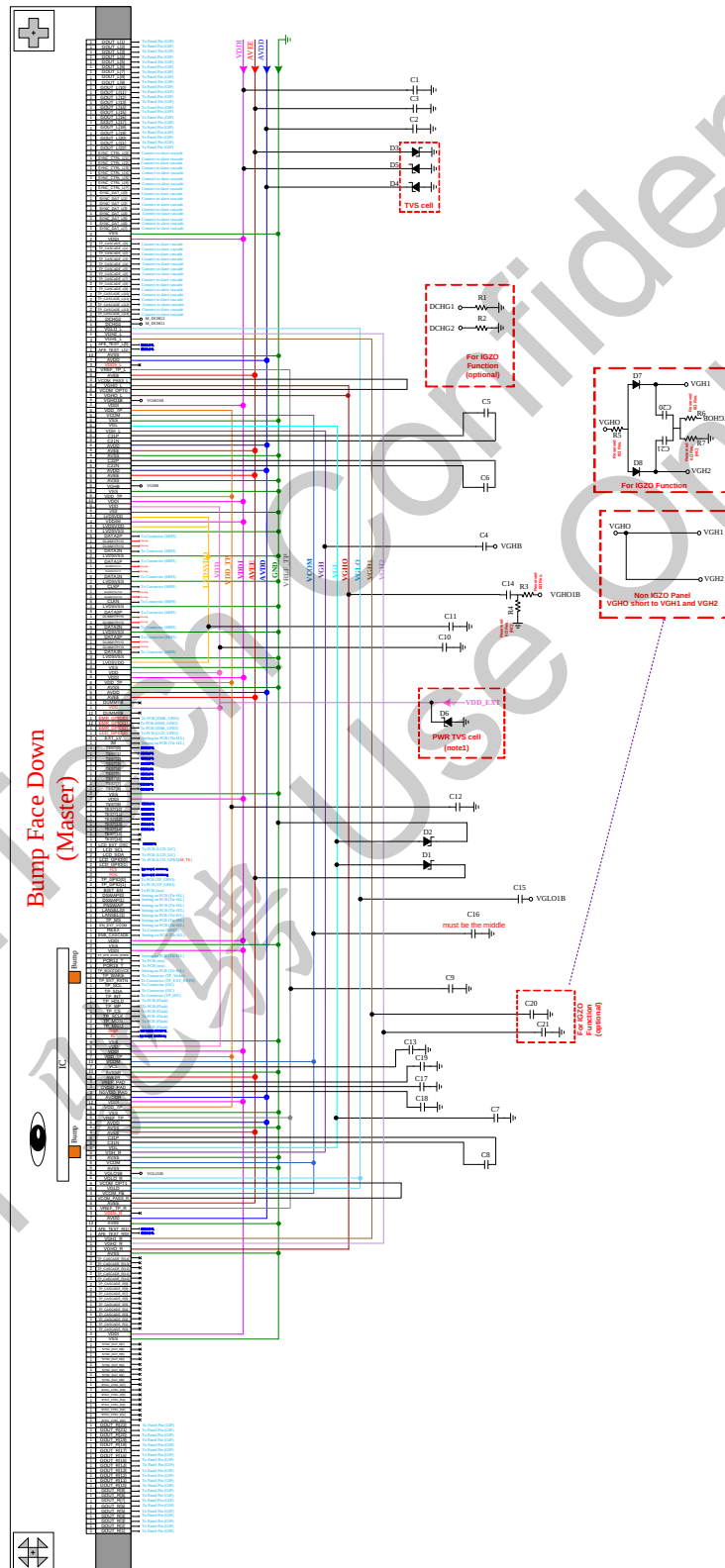


4.4.Application Circuit

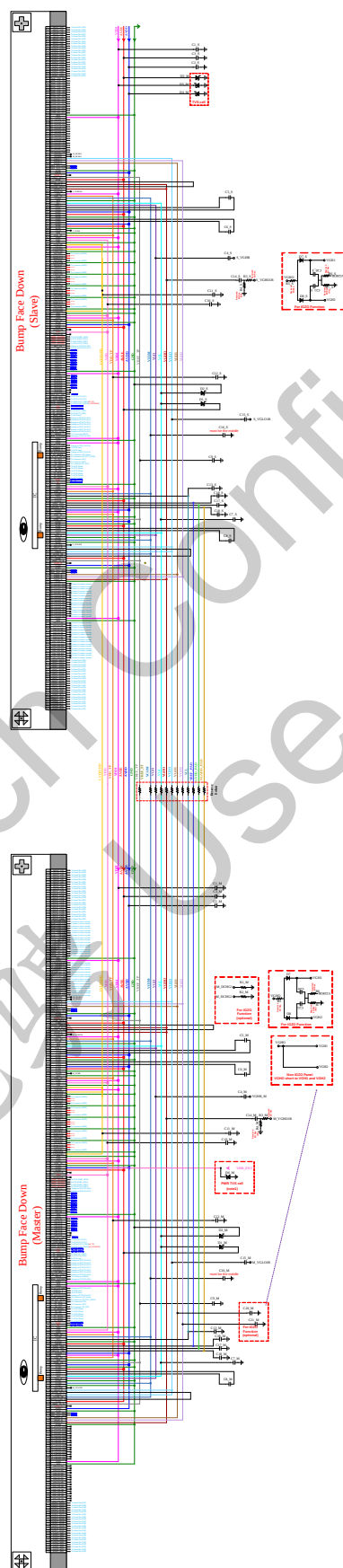
Note1 for 4-Power mode, VDD_EXT connect TVS.

Note2 It's for design reference only! User should contact our sales or FAE for suitable circuit design in actual case.

Single Chip



Dual Chip



4.5. BOM List

Please refer to application note.

4.6. Flash Select

Please refer to application note.

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5. INSTRUCTION

5.1. Outline

The FT7150 supports high speed serial interface, MIPI, to configure system via accessing command register. When the command register is executed, sending the command information to specify which index register would be accessed and following the data to that control register. The MIPI interface is compliant with MIPI Alliance Standard for Display Serial Interface (DSI-2), Version 1.00, D-PHY Version 1.1, Display Command Set (DCS), Version 1.3.

The FT7150 has the following major categories of instructions:

- (1). System function instructions (User Command Set).
- (2). Customer Command List and Description (Manufacturer Command Set / Command 2).

These instructions are asynchronous to the FT7150 internal clock, requiring no wait cycles. Because the writing of instruction data does not interfere with the host controller processing, instructions can be handles smoothly and efficiently. The following describes details of instruction settings.

5.1.1. System function command list and description

After the H/W reset by RESX pin or S/W reset by SWRESET command, each internal register becomes default state (Refer “RESET TABLE” section). Commands 28h and 29h are updated during V-Blanking to avoid abnormal visual effects. By the way, all commands in master and slave side can be updated concurrently during V-Blanking via MIPI DSI v1.2 FSC function.

System function command access flow is described as following example.

Example 1: Sleep Out

Address 0x11

Example 2: Display On

Address 0x29

Example 3: Bypass Mode

Address 0x09

DATWR 0x01

System Function Command List

Command	(Hex)	Write/Read /Command	Function	Parameter Number	MIPI Transmission
SWRESET	01	W	Software Reset.	0	LPDT/HSDT
BISTEN	02	WR	BIST Mode Enable. 0x5A : Enable ; Others : Disable	1	LPDT/HSDT
DSCEN	03	R	Read VESA DSC Status. 0x00: VDSC Disabled; 0x01: VDSC Enabled	1	LPDT/HSDT
DSTB0	04	WR	Deep Standby Mode Enable 0. {DSTB0, DSTB1} = 0x5A5A Enter Deep Standby mode ; others no action.	1	LPDT/HSDT
DSTB1	05	WR	Deep Standby Mode Enable 1. {DSTB0, DSTB1} = 0x5A5A Enter Deep Standby mode ; others no action.	1	LPDT/HSDT
LONGH_ENB	09	WR	Long-H Mode Disable. 1 : Long-V Mode only ; 0 : Long-H Mode	1	LPDT/HSDT
SLPIN	10	C	Sleep in	0	LPDT/HSDT
SLPOUT	11	C	Sleep out	0	LPDT/HSDT
MA_TERM_R_EN	14	WR	Master MIPI Termination Resistor Enable. 0x5A : Disable Master termination. 0x5A : Force Master Termination. Others : Follow MIPI state	1	LPDT/HSDT
SL_TERM_R_EN	15	WR	Master MIPI Termination Resistor Enable. 0x5A : Disable Master termination. 0x5A : Force Master Termination. Others : Follow MIPI state	1	LPDT/HSDT
DISPOFF	28	C	Display off	0	LPDT/HSDT
DISPON	29	C	Display on	0	LPDT/HSDT
OTP_STOP_REL_OAD	41 4E	WR	Both [41]/[4E] not equal to 0x5A, OTP perform self-reload periodically. [41] = 0x5A or [4E] = 0x5A, data bus is controlled by external interface and stop OTP reload.	1	LPDT/HSDT
EXT_ADR	42	WR	Extended address of I2C and MIPI. SysAddr = {EXT_ADR[6:0] + OFFSET[6:0]}	1	LPDT/HSDT
CMD_REPLY_EN	43	WR	0xC3 : Only Slave reply I2C/MIPI readout request Others : Only master reply I2C/MIPI readout request	1	LPDT/HSDT
OTP_CTRL_STS	48	WR	OTP Control and status.	1	LPDT/HSDT
DISBV_SET	51h	W	Display Brightness Value Setting	1	LPDT/HSDT
DISBV_RD	52h	W/R	Read Display Brightness Value	1	LPDT/HSDT
DISBV_CTRL	53h	W/R	Display Brightness Value Control	1	LPDT/HSDT
RDDISBV_CTRL	54h	R	Read Display Brightness Value Control	1	LPDT/HSDT
WRFCC_CABC	55h	W	Write Content Adaptive Brightness Control	1	LPDT/HSDT
RDFCC_CABC	56h	R	Read Content Adaptive Brightness Control	1	LPDT/HSDT
OTP_PROG	58h	W/R	OTP Program	1	LPDT/HSDT

Note: LPDT (Low Power Mode), HSDT (High Speed Mode)

Note: At MIPI direct mode, no matter MASTER IC or SLAVE IC, cmd need writing by each MIPI bus. Master can't pass cmd to Slave.

5.2. System Function Command Description

5.2.1. SWRESET (01h): Software Reset

Bank -									
Parameter Address	D7	D6	D5	D4	D3	D2	D1	D0	Default
01H (SWRST)	No Parameter								-

Description
SWRST : Software Reset Address = '01H' - When the Software Reset command is written, it causes a software reset to display circuit only. - It resets the commands and parameters to their reset default values and all source & gate outputs are set to VSS (display off). (See default tables in each command description) Restriction and notes : - It will be necessary to wait 100msec before sending new command following software reset. - The display module loads all display supplier's factory default values to the registers during 100msec. - Software Reset command cannot work during Deep Standby State.

5.2.2. BIST_MODE (02H): Enter BIST mode

Bank -									
Parameter Address	D7	D6	D5	D4	D3	D2	D1	D0	Default
02H	bist_en[7:0]								A5h

Description
bist_en[7:0] : - This command is used to set BIST Mode function '5Ah' = Enter BIST Mode. 'Others' = Exit BIST Mode. Restriction and notes : - Both register software setting and I/O hardware pin can enter BIST Mode function. (Control ORed) - In CASCADE/Direct Mode application, this command should send to Master side that dominates state of both sides.

5.2.3. DSCEN (03H): VESA DSC Enable

Bank-									
Parameter Address	D7	D6	D5	D4	D3	D2	D1	D0	Default
03H	Reserved							VDSC_EN	00h

Description
VDSC_EN : - This command is used to set VESA DSC Mode function '1' = Enable VESA DSC. '0' = Disable VESA DSC. Restriction and notes : -

5.2.4. DEEP_STBY (04H/05H): Enter Deep Standby Mode

Bank-									
Parameter Address	D7	D6	D5	D4	D3	D2	D1	D0	Default
04H	DEEP_STBY0[7:0]								00h
05H	DEEP_STBY1[7:0]								00h

Description
- These two command are used to set Deep Standby Mode function. - There are 2 methods that can enter Deep Standby State : Method 1 : Set DEEP_STBY0[7:0] = 5Ah and DEEP_STBY1[7:0] = 5Ah in any state. Method 2 : Set DEEP_STBY0[7:0] = A5h and DEEP_STBY1[7:0] = A5h when Sleep In Mode. Restriction and notes : - In CASCADE/Direct Mode application, these commands should send to Master side that dominates state of both sides. - Only Hardware Reset can exit Deep Standby Mode, and it will be necessary to wait 100msec before sending new command following hardware reset. - The display module loads all display supplier's factory default values to the registers during 100msec.

5.2.5. LONGH_MODE (09H): Long-H mode disable

Bank-									
Parameter Address	D7	D6	D5	D4	D3	D2	D1	D0	Default
09H	Reserved							longH_enb	00h

Description
LONGH_ENB : - This command is used to disable/enable Long-H Mode function. '1' = Long-H Mode disable.. '0' = Long-H Mode enable.(Default) Restriction : - In CASCADE application, this command should send to Master side that dominates state of both sides.

5.2.6. SLPIN (10H) & SLPOUT (11H) : Sleep-In & Sleep-Out

Bank-									
Parameter Address	D7	D6	D5	D4	D3	D2	D1	D0	Default
10H (SLPIN)	No Parameter								-
11H (SLPOUT)	No Parameter								-

Description	
SLPIN : Sleep-In (Enter Standby Mode) Address = '10H' - This command causes the LCD module to enter the power consumption reduced mode. - In this mode, internal display oscillator is stopped, and panel scanning is stopped. - Only the command path are still working to support the exit from Standby Mode.	
Sleep In	
Restriction : - This command has no effect when module is already in sleep in mode. Standby Mode can only be exit by the SLPOUT Command (11H).	
SLPOUT : Sleep-Out (Exit Standby Mode) Address = '11H' - This command causes the LCD module to exit the power consumption reduced mode. - In this mode, internal display oscillator is started, and panel scanning is started.	
Sleep Out	
Restriction : - This command has no effect when module is already in sleep out mode. - Sleep Out Mode can only be exit by the SLPIN Command (10H).	

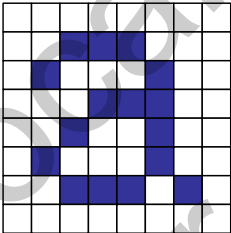
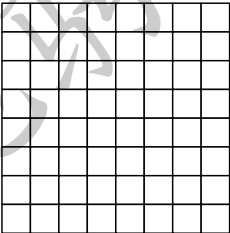
5.2.7. TERM_R_EN (14H~15H): MIPI TermR Enable

Bank-									
Parameter Address	D7	D6	D5	D4	D3	D2	D1	D0	Default
14H	MA_TERM_R_EN[7:0]								FFh
15H	SL_TERM_R_EN[7:0]								FFh

Description
MA_TERM_R_EN[7:0] : Master Side MIPI TermR Enable - This command is used to set Master side MIPI TermR enable, disable or normal operation. '5Ah' = Force to enable MIPI TermR 'A5h' = Force to disable MIPI TermR 'Others' = Normal operation that depends on MIPI High Speed Mode SL_TERM_R_EN[7:0] : Slave Side MIPI TermR Enable - This command is used to set Slave2 side MIPI TermR enable, disable or normal operation. '5Ah' = Force to enable MIPI TermR 'A5h' = Force to disable MIPI TermR 'Others' = Normal operation that depends on MIPI High Speed Mode

5.2.8. DISPLAY_CTRL (28H~29H) : Display Control

Bank-									
Parameter Address	D7	D6	D5	D4	D3	D2	D1	D0	Default
28H (DISPOFF)	No Parameter								-
29H (DISPON)	No Parameter								-

Description
DISPOFF : Display Off Address = '28H' - This command is used to enter into DISPLAY OFF mode. In this mode, the output from the Memory is disabled and blank page is inserted. - This command does not change any other status. - There will be no abnormal visible effect on the display. - Exit from this command by Display On (29H) (Example) Memory  → Display 
Restriction : - This command has no effect when module is already in Display Off mode.
DISPON : Display On Address = '29H' - This command is used to recover from DISPLAY OFF mode. Output from the Memory is enabled. - This command does not change any other status.

(Example)

Memory

→

Display

Restriction :

- This command has no effect when module is already in Display On mode.

5.2.9. OTP_STOP_RELOAD (41H/4EH): OTP Stop Reload Enable

Bank-									
Parameter Address	D7	D6	D5	D4	D3	D2	D1	D0	Default
41H	OTP_STOP_RELOAD[7:0]								00h
4EH	OTP_STOP_RELOAD[7:0]								00h

Description
OTP_STOP_RELOAD : OTP Stop Reload Enable - This command is used to enable OTP stop reload function 'REG41=5Ah or REG4E=5Ah' : Stop OTP reload and switch bus to external interface. 'Others' : Enable OTP reload and switch bus to reload controller.

5.2.10. EXT_ADR (42H): Extended Address of Command Interface

Bank-									
Parameter Address	D7	D6	D5	D4	D3	D2	D1	D0	Default
42H		Bank_Sel[6:0]							2Fh

Description
Bank_Sel[6:0] : Bank Selection of following command groups for I2C, MIPI and SYSTEM interface. - This command is used to set extended address of I2C, MIPI and SYSTEM interface.

5.2.11. CMD_REPLY_EN (43H): Command Reply Enable

Bank-									
Parameter Address	D7	D6	D5	D4	D3	D2	D1	D0	Default
43H	CMD_REPLY_EN[7:0]								00h

Description
CMD_REPLY_EN[7:0] : Command Reply Enable - This command is used to set which side will reply command read data. 'C3h' = Slave side replies read data. 'Others' = Master side replies read data.

5.2.12. OTP_CTRL_STATUS (48H): OTP Control & Status

Bank-									
Parameter Address	D7	D6	D5	D4	D3	D2	D1	D0	Default
48H	Reserved	OTP_LOAD_FINISH	OTP_RELOAD_FINISH	SPI_LOAD_FINISH	Reserved	OTP_OP_MODE[2:0]			00h

Description
OTP_LOAD_FINISH (Read-Only) : OTP Initial Load Finish Flag '1' = OTP initial load finish OTP_RELOAD_FINISH (Read-Only) : OTP Reload Finish Flag '1' = OTP reload finish SPI_LOAD_FINISH (Read-Only) : SPI Flash Load Finish Flag '1' = SPI flash load finish OTP_OP_MODE : OTP Operation Mode '000' = Normal Mode '001' = Initial Margin Read '010' = Program Mode '100' = Program Margin Read

5.2.13. DISBV_SET (51H/52H): Display Brightness Value Setting

Bank-									
Parameter Address	D7	D6	D5	D4	D3	D2	D1	D0	Default
51H	DBV[11:4]								FFh
52H	Reserved				DBV[3:0]				FFh

Description
- This command is used to adjust the brightness value of the display. - It should be checked what is the relationship between this written value and output brightness of the display. This relationship is defined on the display module specification. - In principle relationship is that 000h value means the lowest brightness and FFFh value means the highest brightness.

5.2.14. DISBV_RD (52H/53H): Read Display Brightness Value

Bank-									
Parameter Address	D7	D6	D5	D4	D3	D2	D1	D0	Default
52H	DBV[11:4]								FFh
53H	Reserved				DBV[3:0]				FFh

Description
- This command returns the brightness value of the display. - This command can be used to read the brightness value of the display also when Display brightness control is in automatic mode. - It should be checked what the relationship between this returned value and output brightness of the display. This relationship is defined on the display module specification. - In principle the relationship is that 000h value means the lowest brightness and FFFh value means the highest brightness. - DBV[11:0] is reset when display is in sleep-in mode. - DBV[11:0] is '0' when bit BCTRL of "Display Brightness Value Control (53H)" command is '0'. - DBV[11:0] is manual set brightness specified with "Display Brightness Value Control (53H)" command when bit BCTRL is '1'. - See command "Display Brightness Value Setting (51H)".

5.2.15. DISBV_CTRL (53H): Display Brightness Value Control

Bank-									
Parameter Address	D7	D6	D5	D4	D3	D2	D1	D0	Default
53H	Reserved		BCTRL	Reserved	DD	BL	Reserved		00h

Description
- This command is used to control ambient light, brightness and gamma settings. BCTRL : Brightness Control Block On/Off. This bit is always used to switch brightness for display and keyboard. '0' = Off (Brightness registers are 00h) '1' = On (Brightness registers are active, according to the other parameters.) DD : Display Dimming - Dimming function is adapted to the brightness registers for display and keyboard when bit BCTRL is changed at DD=1, e.g. BCTRL: 0 -> 1 or 1-> 0. '0' = Display Dimming is off '1' = Display Dimming is on BL : Backlight On/Off - When BL bit change from "On" to "Off", backlight is turned off '0' = Off (Completely turn off backlight circuit. Control lines must be low.) '1' = On

5.2.16. RDDISBV_CTRL (54H): Read Display Brightness Value Control

Bank-									
Parameter Address	D7	D6	D5	D4	D3	D2	D1	D0	Default
54H	Reserved		BCTRL	Reserved	DD	BL	Reserved		00h

Description
- This command returns ambient light and brightness control values, see command "Display Brightness Value Control (53H)". BCTRL: Brightness Control Block On/Off. This bit is always used to switch brightness for display. '0' = Off '1' = On ... DD: Display Dimming '0' = Display Dimming is off '1' = Display Dimming is on ... BL: Backlight On/Off, this bit is always controlled by the user '0' = Off (completely turn off backlight circuit) '1' = On

5.2.17. WRFCC_CABC (55H): Write Focal CleverColor – Content Adaptive Brightness Control

Bank-									
Parameter Address	D7	D6	D5	D4	D3	D2	D1	D0	Default
55H	Reserved						CABC_MODE[1:0]		00h

Description																	
- This command is used to set parameters for power functionality. - There is possible to use 3 different modes for content adaptive image functionality, which are defined on a table below. <table border="1"> <thead> <tr> <th>CABC_MODE</th><th>Function</th><th>Note</th></tr> </thead> <tbody> <tr> <td>0h</td><td>Power Save Off</td><td>CABC Off</td></tr> <tr> <td>1h</td><td>Power Save Low</td><td>User Interface Image(UI)</td></tr> <tr> <td>2h</td><td>Power Save Medium</td><td>Still Picture(ST)</td></tr> <tr> <td>3h</td><td>Power Save High</td><td>Moving Image(MV)</td></tr> </tbody> </table> CABC = Content Adaptive Brightness Control			CABC_MODE	Function	Note	0h	Power Save Off	CABC Off	1h	Power Save Low	User Interface Image(UI)	2h	Power Save Medium	Still Picture(ST)	3h	Power Save High	Moving Image(MV)
CABC_MODE	Function	Note															
0h	Power Save Off	CABC Off															
1h	Power Save Low	User Interface Image(UI)															
2h	Power Save Medium	Still Picture(ST)															
3h	Power Save High	Moving Image(MV)															

5.2.18. RDFCC_CABC (56H): Read Focal CleverColor – Content Adaptive Brightness Control

Bank-									
Parameter Address	D7	D6	D5	D4	D3	D2	D1	D0	Default
56H	Reserved						CABC_MODE[1:0]		00h

Description		
- This command returns for power functionality see command “Write Focal CleverColor – Content Adaptive Brightness Control (55H) ”.		

5.2.19. OTP_PROG (58H/5AH/64H/65H/66H/67H) : OTP Program

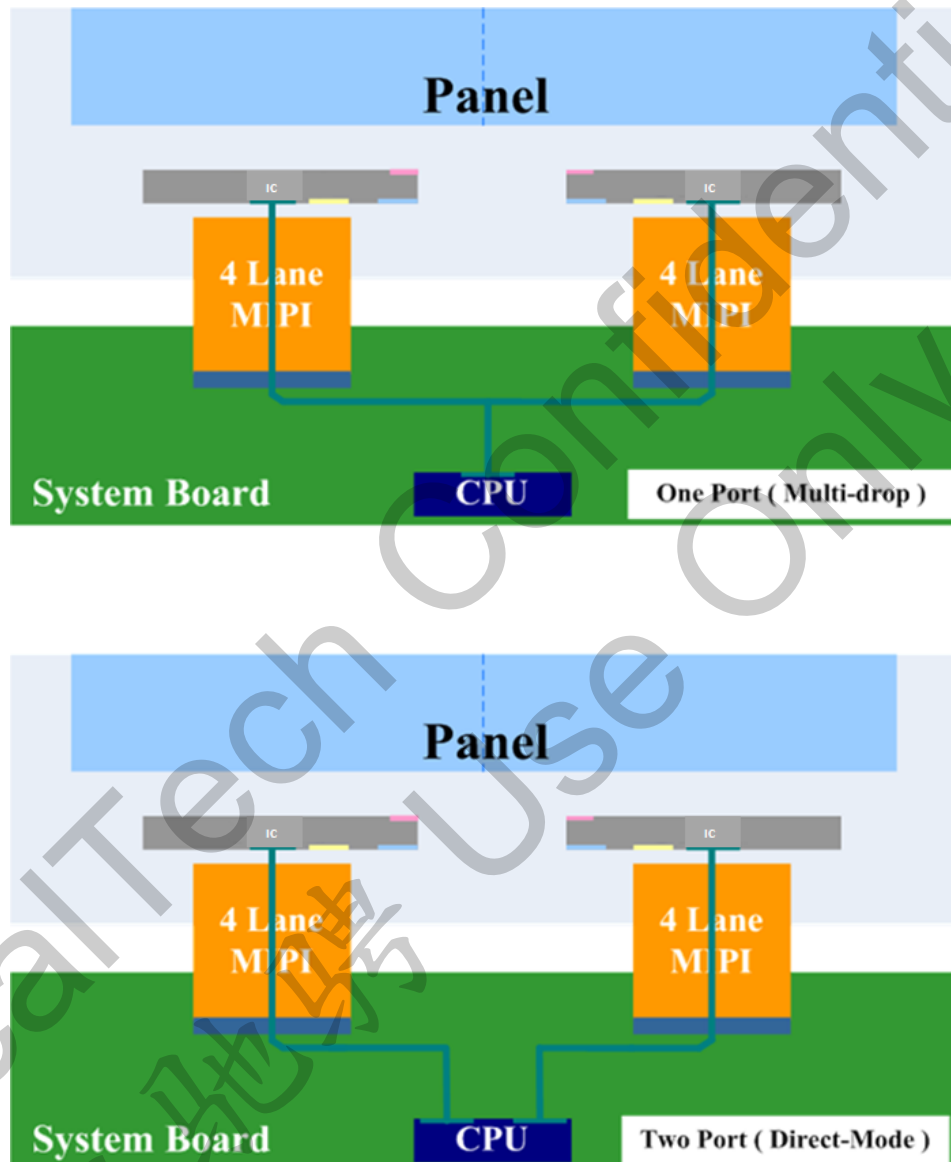
Bank-									
Parameter Address	D7	D6	D5	D4	D3	D2	D1	D0	Default
58H	OTP_PROG_START [7:0]								00h
5AH	OTP_PROG_UNLOCK [7:0]								00h
64H	OTP_PROG_BANK[7:0]								00h
65H	OTP_PROG_BANK[15:8]								00h
66H	OTP_PROG_BANK[23:16]								00h
67H	OTP_PROG_BANK[31:24]								00h

Description		
OTP_PROG_START[7:0] : OTP Bank Programming Start - This command is used to set OTP bank programming start. - When OTP bank programming is done, register value will be set to EDh. ‘AAh’ = Start OTP bank programming. ‘Others’ = Not programming. OTP_PROG_UNLOCK[7:0] : OTP Programming Function Unlock - This command is used to set OTP programming function unlock. ‘96h’ = Unlock OTP programming function. ‘Others’ = Lock OTP programming function. _PROG_BANK[31:0] : OTP Programming Bank Set - This command is used to set OTP programming bank from Register/SRAM into OTP.		

6. FUNCTIONS

6.1. Interface Architecture

FT7150 can support both multi-drop and direct mode architecture for MIPI interface for 2-chip configuration.



6.2. Interface Type Selection

FT7150 support D-PHY MIPI 2/3/4-Lane and lvds interface, depend on IM pad setting.

IM	Interface Selection
0	DPHY MIPI-4Lane
1	LVDS 4 lane

LANSEL[1:0]	Interface Selection
00	Reserved
01	MIPI-2Lane
10	MIPI-3Lane
11	MIPI-4Lane

DPHY	PNSWAP	DSWAP[1:0]	DSI-D2+	DSI-D2-	DSI-D1+	DSI-D1-	DSI-CLK+	DSI-CLK-	DSI-D0+	DSI-D0-	DSI-D3+	DSI-D3-
	0	00	D3-	D3+	D2-	D2+	CLK-	CLK+	D1-	D1+	D0-	D0+
		01	D3-	D3+	D0-	D0+	CLK-	CLK+	D1-	D1+	D2-	D2+
		10	D0-	D0+	D1-	D1+	CLK-	CLK+	D2-	D2+	D3-	D3+
		11	D2-	D2+	D1-	D1+	CLK-	CLK+	D0-	D0+	D3-	D3+
	1	00	D3+	D3-	D2+	D2-	CLK+	CLK-	D1+	D1-	D0+	D0-
		01	D3+	D3-	D0+	D0-	CLK+	CLK-	D1+	D1-	D2+	D2-
		10	D0+	D0-	D1+	D1-	CLK+	CLK-	D2+	D2-	D3+	D3-
		11	D2+	D2-	D1+	D1-	CLK+	CLK-	D0+	D0-	D3+	D3-

LVDS swap table:

LVDS Lanes SWAP table												
SOFT controller	HW controller		PAD Name									
register setting (reg_lvds_dswap_M/S[21])	PSWAP	DSWAP[1:0]	DATA2P	DATA2N	DATA1P	DATA1N	CLKP	CLKN	DATA0P	DATA0N	DATA3P	DATA3N
0	0	00	D3N	D3P	D2N	D2P	CLKN	CLKP	D1N	D1P	D0N	D0P
		01	D3N	D3P	D0N	D0P	CLKN	CLKP	D1N	D1P	D2N	D2P
		10	D0N	D0P	D1N	D1P	CLKN	CLKP	D2N	D2P	D3N	D3P
		11	D2N	D2P	D1N	D1P	CLKN	CLKP	D0N	D0P	D3N	D3P
	1	00	D3P	D3N	D2P	D2N	CLKP	CLKN	D1P	D1N	D0P	D0N
		01	D3P	D3N	D0P	D0N	CLKP	CLKN	D1P	D1N	D2P	D2N
		10	D0P	D0N	D1P	D1N	CLKP	CLKN	D2P	D2N	D3P	D3N
		11	D2P	D2N	D1P	D1N	CLKP	CLKN	D0P	D0N	D3P	D3N
1	0	00	D0N	D0P	D2N	D2P	D1N	D1P	D3N	D3P	CLKN	CLKP
		01	D2N	D2P	D0N	D0P	D1N	D1P	CLKN	CLKP	D3N	D3P
		10	D1N	D1P	D2N	D2P	CLKN	CLKP	D3N	D3P	D0N	D0P
		11	D2N	D2P	D1N	D1P	CLKN	CLKP	D0N	D0P	D3N	D3P
	1	00	D0P	D0N	D2P	D2N	D1P	D1N	D3P	D3N	CLKP	CLKN
		01	D2P	D2N	D0P	D0N	D1P	D1N	CLKP	CLKN	D3P	D3N
		10	D1P	D1N	D2P	D2N	CLKP	CLKN	D3P	D3N	D0P	D0N
		11	D2P	D2N	D1P	D1N	CLKP	CLKN	D0P	D0N	D3P	D3N

6.3.MIPI-DSI Interface (D-option)

6.3.1. General description

The communication can be separated 2 different levels between the MCU and the display module:

- Interface Level : Low level communication
- Packet level : High level communication

6.3.2. Interface level communication

6.3.2.1 General

The display module uses data and clock lane differential pairs for DSI. Both clock lane and data lane0 can be driven Low Power (LP) or High Speed (HS) mode. Data lane1 can be driven High Speed mode only.

-	Lane support mode	MPU(Host)	FT7150(Slave)
Clock Lane	Unidirectional lane • High-Speed Clock only • Simplified Escape Mode (ULPS Only)		
Data Lane0	Bi-directional lane • Forward high-speed only • Bi-directional Escape Mode • Bi-direction LPDT		
Data Lane1	Unidirectional lane • Forward high-speed only • Simplified Escape Mode (ULPS Only)		

Table: Lane types and support mode

Low Power mode means that each line of the differential pair is used in single end mode and a differential receiver is disable (A termination resistor of the receiver is disable) and it can be driven into a low power mode.

High Speed mode means that differential pairs (The termination resistor of the receiver is enable) are not used in the single end mode.

There are used different modes and protocols in each mode when there are wanted to transfer information from the MCU to the display module and vice versa.

The State Codes of the High Speed (HS) and Low Power (LP) lane pair are defined below.

Lane Pair State Code	Line DC Voltage Levels		High Speed (HS)	Low-Power (LP)	
	Dn+ Line	Dn- Line	Burst Mode	Control Mode	Escape Mode
HS-0	Low (HS)	High (HS)	Differential-0	Note 1	Note 1
HS-1	High (HS)	Low (HS)	Differential-1	Note 1	Note 1
LP-00	Low (LP)	Low (LP)	Not Defined	Bridge	Space
LP-01	Low (LP)	High (LP)	Not Defined	HS-Request	Mark-0
LP-10	High (LP)	Low (LP)	Not Defined	LP-Request	Mark-1
LP-11	High (LP)	High (LP)	Not Defined	Stop	Note 2

Table: High Speed and Low-Power Lane Pair State Descriptions

6.3.2.2 DSI-CLK lanes

DSI-CLK+/- lanes can be driven into three different power modes: Low Power Mode (LPM LP-11), Ultra Low Power Mode (ULPM) or High Speed Clock Mode (HSCM).

Clock lanes are in a single end mode (LP = Low Power) when there is entering or leaving Low Power Mode(LPM) or Ultra Low Power Mode (ULPM).

Clock lanes are in the single end mode (LP = Low Power) when there is entering in or leaving out High Speed Clock Mode (HSCM).

These entering and leaving protocols are using clock lanes in the single end mode to generate an entering or leaving sequences.

The principal flow chart of the different clock lanes power modes is illustrated below.

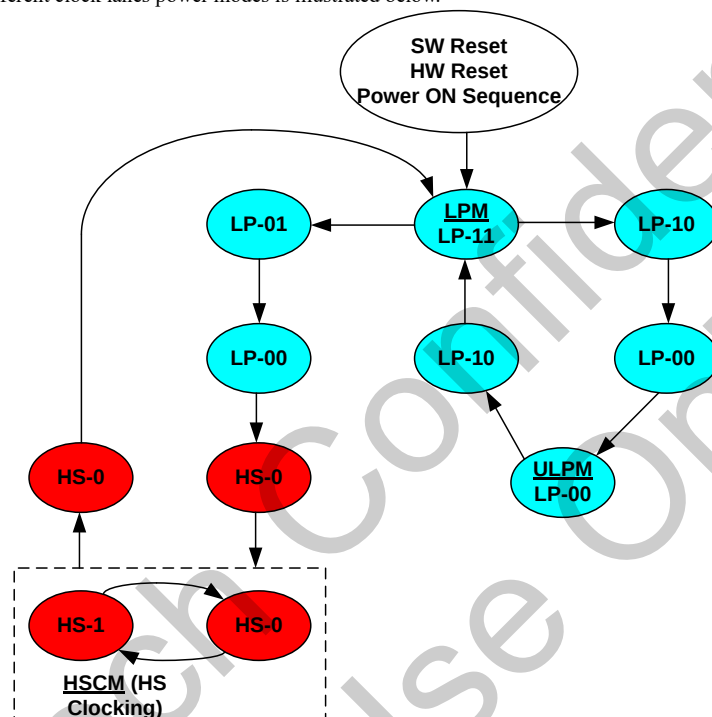


Figure: Clock Lanes Power Modes

Notes:

1. Low-Power Receivers (LP-Rx) of the lane pair are checking the LP-00 state code, when the Lane Pair is in the High Speed (HS) mode.
2. If Low-Power Receivers (LP-Rx) of the lane pair recognizes LP-11 state code, the lane pair returns to LP-11 of the Control Mode.

Low Power Mode (LPM)

DSI-CLK+/- lanes can be driven to the Low Power Mode (LPM), when DSI-CLK lanes are entering LP-11 State Code, in three different ways:

- 1) After SW Reset, HW Reset or Power On Sequence =>LP-11
- 2) After DSI-CLK+/- lanes are leaving Ultra Low Power Mode (ULPM, LP-00 State Code) =>LP-10 =>LP-11 (LPM). This sequence is illustrated below.

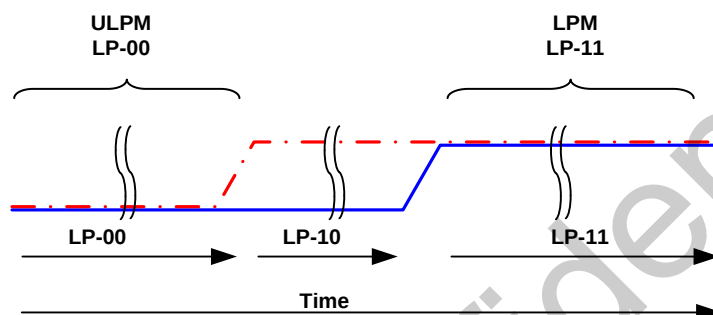


Figure: From ULPM to LPM

- 3) After DSI-CLK+/- lanes are leaving High Speed Clock Mode (HSCM, HS-0 or HS-1 State Code) =>HS-0 =>LP-11 (LPM). This sequence is illustrated below.

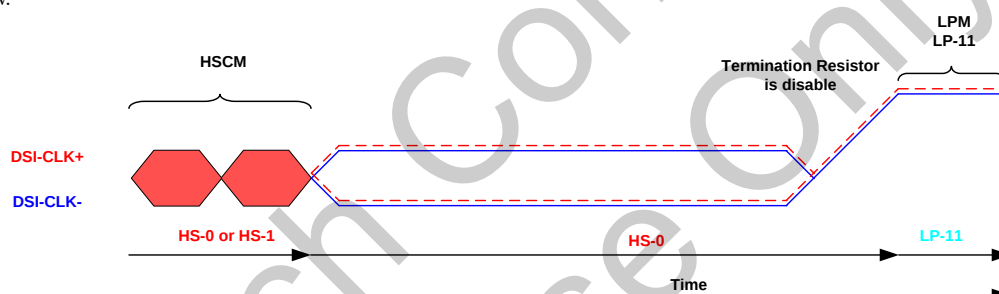


Figure: From HSCM to LPM

All three mode changes are illustrated a flow chart below.

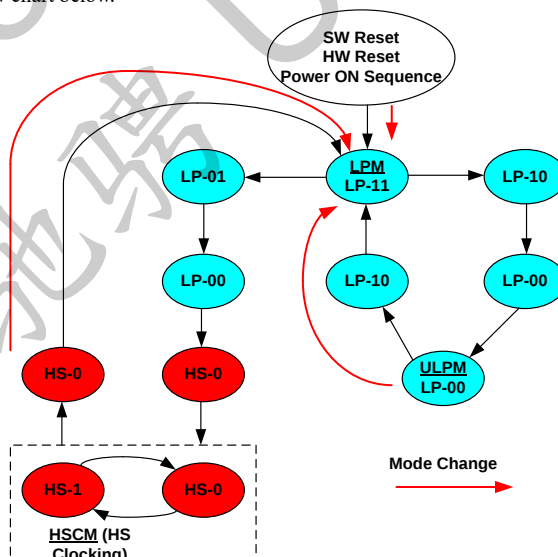


Figure: All three mode changes to LPM

Ultra Low Power Mode (ULPM)

DSI-CLK+/- lanes can be driven to the High Speed Clock Mode (HSCM), when DSI-CLK lanes are starting to work between HS-0 and HS-1 State Codes.

The only entering possibility is from the Low Power Mode (LPM, LP-11 State Code) =>LP-01 =>LP-00 =>HS-0 =>HS-0/1 (HSCM). This sequence is illustrated below.

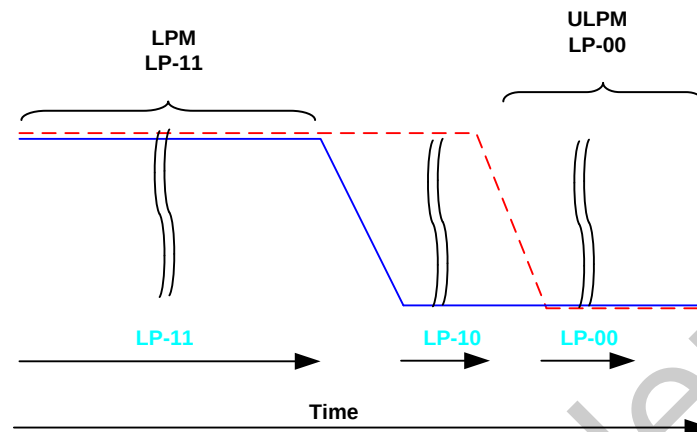


Figure: From LPM to UPLM

The mode change is also illustrated below:

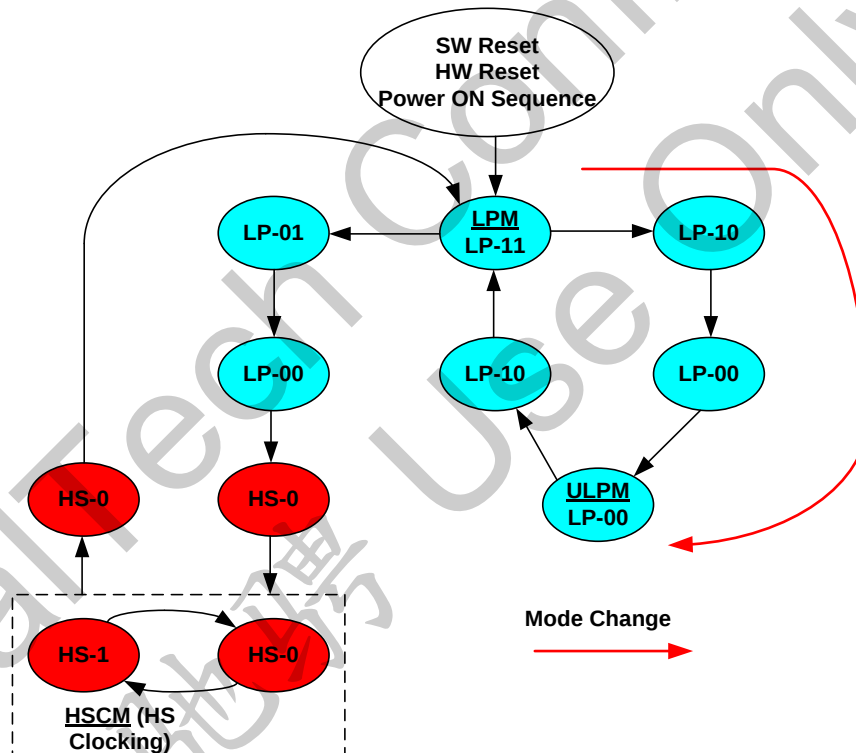


Figure: The mode change from LPM to UPLM

High-speed Clock Mode (HSCM)

DSI-CLK+/- lanes can be driven to the High Speed Clock Mode (HSCM), when DSI-CLK lanes are starting to work between HS-0 and HS-1 State Codes.

The only entering possibility is from the Low Power Mode (LPM, LP-11 State Code) =>LP-01 =>LP-00 =>HS-0 =>HS-0/1 (HSCM). This sequence is illustrated below.

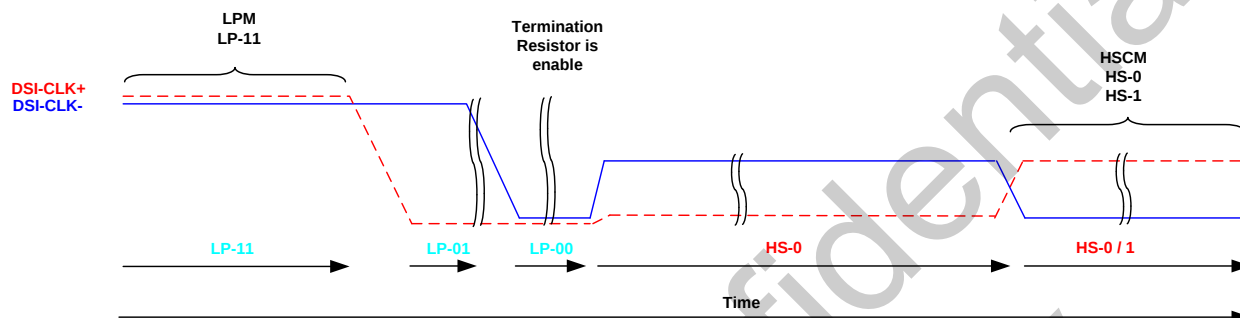


Figure: From LPM to HSCM

The mode change is also illustrated below:

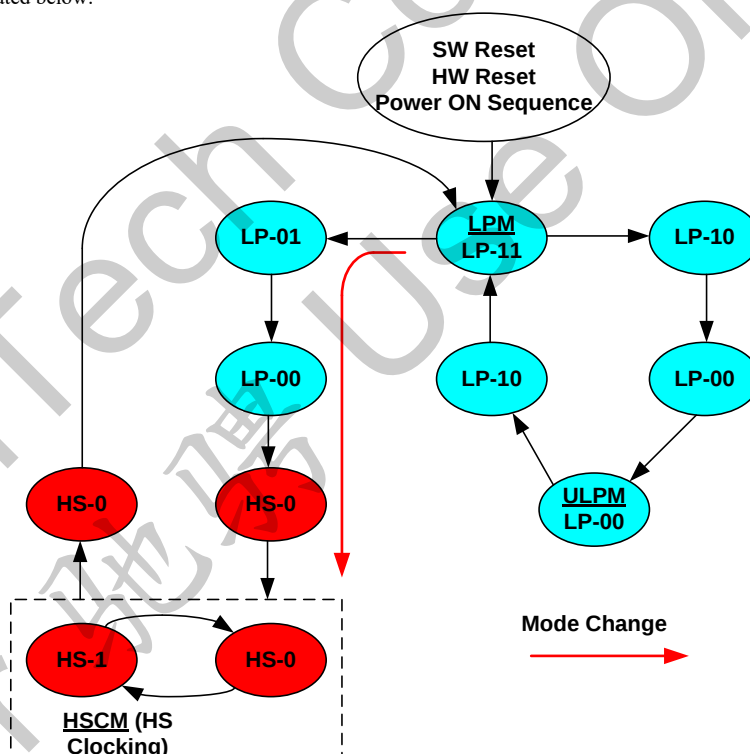


Figure: Mode change from LPM to HSCM

The high speed clock (DSI-CLK+/-) is started before high speed data is sent via DSI-Dn+/- lanes. The high speed clock continues clocking after the high speed data sending has been stopped

The burst of the high speed clock consists of:

- Even number of transitions
- Start state is HS-0
- End state is HS-0

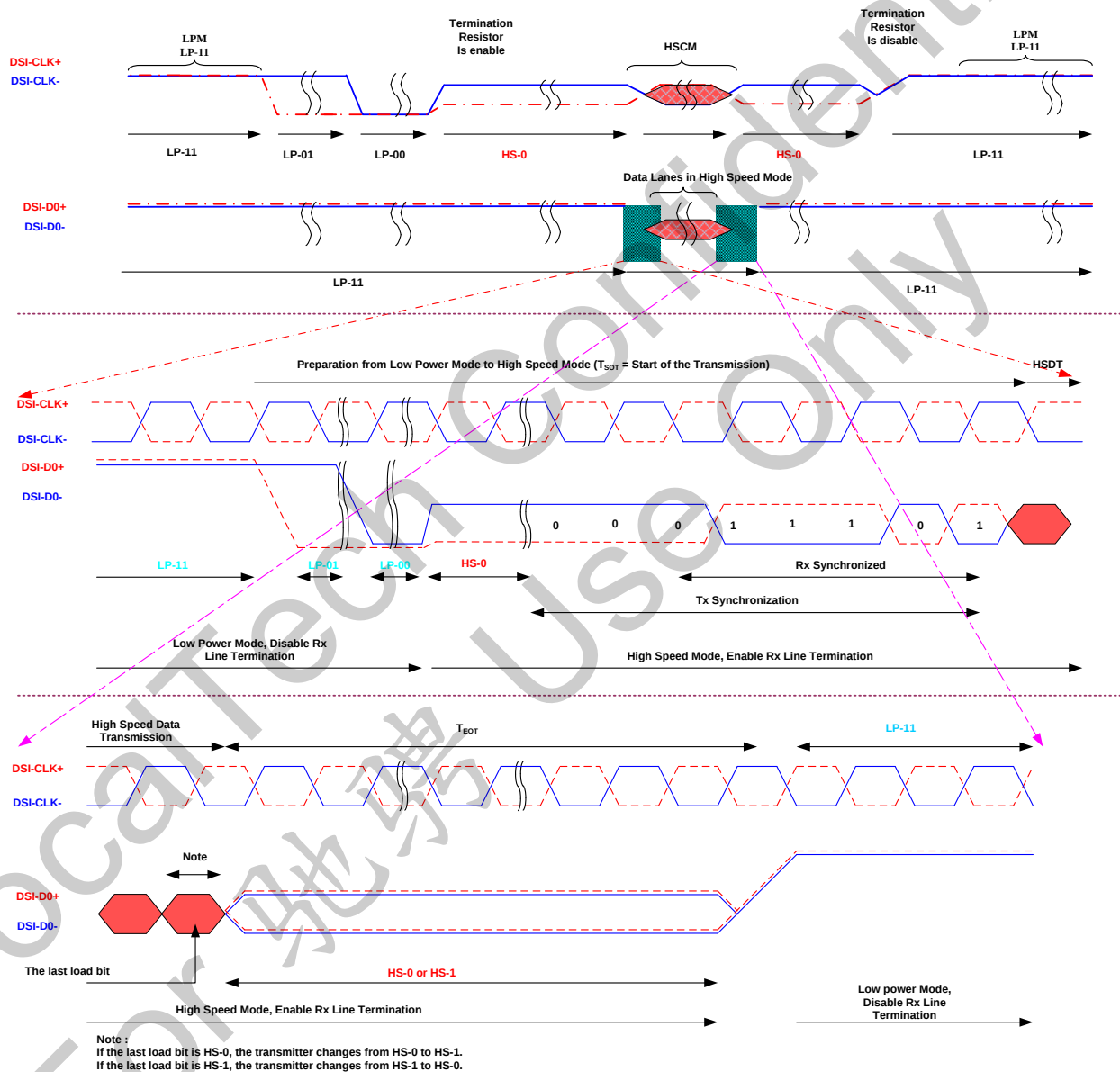


Figure: High speed clock burst

6.3.3. DSI data lanes

6.3.3.1. General

DSI-Dn+/- Data Lanes can be driven in different modes which are:

- Escape Mode (only support DSI_D0 data lane pair)
- High-Speed Data Transmission (support all data lane pairs)
- Bus Turnaround Request (only support DSI_D0 data lane pair)

These modes and their entering codes are defined on the following table.

Mode	Entering Mode Sequence	Leaving Mode Sequence
Escape Mode	LP-11 =>LP-10 =>LP-00 =>LP-01 =>LP-00	LP-00 =>LP-10 =>LP-11 (Mark-1)
High-Speed Data Transmission	LP-11 =>LP-01 =>LP-00 =>HS-0	(HS-0 or HS-1) =>LP-11
Bus Turnaround Request	LP-11 =>LP-10 =>LP-00 =>LP-10 =>LP-00	High-Z, Note

Table: Entering and leaving sequences

6.3.3.2. Escape modes

Escape mode is a special mode of operation for Data Lanes using Low-Power states. With this mode some additional functionality becomes available.

Escape mode operation shall be supported in the Forward direction and Reverse direction.

The basic sequence of the Escape Mode is as follow

- Start: LP-11
- Escape Mode Entry : LP-11 =>LP-10 =>LP-00 =>LP-01 =>LP-00
- Escape Command, which is coded, when one of the data lanes is changing from low-to-high-to-low then this changed data lane is presenting a value of the current data bit.
- A payload stream if it is needed
- Exit Escape (Mark-1) LP-00 =>LP-10 =>LP-11
- End: LP-11

For Data Lane0, once Escape mode is entered, the transmitter shall send an 8-bit entry command to indicate the requested action.

All currently available Escape mode commands and actions are list below.

- Send or receive “Low-Power Data Transmission” (LPDT)
- Drive data lanes to “Ultra-Low Power State” (ULPS)
- Indicate “Remote Application Reset” (RAR), which is resetting the display module (same as S/W Reset function)
- Indicate “Tearing Effect” (TEE), which is used for a TE line event from the display module to the MCU,
- Indicate “Acknowledge” (ACK), which is used for a non-error event from the display module to the MCU.

The Stop state shall be used to exit Escape mode and cannot occur during Escape mode operation because of the Spaced-One-Hot encoding. Stop state immediately returns the Lane to Control mode. If the entry command doesn't match a supported command, that particular Escape mode action shall be ignored and the receive side waits until the transmit side returns to the Stop state.

For Data Lane1 and 2, only support ULPS Escape mode commands.

- Drive data lanes to "Ultra-Low Power State" (ULPS)

The basic construction is illustrated below:

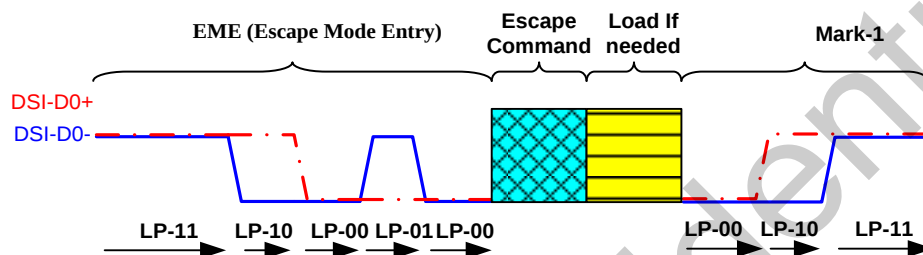


Figure: General Escape mode sequence

The number of the different Escape Commands is eight. These eight different Escape Commands can be divided 2 different groups: Mode or Trigger. Escape command groups are defined below.

Escape Command	Command Type Mode/Trigger	Entry Command Pattern (First Bit => Last Bit Transmitted)
Low-Power Data Transmission	Mode	1110 0001bin
Ultra-Low Power Mode	Mode	0001 1110bin
Remote Application Reset	Trigger	0110 0010 bin
Tearing Effect	Trigger	0101 1101 bin
Acknowledge	Trigger	0010 0001 bin

Table: Escape commands

The MCU is informing to the display module that it is controlling data lanes (DSI-D0+/-) with the mode e.g. The MCU can inform to the display module that it can put data lanes in the low power mode.

The MCU is waiting from the display module event information, which has been set by the MCU, with the trigger e.g. when the display module reaches a new V-synch, the display module sent to the MCU a TE trigger (TEE), if the MCU has been requested it.

Low-Power Data Transmission (LPDT)

The MCU can send data to the display module in Low-Power Data Transmission (LPDT) mode when data lanes are entering in Escape Mode and Low-Power Data Transmission (LPDT) command has been sent to the display module. The display module is also using the same sequence when it is sending data to the MCU.

The Low Power Data Transmission (LPDT) is using a following sequence:

- Start: LP-11
- Escape Mode Entry : LP-11 =>LP-10 =>LP-00 =>LP-01 =>LP-00
- Low-Power Data Transmission (LPDT) command in Escape Mode: 1110 0001 (First to Last bit)
- Payload (Data):
 - One or more bytes
 - Data lanes are in pause mode when data lanes are stopped (Both lanes are low) between bytes
- Mark-1: LP-00 =>LP-10 =>LP-11
- End: LP-11

This sequence is illustrated for reference purposes below:

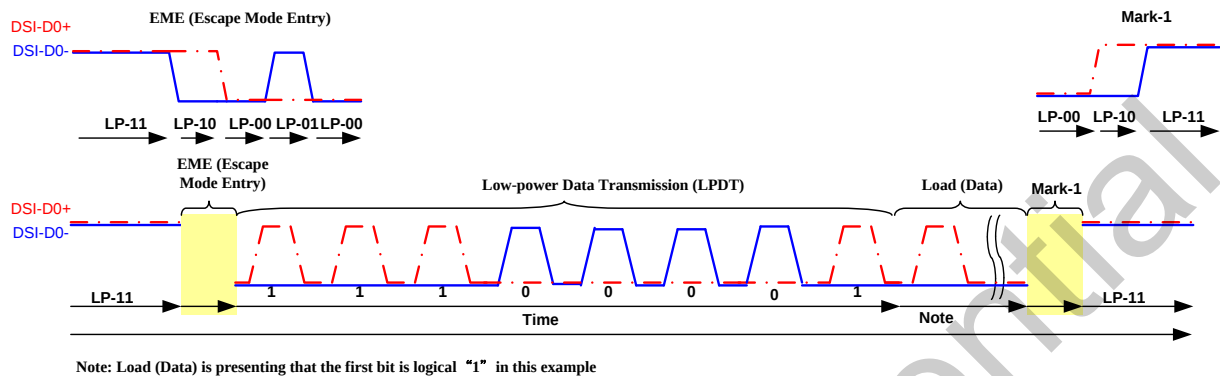


Figure: Low-power data transmission

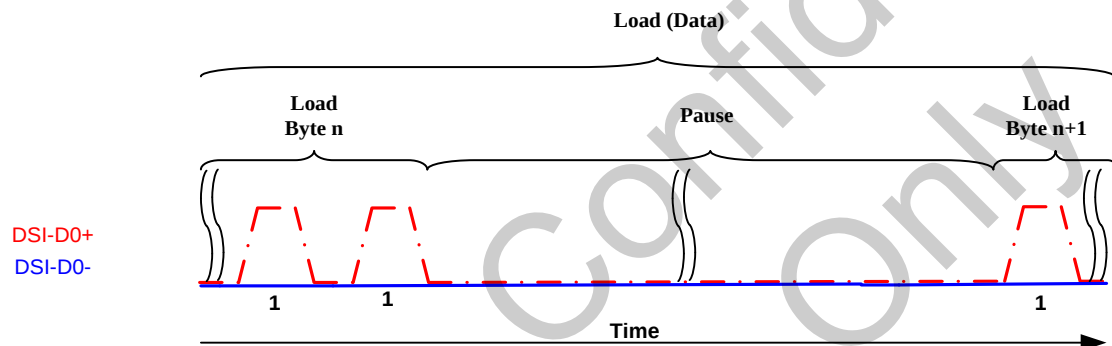


Figure: Pause (example)

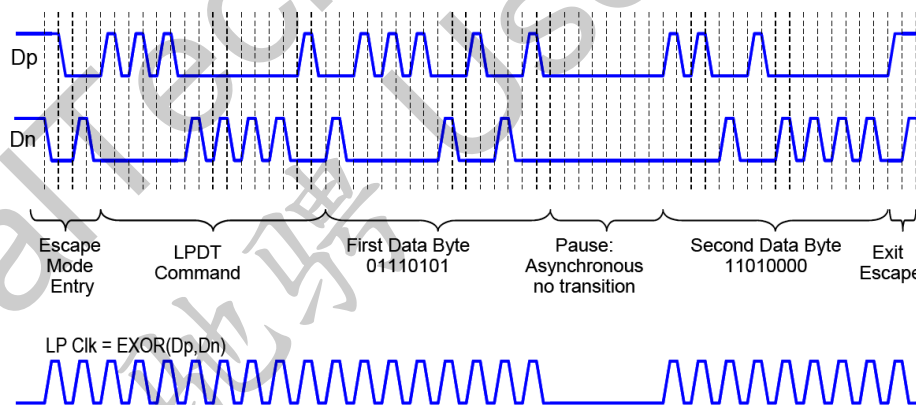


Figure: Two Data Byte Low-Power Data Transmission Example

Ultra-Low Power State (ULPS)

The MCU can force data lanes in Ultra-Low Power State (ULPS) mode when data lanes are entering in Escape Mode.

The Ultra-Low Power State (ULPS) is using a following sequence:

- Start: LP-11
- Escape Mode Entry : LP-11 =>LP-10 =>LP-00 =>LP-01 =>LP-00
- Ultra-Low Power State (ULPS) command in Escape Mode: 0001 1110 (First to Last bit)
- Ultra-Low Power State (ULPS) when the MCU is keeping data lanes low
- Mark-1: LP-00 =>LP-10 =>LP-11
- End: LP-11

This sequence is illustrated for reference purposes below:

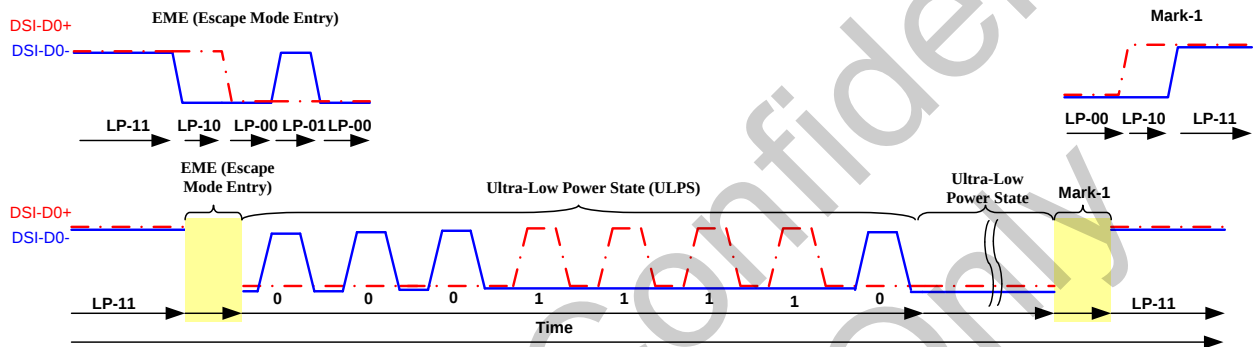


Figure: Ultra-low power state (ULPS)

Remote Application Reset (RAR)

The MCU can inform to the display module that it should be reset in Remote Application Reset (RAR) trigger when data lanes are entering in Escape Mode. The Remote Application Reset is using a following sequence:

- Start: LP-11
- Escape Mode Entry : LP-11 =>LP-10 =>LP-00 =>LP-01 =>LP-00
- Remote Application Reset (RAR) command in Escape Mode: 0110 0010 (First to Last bit)
- Mark-1: LP-00 =>LP-10 =>LP-11
- End: LP-11

This sequence is illustrated for reference purposes below:

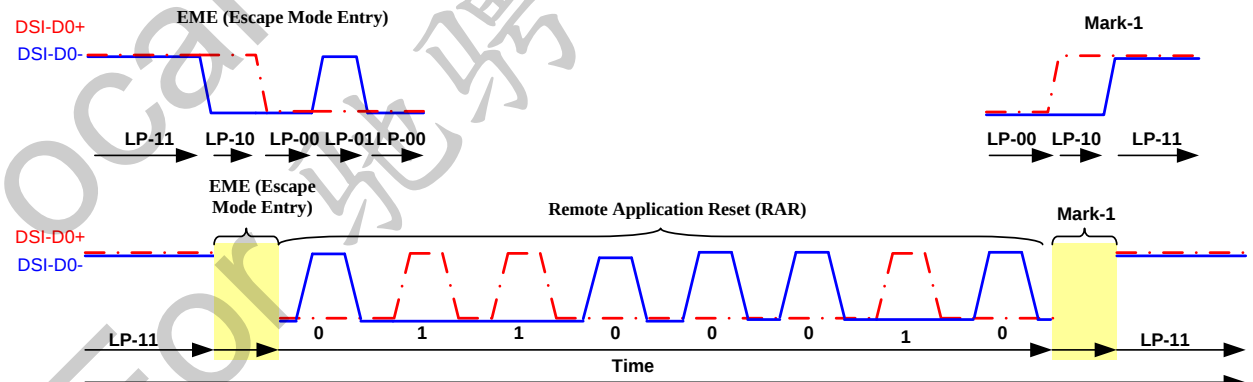


Figure: Remote Application Reset (RAR)

Tearing Effect (TEE)

The display module can inform to the MCU when a tearing effect event (New V-synch) has been happen on the display module by Tearing Effect (TEE).

The Tearing Effect (TEE) is using a following sequence:

- Start: LP-11
- Escape Mode Entry: LP-11 =>LP-10 =>LP-00 =>LP-01 =>LP-00
- Tearing Effect (TEE) trigger in Escape Mode: 0101 1101 (First to Last bit)
- Mark-1: LP-00 =>LP-10 =>LP-11
- End: LP-11

This sequence is illustrated for reference purposes below:

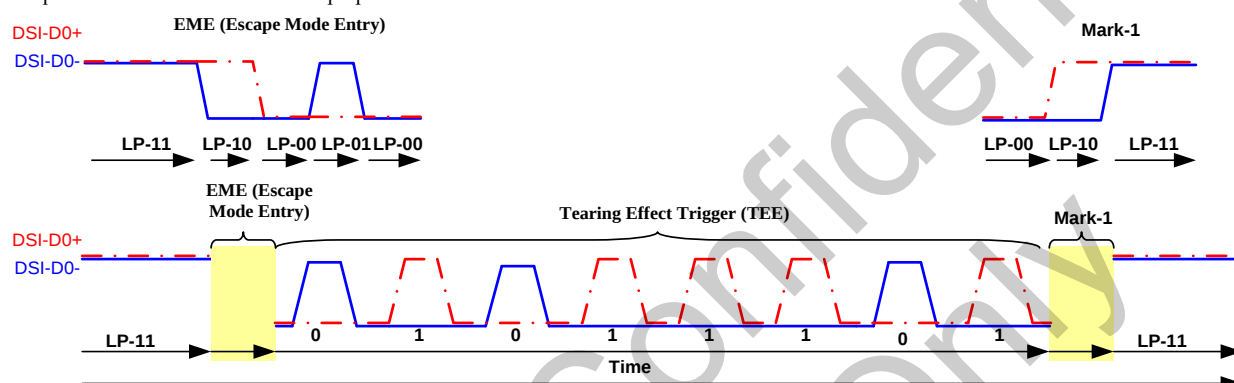


Figure: Tearing effect (TEE)

Acknowledgement (ACK)

The display module can inform to the MCU when an error has not recognized on it by Acknowledge (ACK).

The Acknowledge (ACK) is using a following sequence:

- Start: LP-11
- Escape Mode Entry: LP-11 =>LP-10 =>LP-00 =>LP-01 =>LP-00
- Acknowledge (ACK) command in Escape Mode: 0010 0001 (First to Last bit)
- Mark-1: LP-00 =>LP-10 =>LP-11
- End: LP-11

This sequence is illustrated for reference purposes below:

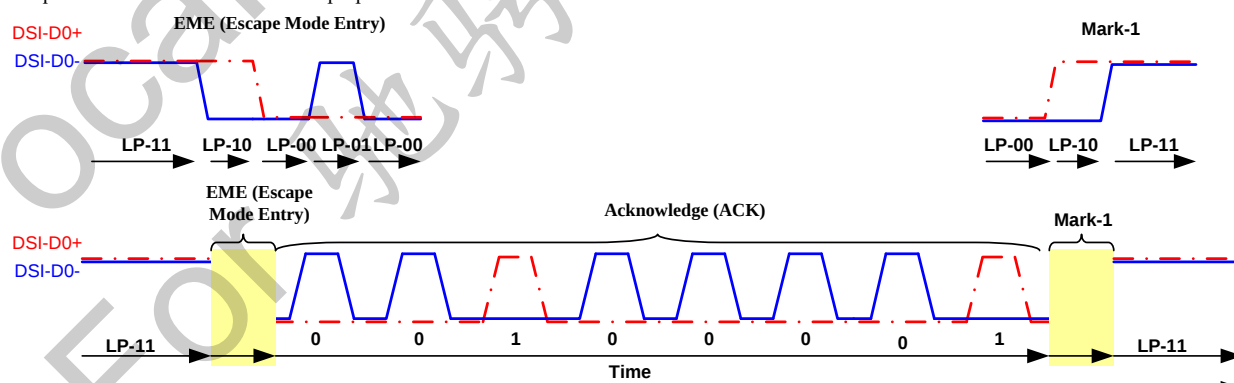


Figure: Acknowledgement (ACK)

6.3.3.3. High-Speed Data Transmission (HSDT)

Entering High-Speed Data Transmission (T_{sof} of HSDT)

The display module is entering High-Speed Data Transmission (HSDT) when Clock lanes DSI-CLK+/- have already been entered in the High-Speed Clock Mode (HSCM) by the MCU. See more information on chapter "High-Speed Clock Mode (HSCM)".

Data lanes DSI-D0+/- of the display module are entering (TSOT) in the High-Speed Data Transmission(HSDT) as follows

- Start: LP-11
- HS-Request: LP-01
- HS-Settle: LP-00 => HS-0 (Rx: Lane Termination Enable)
- Rx Synchronization: 011101 (Tx (= MCU) Synchronization: 0001 1101)
- End: High-Speed Data Transmission (HSDT) – Ready to receive High-Speed Data Load

This same entering High-Speed Data Transmission (TSOT of HSDT) sequence is illustrated below.

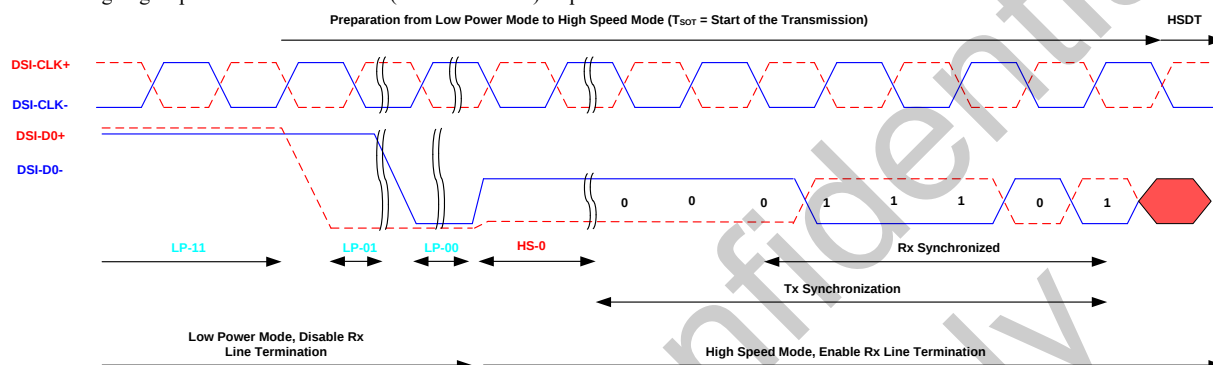


Figure: Tsot of HSDT

Leaving High-Speed Data Transmission (T_{EOT} of HSDT)

The display module is leaving the High-Speed Data Transmission (T_{EOT} of HSDT) when Clock lanes DSI-CLK+/- are in the High-Speed Clock Mode (HSCM) by the MCU and this HSCM is kept until data lanes

DSI-D0+/- are in LP-11 mode. See more information on chapter “7.2.2 High-Speed Clock Mode (HSCM)”.

Data lanes DSI-D0+/- of the display module are leaving from the High-Speed Data Transmission (T_{EOT} of HSDT) as follows

- Start: High-Speed Data Transmission (HSDT)
- Stops High-Speed Data Transmission
 - MCU changes to HS-1, if the last load bit is HS-0
 - MCU changes to HS-0, if the last load bit is HS-1
- End: LP-11 (Rx: Lane Termination Disable)

This same leaving High-Speed Data Transmission (T_{EOT} of HSDT) sequence is illustrated below

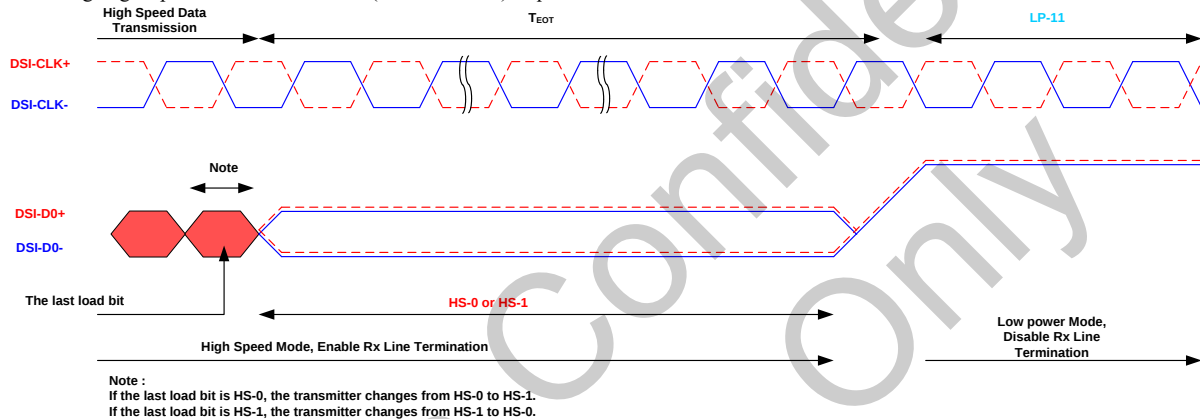


Figure: TEOT of HSDT

Burst of the High-Speed Data Transmission (HSDT)

The burst of the high-speed data transmission (HSDT) can consist of one data packet or several data packets.

These data packets can be Long (Lpa) or Short (Spa) packets. These packets are defined on chapter “Short Packet (Spa) and Long Packet (Lpa) Structures”.

These different burst of the High-Speed Data Transmission (HSDT) cases are illustrated for reference purposes below.

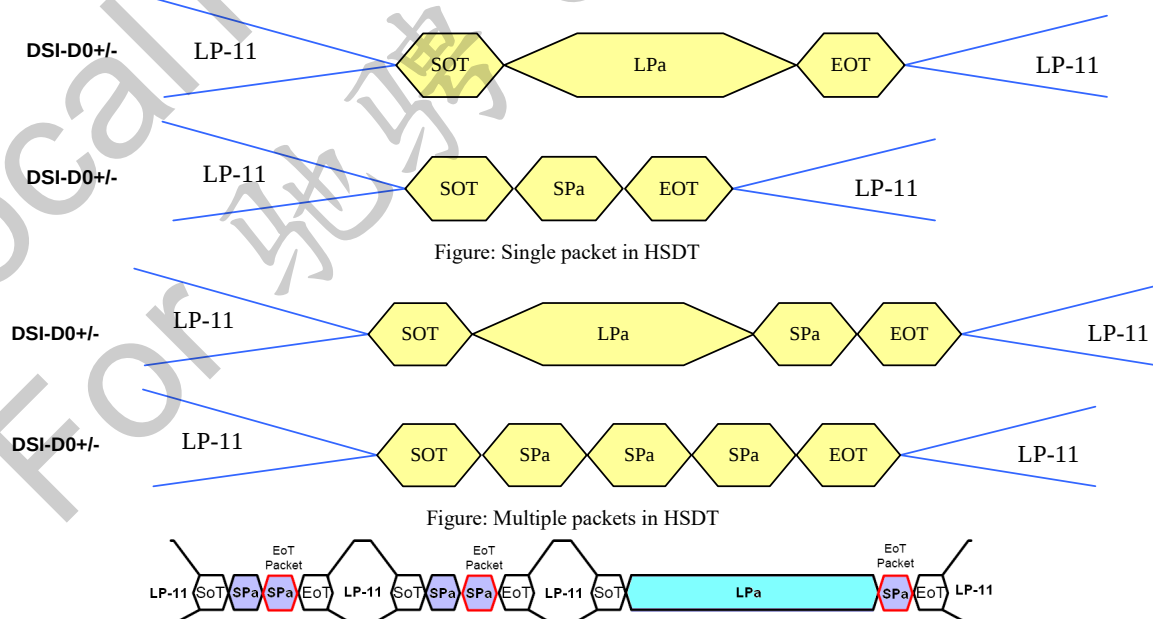


Figure: Packets with EoT package in HSDT

Abbreviation	Explanation
LP-11	Low Power Mode, Data lanes are '1's (Stop Mode)
SOT	Start of the Transmission
Lpa	Long Packet
Spa	Short Packet
EOT	End of the Transmission

Table: Abbreviations

6.3.3.4. Bus Turnaround (BTA)

The MCU or display module, which is controlling DSI-D0+/- Data Lanes, can start a bus turnaround procedure when it wants information from a receiver, which can be the MCU or display module.

The MCU and display module are using the same sequence when this bus turnaround procedure is used.

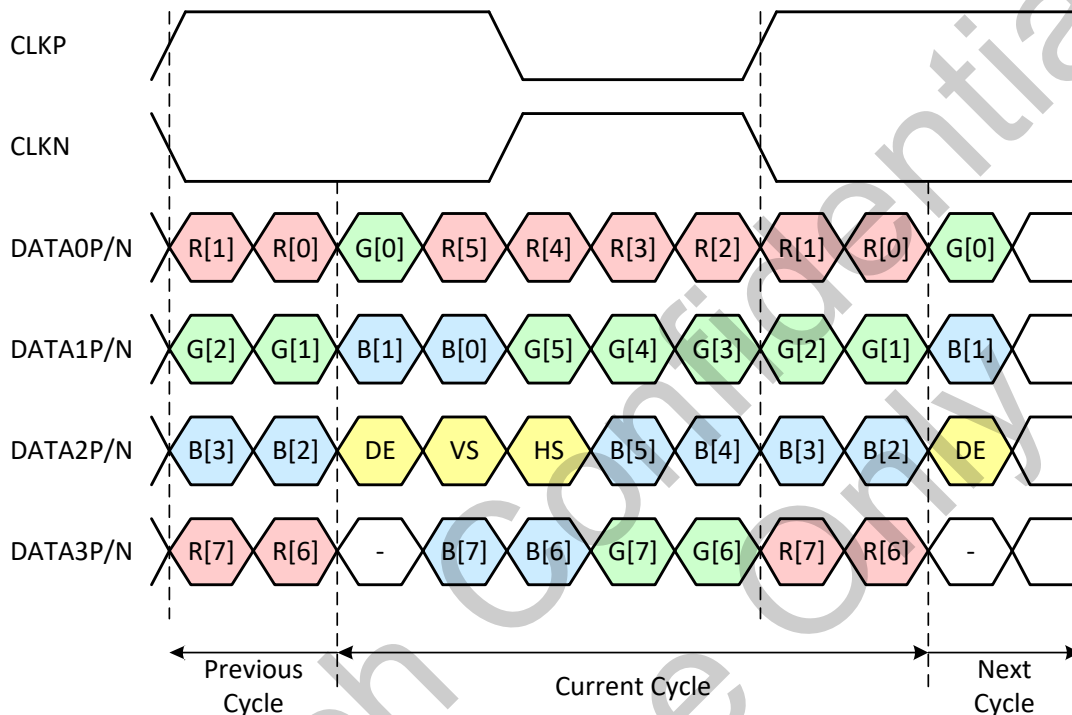
This sequence is described for reference purposes, when the MCU wants to do the bus turnaround procedure to the display module, as follows.

- Start (MCU): LP-11
- Turnaround Request (MCU): LP-11 =>LP-10 =>LP-00
- The MCU waits until the display module is starting to control DSI-D0+/- data lanes and the MCU stops to control DSI-D0+/- data lanes (= High-Z)
- The display module changes to the stop mode: LP-00 =>LP-10 =>LP-11

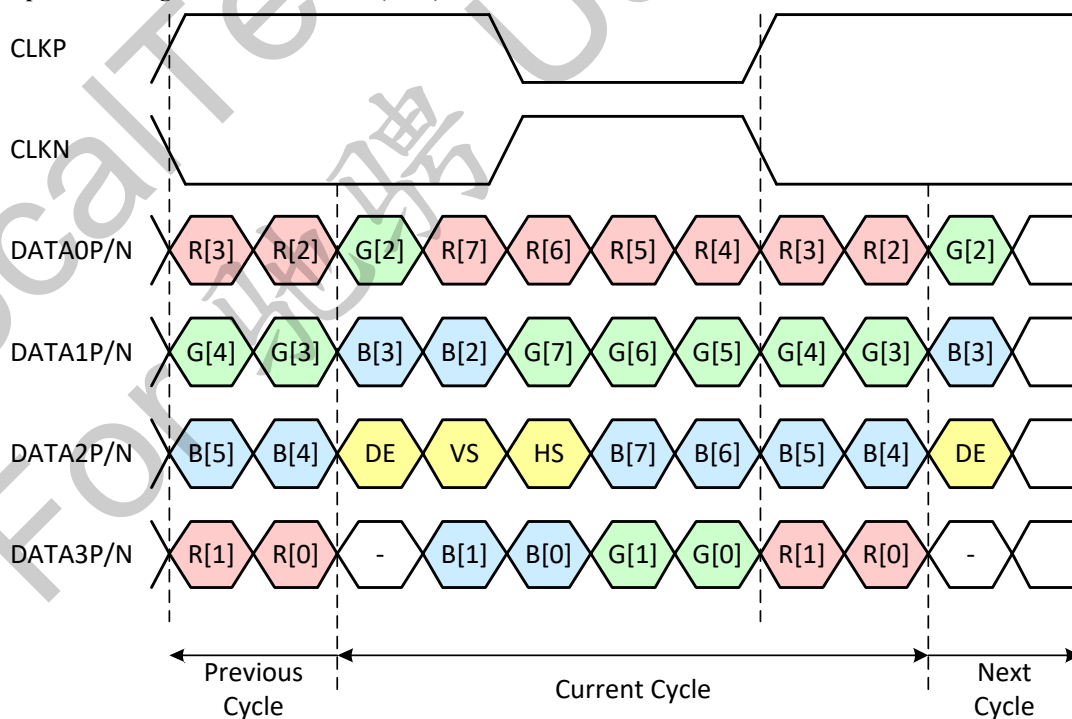
6.4. LVDS Interface

It supports different display resolutions with single port LVDS interface.

6.4.1. 1-port LVDS signals, VESA format (8-bit)



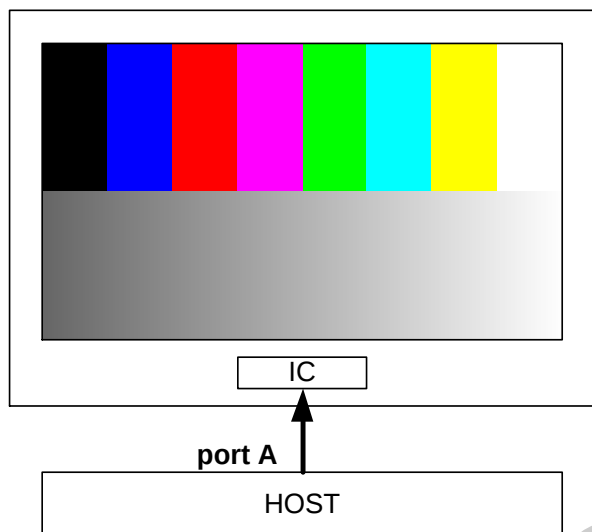
6.4.2. 1-port LVDS signals, JEIDA format (8-bit)



6.4.3. LVDS architecture

Cascade 1 IC

Single Port LVDS

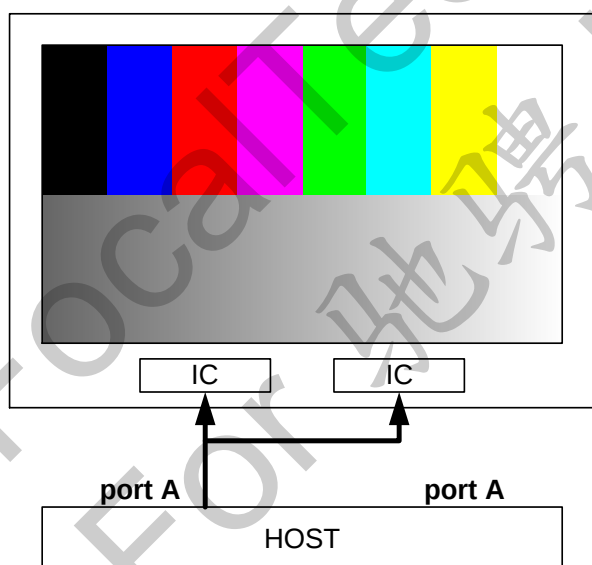


CLK rate = 110 MHz

Option: Need 5 Resistors (100 ohm/Resistor)

Cascade 2 ICs

Single port LVDS by multi-drop architecture

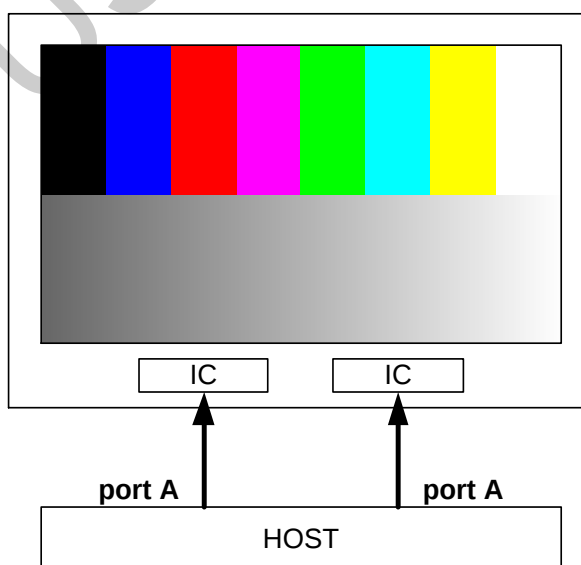


CLK rate = 110 MHz

Option :Need 5 Resistors (100 ohm/Resistor)

Cascade 2 ICs

Single port LVDS by point to point architecture

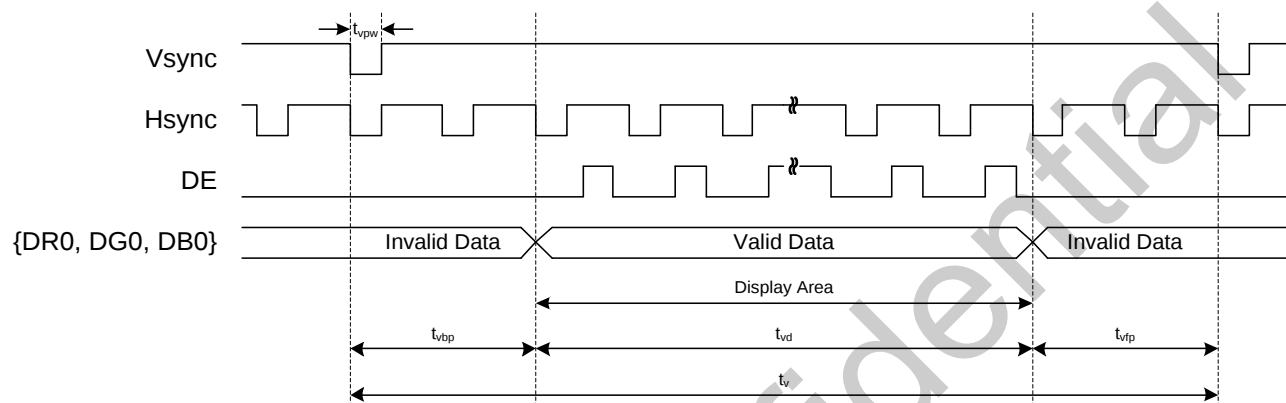


CLK rate = 55 MHz

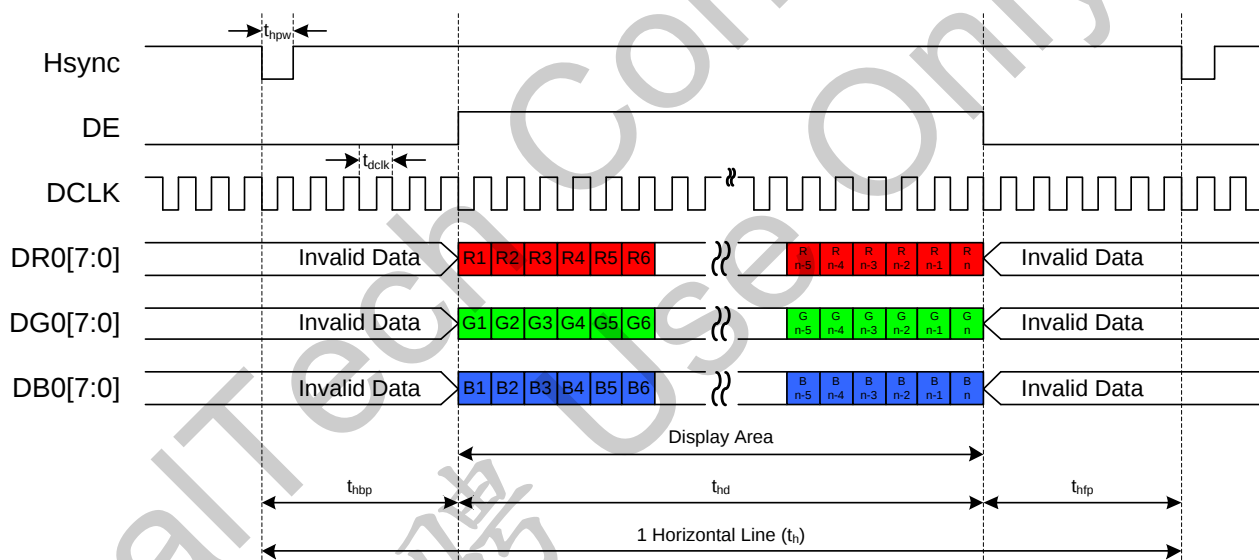
Host IC need to split the whole image as 2 blocks
Option: Need 10 Resistors (100 ohm/Resistor)

6.4.4. LVDS Video Input Timing

Vertical timing after LVDS 1-port client decode (internal signal) is:



Horizontal timing after LVDS 1-port client decode (internal signal) is:



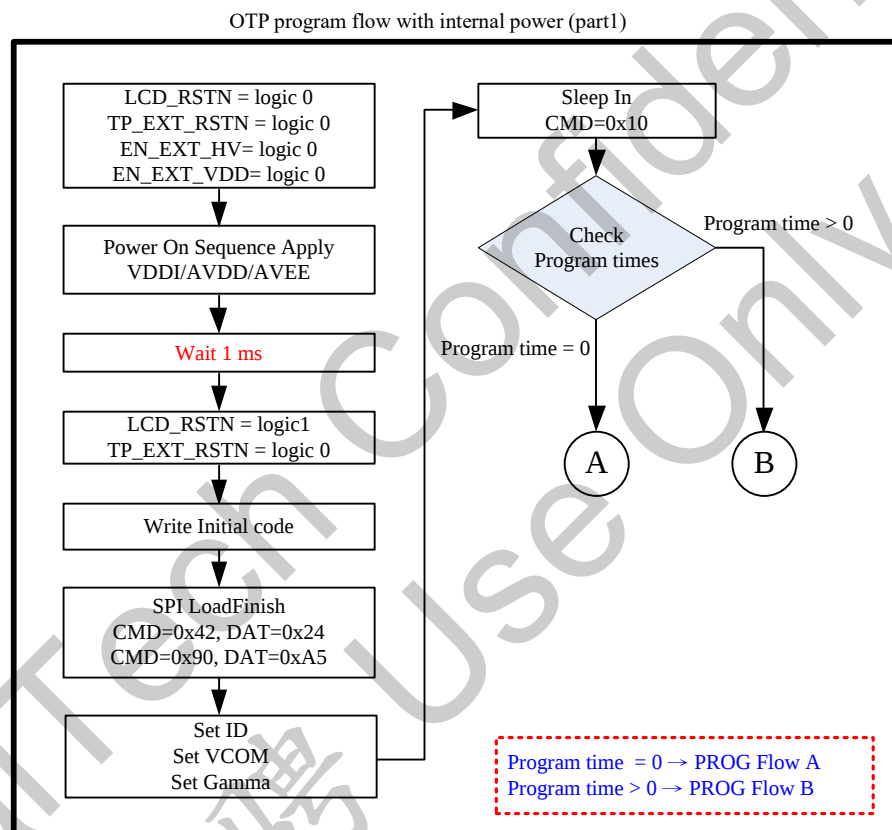
by I2C_SLAVE address, please refer to the following truth table for write case and read case.

I2C_SLAVE address	Description
7'h50	Read/Write master (TP_MS = 1'b1) enable Read/Write slave (TP_MS = 1'b0) enable
7'h52	Read/Write master (TP_MS = 1'b1) enable
7'h54	Read/Write slave (TP_MS = 1'b0) enable

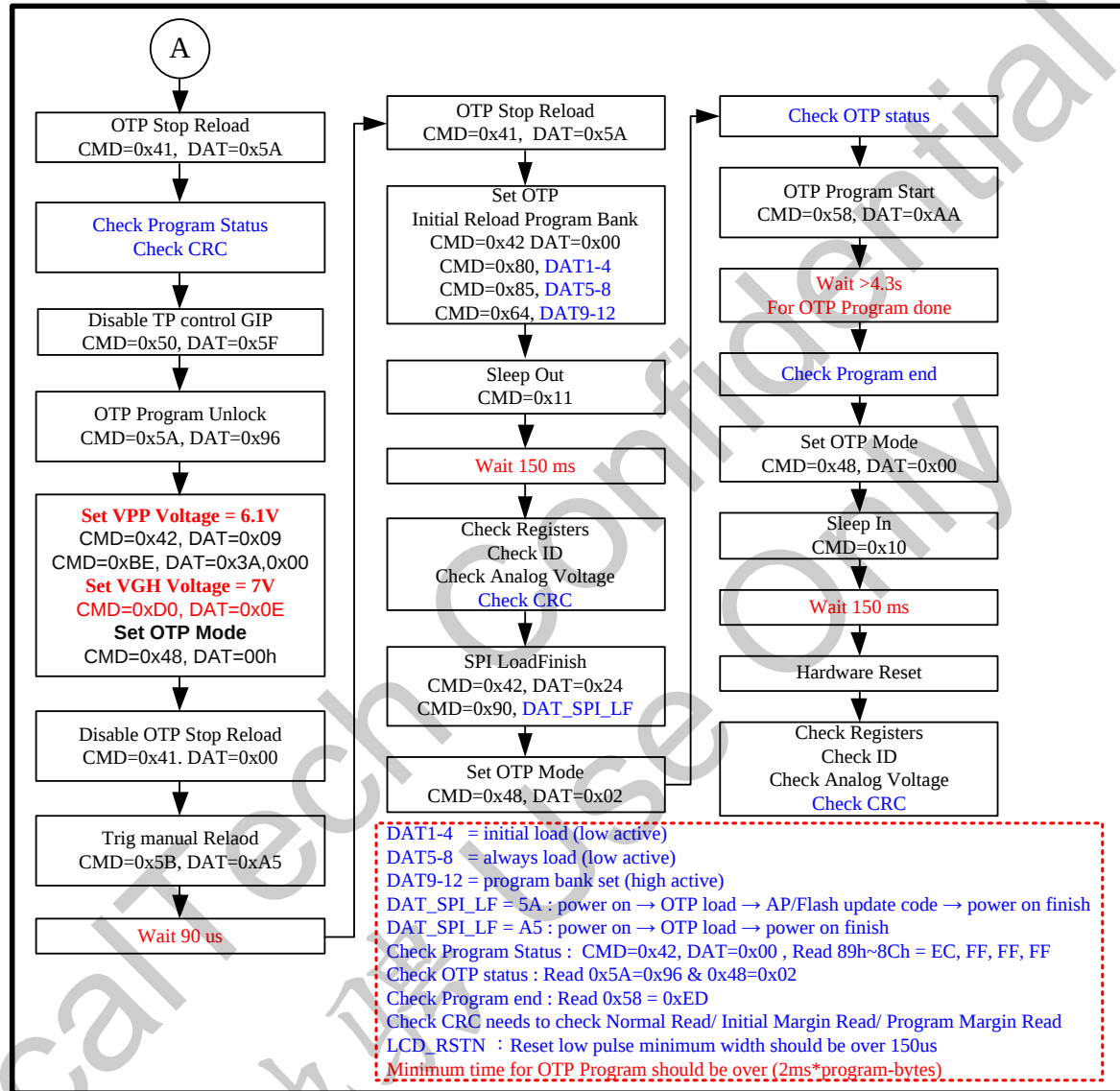
6.6.NVM Programming Procedure

6.6.1. NVM program flow chart with internal power

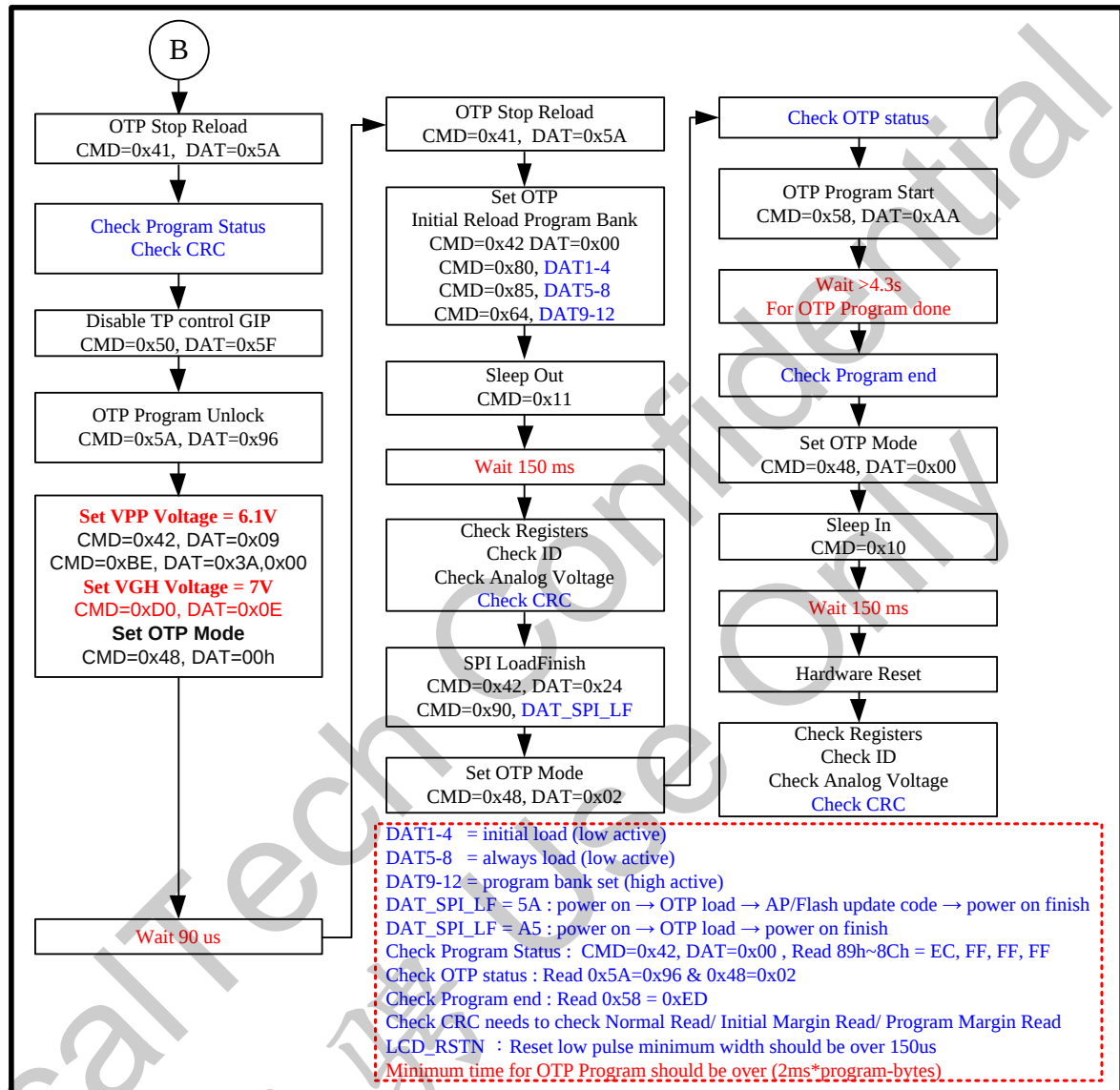
1. TCON registers must include correct panel timing configurations to program NVM on panel.
2. TP_EXT_RSTN has to keep low during NVM program flow.
3. Bank8 ~ Bank31 are suggested to set “Initial load” for the 1st time OTP download at power on, but not to set “always load” for OTP-auto-reload periodically. It allows HOST/FW to update settings within Bank8 ~ Bank31 and would not be overwritten by OTP-auto-reload.



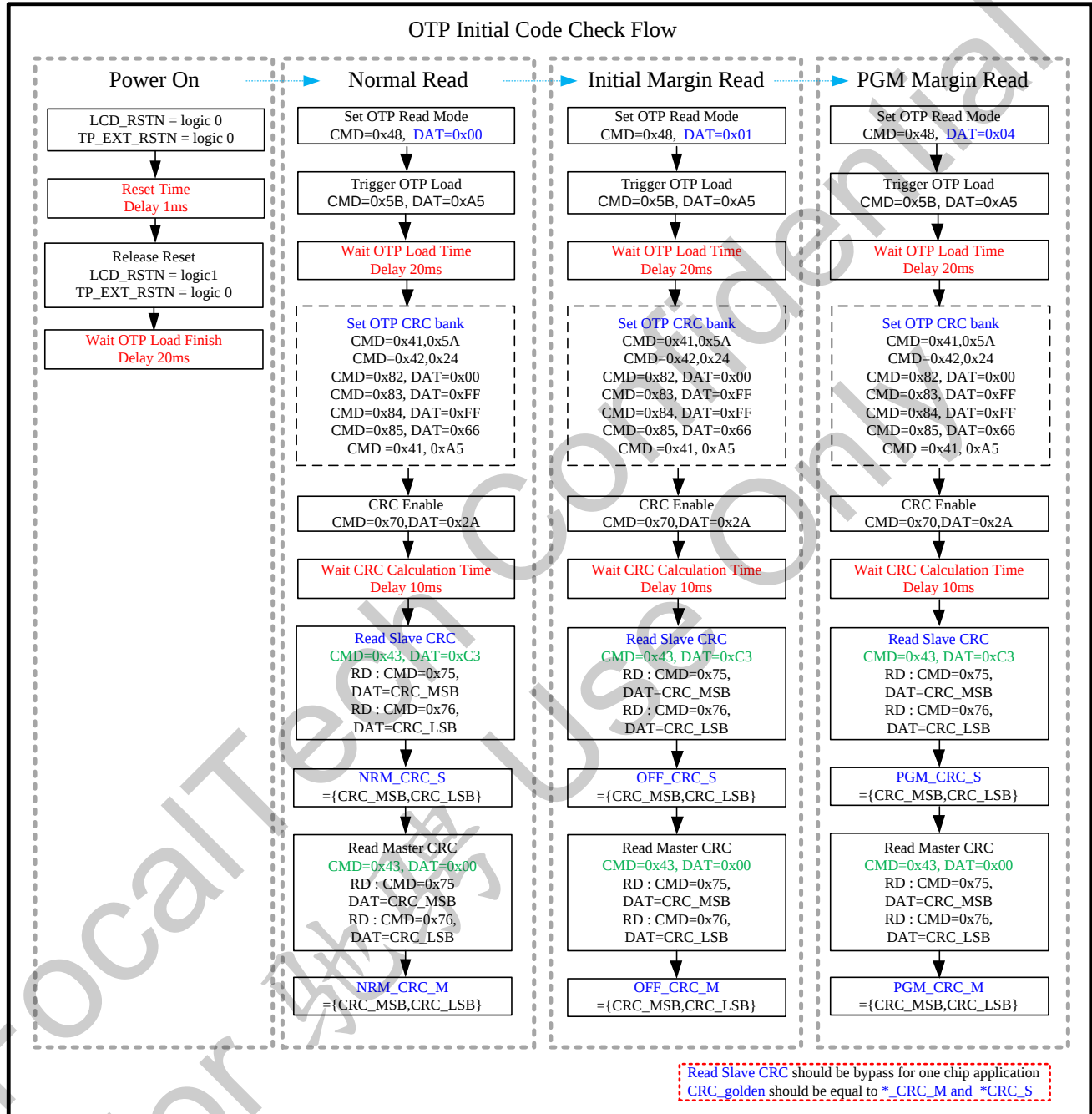
OTP program flow with internal power (part2)



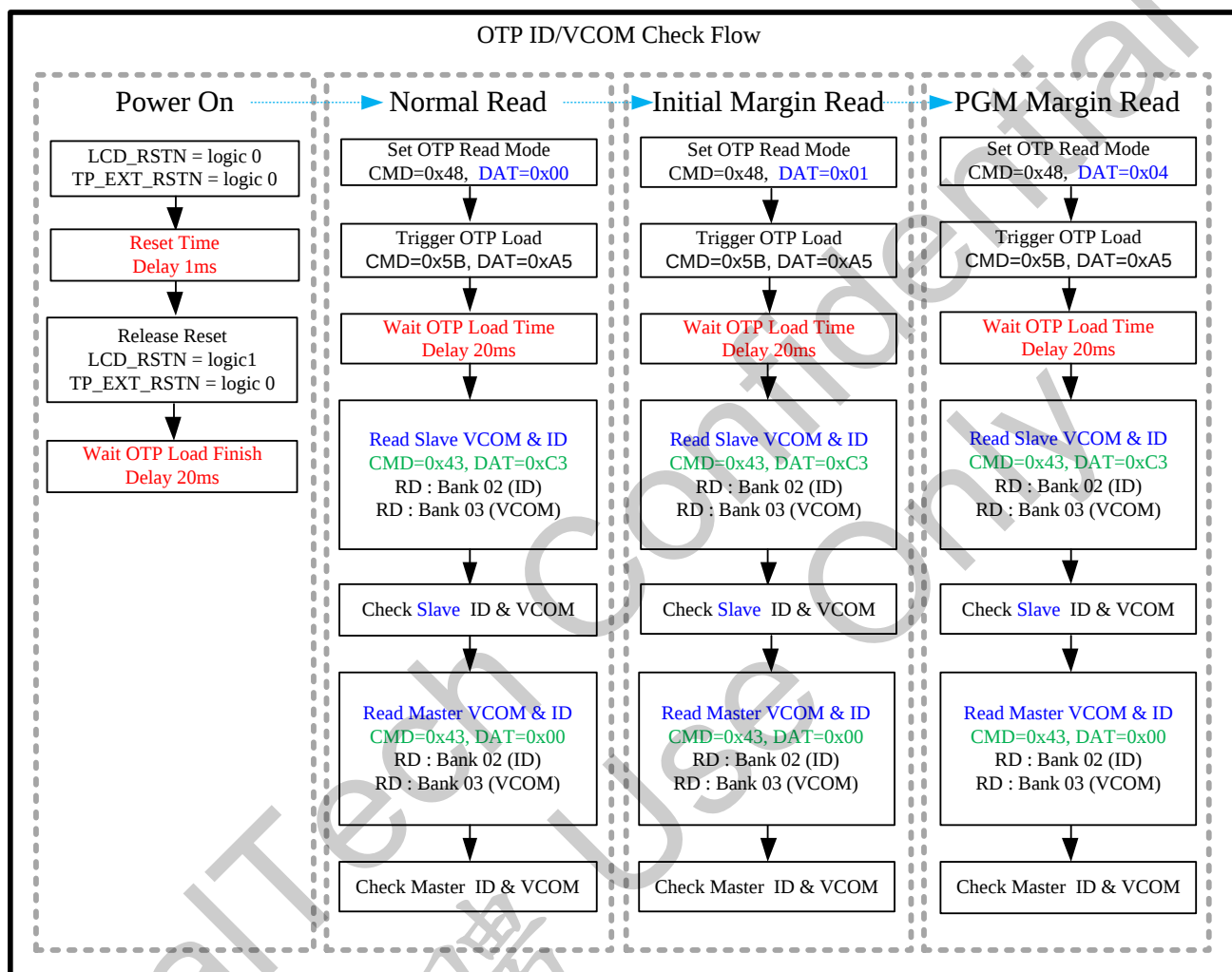
OTP program flow with internal power (part3)



OTP CRC Flow (all bank)



OTP ID and VCOM Check Flow



7 ELECTRICAL SPECIFICATIONS

7.1 Absolute Maximum Ratings

(AVDD = 4.5V ~ 6.5V, AVEE = -4.5V ~ -6.5V, VDDI = 1.65V ~ 1.95V(MIPI) or 2.7V~3.6V(LVDS), Ta = -30°C ~ 85°C)

Parameter	Symbol	Rating	Unit	Note
Power Supply Voltage 1	VDDI-VSS	-0.3 ~ +1.95	V	MIPI application
Power Supply Voltage 1	VDDI-VSS	-0.3 ~ +3.6	V	LVDS application
Power Supply Voltage 2	VDD-VSS	-0.3 ~ +1.35	V	
Power Supply Voltage 3	AVDD-VSS	-0.3 ~ +6.5	V	
Power Supply Voltage 4	VSS-AVEE	-0.3 ~ +6.5	V	
Power Supply Voltage 5	VGH-VGL	-0.3 ~ +32	V	
Input Voltage	Vt	-0.3 ~ VDDI+0.3	V	
Operating Temperature	Topr	-30 ~ +85	°C	
Storage Temperature	Tstg	-55 ~ +110	°C	

Note1. The maximum applicable voltage on any pin with respect to 0V.

Note2. Device is subject to be damaged permanently if stresses beyond those absolute maximum ratings listed above.

7.2 DC Characteristics

7.2.1 Basic DC characteristic

(AVDD = 4.5V~6.5V, AVEE = -4.5V~-6.5V, VDDI = 1.65V~1.95V(MIPI) or 2.7V~3.6V(LVDS), VDD_EXT=1.2V~1.35V, Ta = -30°C ~ 85°

C)

Parameter	Symbol	Conditions	Specification			Unit	Notes
			MIN	TYP	MAX		
Power & Operation Voltage							
Analog Operating voltage	AVDD	Operating Voltage	4.5	5.5	6.5	V	
Analog Operating voltage	AVEE	Operating Voltage	-6.5	-5.5	-4.5	V	
Logic Operating voltage	VDDI	I/O supply voltage	1.65	1.8	1.95	V	MIPI
Logic Operating voltage	VDDI	I/O supply voltage	2.7	3.3	3.6	V	LVDSRX
Digital Operating voltage (4 power mode)	VDD_EXT	External Digital voltage	-	1.3	1.35	V	
Input / Output							
Logic High level input voltage	VIH	-	0.7VDDI	-	VDDI	V	
Logic Low level input voltage	VIL	-	VSS	-	0.3VDDI	V	
Logic High level output voltage	VOH	IOH = -1.0mA	0.8VDDI	-	VDDI	V	
Logic Low level output voltage	VOL	IOL = +1.0mA	VSS	-	0.2VDDI	V	
Logic High level input current	IIH	Vin = VDDI	-	-	1	uA	
Logic Low level input current	IIL	Vin = VDDI	-1	-	-	uA	
VCOM Operation							
VCOMDC output voltage	VCOM	AVDD=AVEE=+/-5V	-3.85	-	0.3	V	
Source Driver							
Gamma positive reference voltage	VGMP	VGMP<AVDD-0.2V	3.75	-	6.3	V	
Gamma negative reference voltage	VGMN	VGMN>AVEE-0.2V	-6.3	-	-3.75	V	
Source output voltage	VSD	-	VGMN	-	VGMP	-	
Output deviation voltage (Source positive output channel)	V _{dev}	Sout >=+4.2V, Sout <=+0.8V	-	-	20	mV	
		+4.2V>Sout>+0.8V	-	-	10	mV	
Output deviation voltage (Source negative output channel)	V _{dev}	Sout <=-4.2V, Sout >=-0.8V	-	-	20	mV	
		-4.2V<Sout<-0.8V	-	-	10	mV	
Output offset voltage	V _{OFFSET}	-	-	-	100	mv	
Reference Voltage							
Internal reference voltage	VREF_TP	-	3	3.5	4.4	V	
Booster operation							
Pump output voltage	VGH	Range=(AVDD-AVEE) ~(2AVDD-2AVEE)	6.0	-	22.2	V	
Pump output voltage	VGL	Range=(AVEE-AVDD) ~(2AVEE-AVDD)	-18.0	-	-5.3	V	
Regulator output voltage	VCL	-	-5	-4.5	-3.5	V	

Note1. The maximum applicable voltage on any pin with respect to 0V.

Note2. Device is subject to be damaged permanently if stresses beyond those absolute maximum ratings listed above.

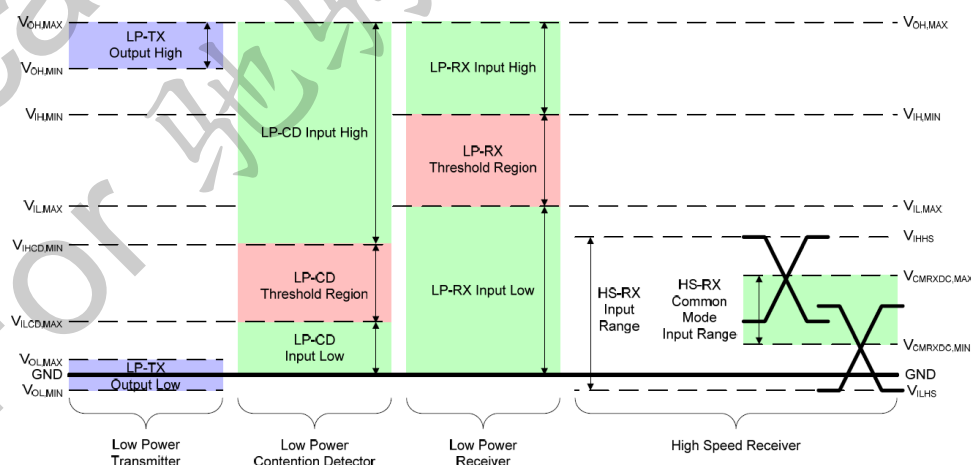
7.2.2 MIPI D-PHY DC character

D-PHY DC characteristics for MIPI-DSI

(Ta = -30°C ~ 85°C)

Parameter	Symbol	Conditions	Specification			Unit
			MIN	TYP	MAX	
Power supply voltage for MIPI Interface						
Power supply voltage for MIPI interface	LVDSVDD	-	1.15	1.2	1.25	V
LPDT Input Characteristics						
Pad signal voltage range	V _I	-	-50	-	1350	mV
Ground Shift	V _{GNDSH}	-	-50	-	50	mV
Logic 0 input threshold	V _{IL}	-	-	-	550	mV
Logic 1 input threshold	V _{IH}	-	880	-		mV
Input hysteresis	V _{HYST}	-	25	-	-	mV
LPDT Output Characteristics						
Output low level	V _{OL}	-	-50	-	50	mV
Output high level	V _{OH}	Note 1	1.15	1.2	1.25	V
Logic 0 contention threshold	V _{ILCD}	-	-	-	200	mV
Logic 1 contention threshold	V _{IHCD}	-	450	-	-	mV
Output impedance of LPDT	Z _{OLP}	-	110	-	-	Ω
Hi-speed Input Characteristics						
Single-end input low voltage	V _{ILHS}	-	-40	-	-	mV
Single-end input high voltage	V _{IHHS}	-	-	-	460	mV
Single-end threshold for HS termination enable	V _{TERM-EN}	-	-	-	450	mV
Differential input low threshold	V _{IDTL}	-	-70	-	-	mV
Differential input high threshold	V _{IDTH}	-	-	-	70	mV
Common mode voltage	V _{CMRXDC}	-	70	-	330	mV
Differential input impedance	Z _{ID}	-	80	100	125	Ω

Note1: Output high level follow Power supply voltage for MIPI



7.2.3 LVDS DC characteristic

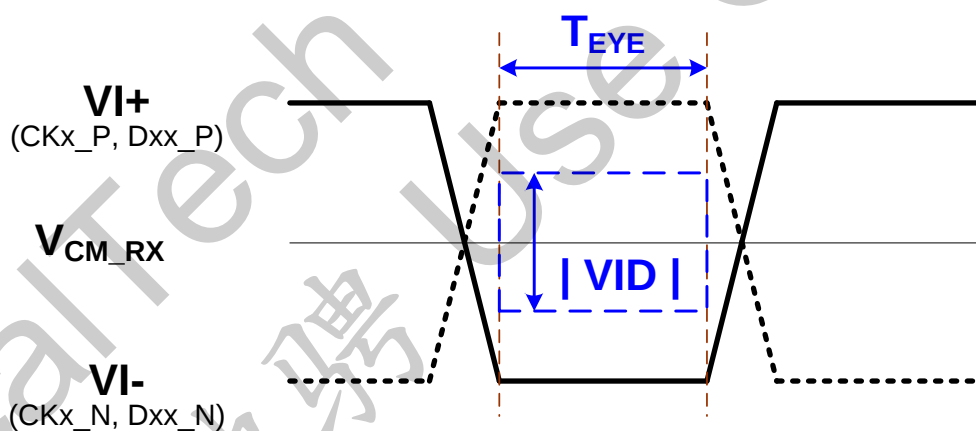
Table: DC characteristics for LVDS

(VDDI = 2.7~3.6V, AVDD=4.5~6.5V, AVEE=-4.5~-6.5V, VSS = AVSS = 0V, T_{OP} = 25°C)

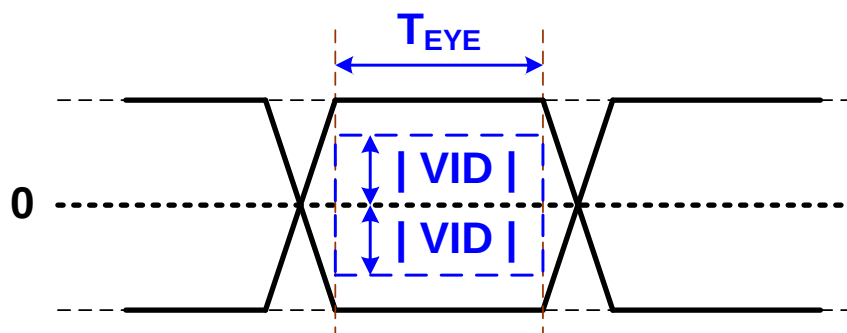
Parameter	Symbol	Conditions	Specification			Unit
			Min.	Typ.	Max.	
For The Digital Circuit: LVDS Mode						
Operating frequency LVDS mode (including SSC operation)	FLVDS	By resolution	15		110	MHz
Differential input common mode voltage	VCM_RX		0.6		1.5	V
Differential input voltage (NOTE 1)	VID		90	350	600	mV
Differential input data eye width	T _{EYE}		0.6	-	-	UI
Differential input leakage current	RXI_lkg		-10	-	+10	μA

NOTE1 : Input Differential Voltage VID = VI+ - VI-

Single-ended



Differential (VI+ - VI-)



7.2.4 SPI DC characteristics

DC characteristics for SPI

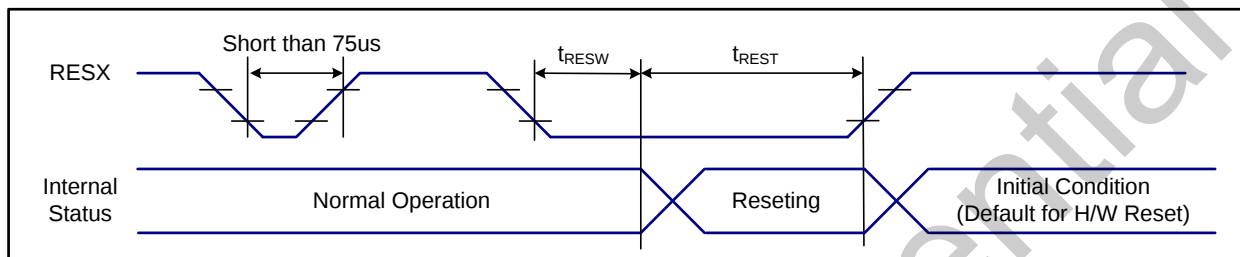
Parameter	Symbol	Conditions	Specification			Unit
			MIN	TYP	MAX	
Input terminal : CS, SCL, MOSI						
Input High Voltage	VIH	-	0.9*VDDI	-	-	V
Input Low Voltage	VIL	-	-	-	0.1*VDDI	V
Input Capacitance	Cin	-	-	10	-	pF
Output terminal : MISO						
Output High Voltage	VOH		-	0.9*VDDI*	-	V
Output Low Voltage	VOL		-	0.1*VDDI*	-	V

*VDDI=1.8V(MIPI) or 2.7~3.6V(LVDS)

7.3 AC Characteristics

7.3.1 Reset timing characteristics

t_{RESW} shorter than 75us, Reset will be rejected.



VSS=0V, VDDI = 1.65V ~ 1.95V(MIPI) or 2.7~3.6(LVDS), Ta = -30°C to 85°C

Symbol	Parameter	MIN	TYP	MAX	Note	Unit
t_{RESW}	*1) Reset low pulse minimum width	150	-	-	Reset signal recognized	us
t_{REST}	*2) Reset complete time	5	-	120	Reset action complete	ms

Table: Reset input timing

Note 1. RESX low pulse that is too short does not cause irregular system reset according to the table below.

RESX Pulse	Action
Shorter than 75us	Reset Rejected
Longer than 150us	Reset Recognized
Between 75us and 150us	Reset sequence starts (It depends on voltage and temperature condition.)

Note 2. Once Reset low pulse is recognized, system requires RESX remaining low for another 5ms to complete H/W reset.

Note 3. During H/W Reset flow, ID0 ~ ID4 and VCOM value in OTP will be latched to internal register during this period. This loading is done every time when H/W reset is complete ; The H/W reset sequence is complete when RESX is remaining low longer than $t_{RESW} + t_{REST}$.

Note 4. It is necessary to wait 15msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120 msec.

7.3.2 I²C interface characteristics

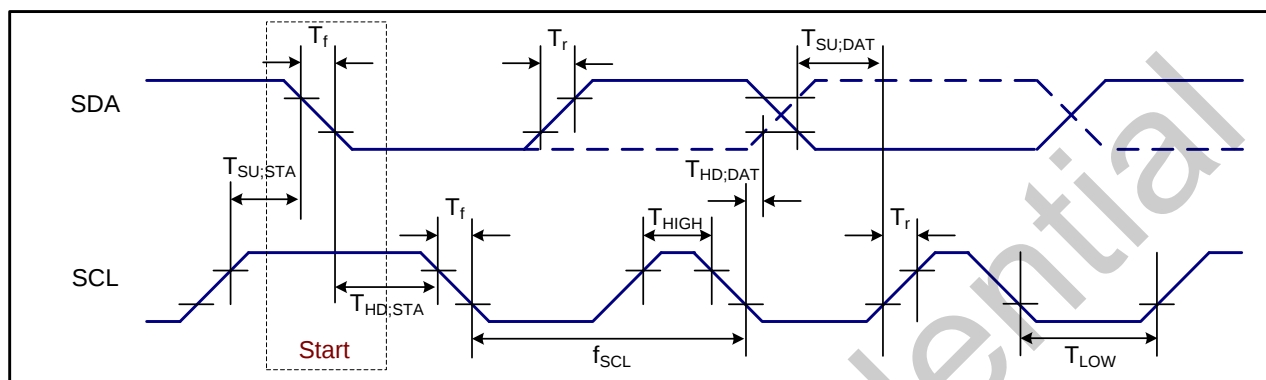


Table: I2C Interface Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
f_{SCLK}	SCL clock frequency	-	10	-	400	kHz
T_{LOW}	SCL clock LOW period	-	1.2	-	-	us
T_{HIGH}	SCL clock HIGH period	-	0.6	-	-	us
$T_{SU;DATA}$	data set-up time	-	250	-	-	ns
$T_{HD;DATA}$	data hold time	-	0	-	0.9	us
T_r	SCL and SDA rise time	Note 2	$20+0.1C_b$	-	300	ns
T_f	SCL and SDA fall time	Note 2	$20+0.1C_b$	-	300	ns
T_f	SDA fall time for read out	-	$20+0.1C_b$	-	1000	ns
C_b	Capacitive load represented by each bus line	-	-	-	400	pF
$T_{SU;STA}$	Setup time for a repeated START condition	-	0.6	-	-	us
$T_{HD;STA}$	START condition hold time	-	0.6	-	-	us
$T_{SU;STO}$	Setup time for STOP condition	-	0.6	-	-	us
T_{SW}	Tolerable spike width on bus	Note 1	-	-	50	ns
T_{BUF}	BUS free time between a STOP and START condition	-	4.7	-	-	us

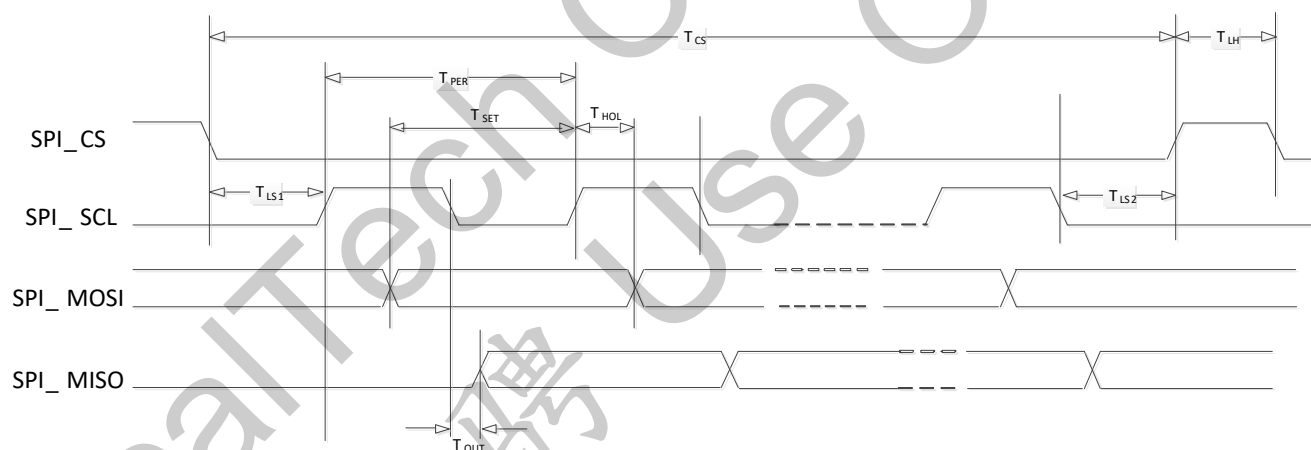
Note1: The device inputs SDA and SCL are filtered and will reject spikes on the bus lines of width $< t_{SW(max)}$.

Note2: The rise and fall times specified here refer to the driver device and are part of the general fast I²C-bus specification. C_b = capacitive load per bus line.

Note3: All timing values are valid within the operating supply voltage and ambient temperature ranges and are referenced to V_{IL} and V_{IH} with an input voltage swing of V_{SS} to V_{DDI} .

7.3.3 SPI characteristics

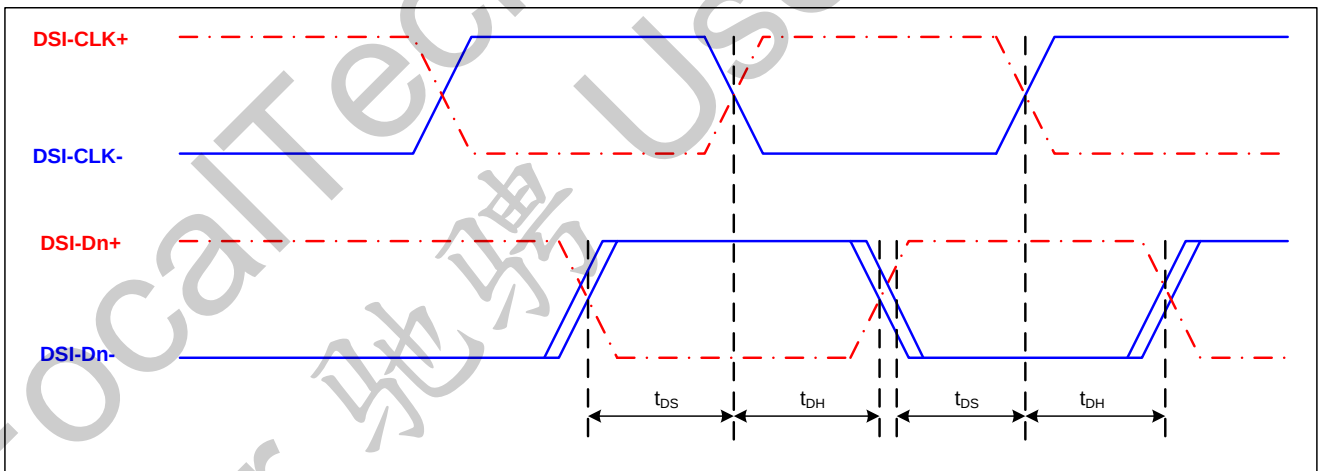
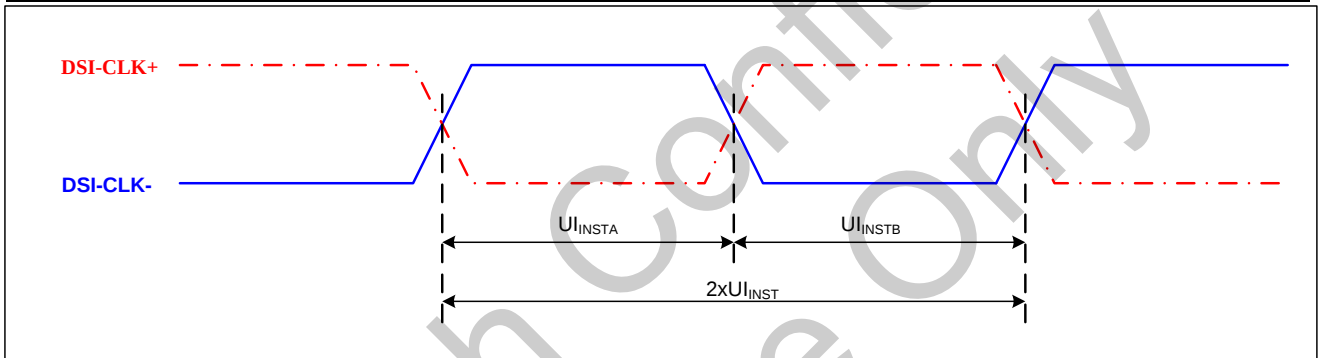
Parameter	Symbol	Conditions	Specification			Unit
			MIN	TYP	MAX	
Terminal : SCL and CS						
Time from CS(10%) to SCL(90%)	TLS1	-	150	-	-	ns
Time from SCL(10%) to CS(90%)	TLS2	-	150	-	-	ns
Terminal : SCL and MOSI						
Data Setup Time : Time from changing MOSI(10%, 90%) to SCL(90%)	TSET	-	10	-	-	ns
Data Hold Time : Time from changing SCL(90%) to MOSI(10%, 90%)	THOL	-	5	-	-	ns
Terminal : SCL and MISO						
Time from SCL(10%) to stable MISO(10%, 90%)	TOUT	100pF,6Ω	-	-	30	ns
Terminal : CS						
Time between SPI cycles, CS at high level (90%)	TLH	-	150	-	-	us
SPI SCL Freq	-	-	-	-	14	MHz



7.3.4 MIPI D-PHY AC characteristics

7.3.4.1 High speed mode

Parameter	Symbol	Parameter	Specification			Unit
			MIN	TYP	MAX	
High Speed Mode						
DSI-CLK+/-	2xUI _{INST}	Double UI instantaneous	1.82	-	25	ns
DSI-CLK+/-	UI _{INSTA} , UI _{INSTB}	UI instantaneous Halfs	0.91	-	12.5	ns
DSI-Dn+/-	t _{DS}	Data to clock setup time	0.15	-	-	UI
DSI-Dn+/-	t _{DH}	Data to clock hold time	0.15	-	-	UI
DSI-CLK+/-	t _{DRTCLK}	Differential rise time for clock	150	-	0.3UI	ps
DSI-Dn+/-	t _{DRTDATA}	Differential rise time for data	150	-	0.3UI	ps
DSI-CLK+/-	t _{DFTCLK}	Differential fall time for clock	150	-	0.3UI	ps
DSI-Dn+/-	t _{DFTDATA}	Differential fall time for data	150	-	0.3UI	ps



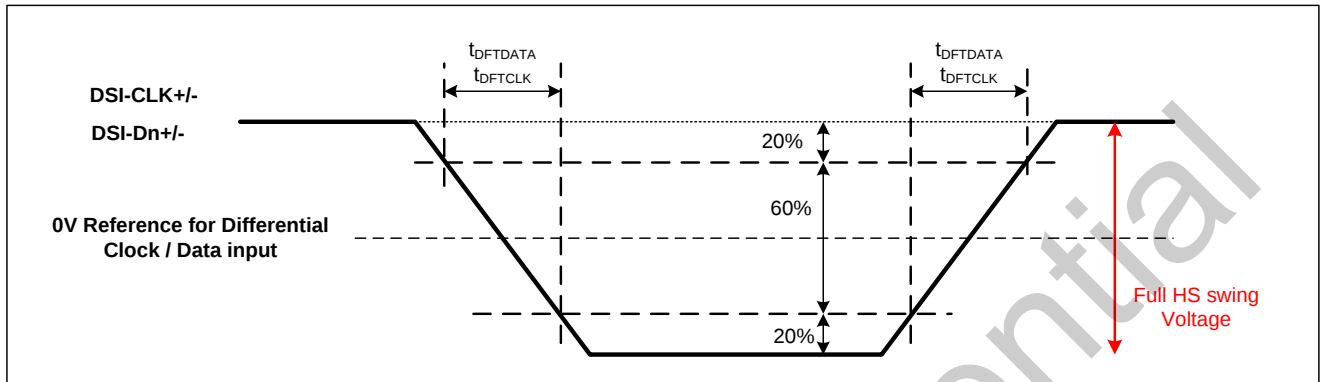


Figure: AC characteristics for MIPI-DSI High speed mode

7.3.4.2 Low power mode

Parameter	Symbol	Parameter	Specification			Unit
			MIN	TYP	MAX	
Low Power mode						
DSI-D0+/-	T _{L_{LPX}-M}	Transmitted length of any Low-Power state period (MCU)	50	-	-	ns
DSI-D0+/-	T _{TA-SURE-M}	The display module waits after the LP-10 before transmitting the LP-00 (MCU)	T _{L_{LPX}-M}	-	2XT _{L_{LPX}-M}	ns
DSI-D0+/-	T _{TA-GET-M}	The display module drives the LP-00 before releasing MCU control	5XT _{L_{LPX}-M}	-	-	ns
DSI-D0+/-	T _{TA-GO-M}	The display drives the LP-00 after accepting control	4XT _{L_{LPX}-M}	-	-	ns
DSI-D0+/-	Ratio T _{L_{LPX}}	Ratio of (T _{L_{LPX}-M} /T _{L_{LPX}-D}) for driving overlap	2/3	-	3/2	-
DSI-D0+/-	T _{L_{LPX}-D}	Transmitted length of any Low-Power state period (Display)	50	58	-	ns
DSI-D0+/-	T _{TA-SURE-D}	The MCU waits after the LP-10 before transmitting the LP-00 (Display)	T _{L_{LPX}-D}	-	2XT _{L_{LPX}-D}	ns
DSI-D0+/-	T _{TA-GET-D}	The MCU drives the LP-00 before releasing Display control	5XT _{L_{LPX}-D}	-	-	ns
DSI-D0+/-	T _{TA-GO-D}	The MCU drives the LP-00 after accepting control	4XT _{L_{LPX}-D}	-	-	ns

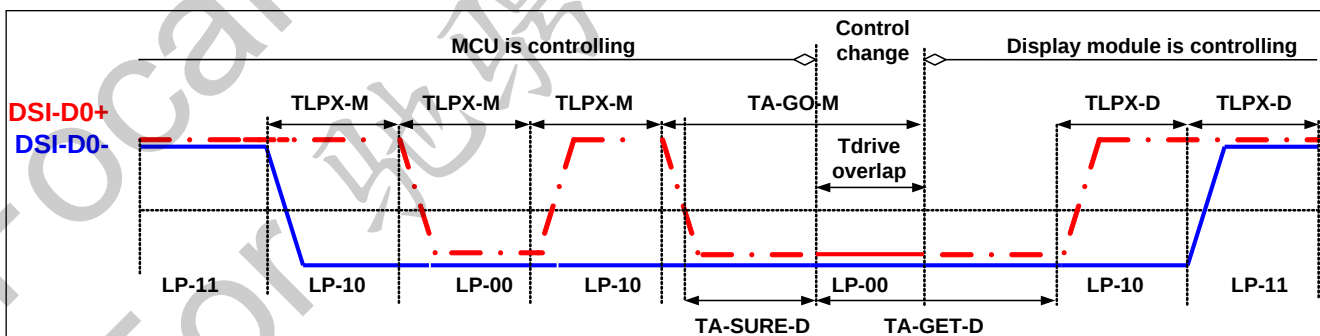


Figure: BTA from the MCU to the Display Module

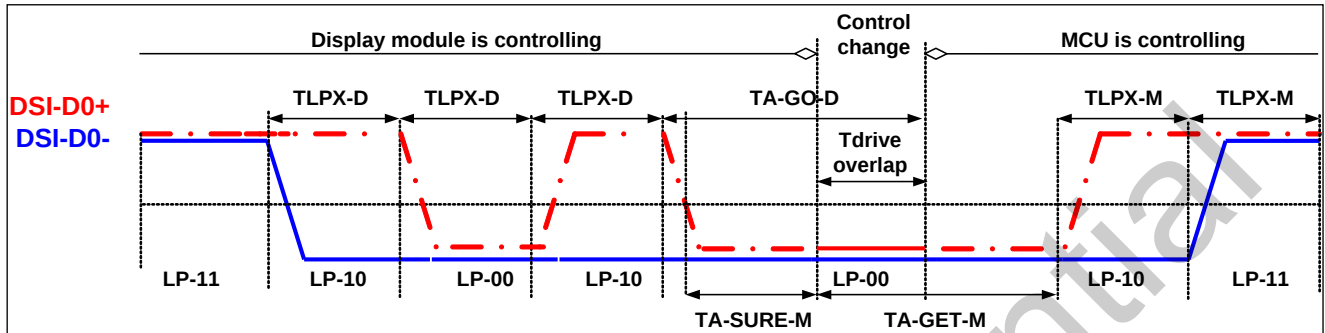


Figure: BTA from the Display Module to the MCU

7.3.4.3 Bursts

Parameter	Symbol	Parameter	Specification			Unit
			MIN	TYP	MAX	
High Speed Data Transmission Bursts						
DSI-Dn+/-	T _{LFX}	Length of any low-power state period	50	-	-	ns
DSI-Dn+/-	T _{HS-PREPARE}	Time to drive LP-00 to prepare for HS transmission	40ns + 4UI	-	85ns + 6UI	ns
DSI-Dn+/-	T _{HS-PREPARE} + T _{HS-ZERO}	T _{HS-PREPARE} + time to drive HS-0 before the sync sequence	145ns + 10UI	-	-	ns
DSI-Dn+/-	T _{D-TERM-EN}	Time to enable Data Lane receiver line termination measured from when Dn crosses V _{IL(max)}	Time for Dn to reach V _{TERM-EN}	-	35ns + 4UI	ns
DSI-Dn+/-	T _{HS-SKIP}	Time-out at RX to ignore transition period of EoT	40	-	55ns + 4UI	ns
DSI-Dn+/-	T _{HS-TRAIL}	Time to drive flipped differential state after last payload data bit of a HS transmission burst	max (8UI, 60ns+4UI)	-	-	ns
DSI-Dn+/-	T _{HS-EXIT}	Time to drive LP-11 after HS burst	100	-	-	ns
DSI-Dn+/-	T _{EoT}	Time from start of T _{HS-TRAIL} period to start of LP-11 state	-	-	105ns + 12UI	ns

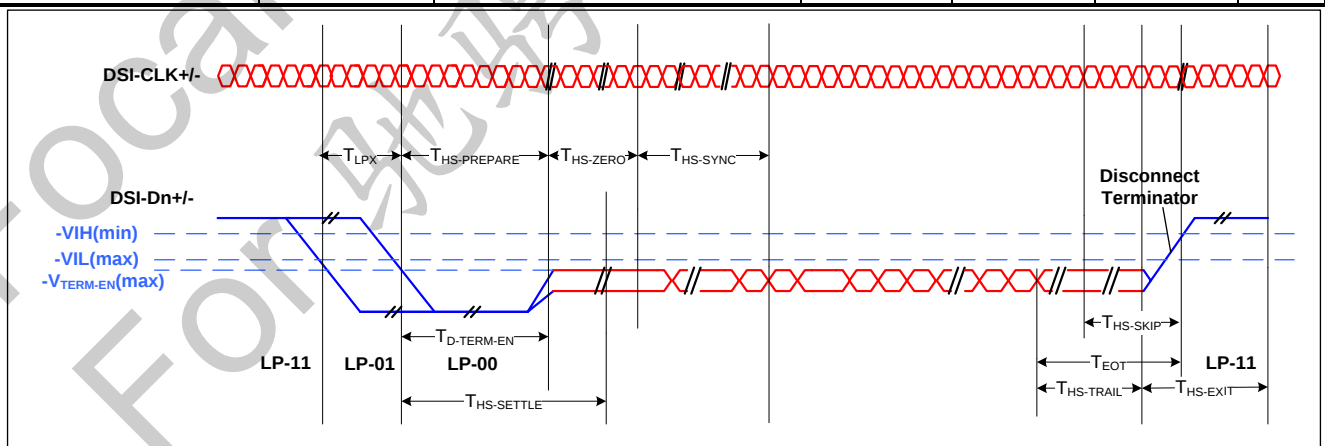


Figure: High Speed Data Transmission Bursts

Parameter	Symbol	Parameter	Specification			Unit
			MIN	TYP	MAX	
Switching the clock Lane between clock Transmission and Low Power Mode						
DSI-CLK+/-	T _{CLK-POST}	Time that the transmitter shall continue sending HS clock after the last associated Data Lane has transitioned to LP mode	60ns + 52UI	-	-	ns
DSI-CLK+/-	T _{CLK-PRE}	Time that the HS clock shall be driven prior to any associated Data Lane beginning the transition from LP to HS mode	8	-	-	UI
DSI-CLK+/-	T _{CLK-PREPARE}	Time to drive LP-00 to prepare for HS clock transmission	38	-	95	ns
DSI-CLK+/-	T _{CLK-TERM-EN}	Time to enable Clock Lane receiver line termination measured from when Dn crosses V _{IL(max)}	Time for Dn to reach V _{TERM-EN}	-	38	ns
DSI-CLK+/-	T _{CLK-PREPARE} + T _{CLK-ZERO}	T _{CLK-PREPARE} + time for lead HS-0 drive period before starting Clock	300	-	-	ns
DSI-CLK+/-	T _{CLK-TRAIL}	Time to drive HS differential state after last payload clock bit of a HS transmission burst	60	-	-	ns
DSI-CLK+/-	T _{EoT}	Time from start of T _{CLK-TRAIL} period to start of LP-11 state	-	-	105ns + 12UI	ns

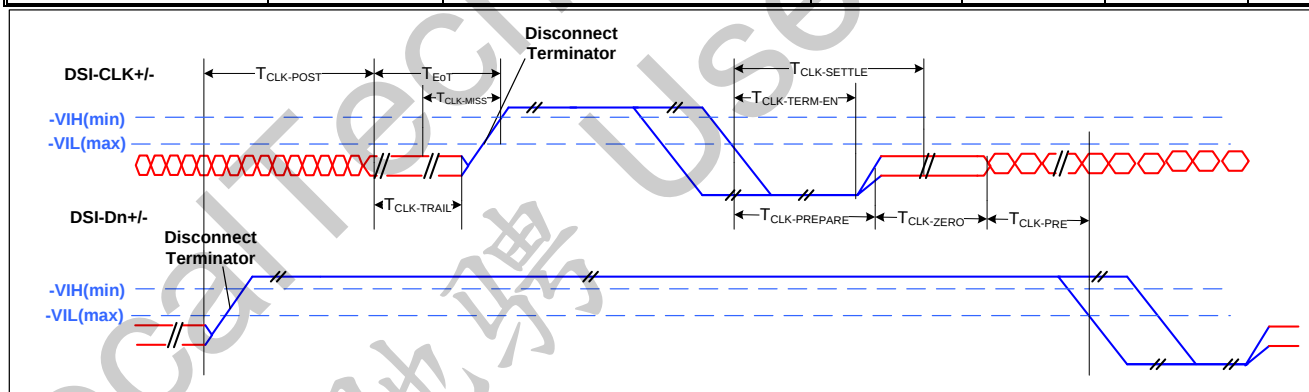


Figure: Switching the clock Lane between clock Transmission and Low Power Mode

7.3.4.4 LP-11 between High Speed and Low Power Modes

DSI-D0 High Speed or Low Power modes are starting or finishing from/to Stop State (SS, LP-11) when 4 different combinations, what are listed below, are possible:

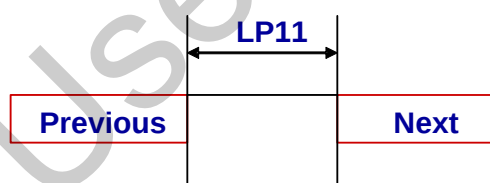
1. High Speed Mode => Stop State (SS, LP-11) => High Speed Mode
2. High Speed Mode => Stop State (SS, LP-11) => Low Power Mode
3. Low Power Mode => Stop State (SS, LP-11) => High Speed Mode
4. Low Power Mode => Stop State (SS, LP-11) => Low Power Mode

The Low Power Mode is also including 2 different functions:

1. Escape
2. Bus Turnaround (BTA)

Stop State (SS, LP-11) Timings from Previous mode to Next mode

Next Previous	Escape mode		HSDT		BTA	
	Min	Max	Min	Max	Min	Max
Escape mode	100 ns	-	100 ns	-	100 ns	-
HSDT	60ns + 52UI	-	60ns + 52UI	-	60ns + 52UI	-
BTA	100 ns	-	100 ns	-	100 ns	-



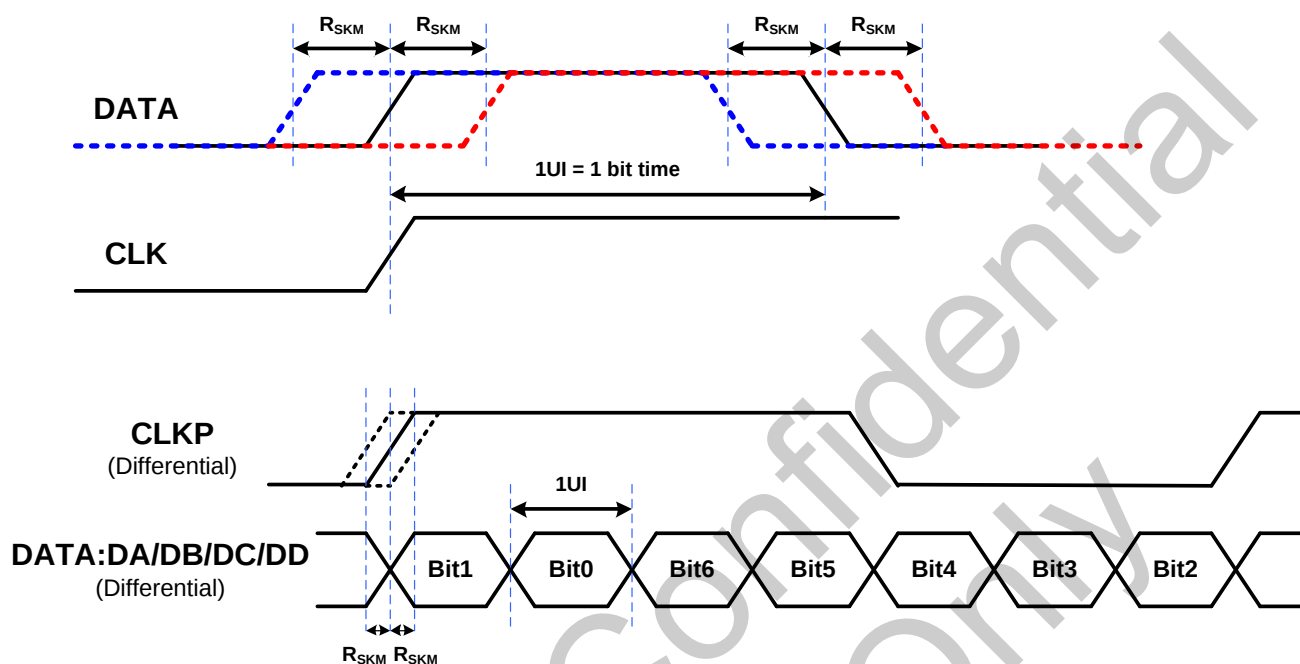
7.3.5 LVDS AC timing characteristics

Parameter	Symbol	Conditions	Spec.			Unit
			Min	Typ	Max	
Input data skew margin	RSKM (1)	FLVDS = 110MHz VID = 200mV VCM_RX = 1.2v	-	-	0.2	UI
Clock high time	TLVCH (2)	-	-	4/(7*FLVDS)	-	nS
Clock low time	TLVCL (2)	-	-	3/(7*FLVDS)	-	nS
PLL wake-up time	TPLLwkup (3)	-	-	-	150	μS
Sync skew margin between point to point	T _{SYNCSKEW} (4)	-	-	-	7	UI
Modulation Frequency	SSCMF (5)	FLVDS = 110 MHz	20	-	200	KHz
Modulation Rate	SSCMR (5)	FLVDS = 110 MHz	-5	-	+5	%

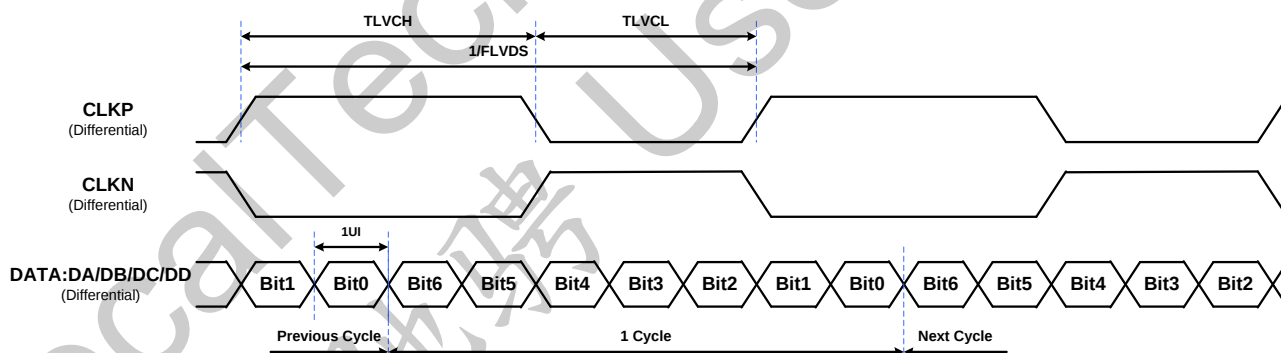
NOTE1 : FLVDS = 15 MHz ~ 110 MHz (including SSC operation)

NOTE2 : Support DE mode H-blanking maximum +/- 16 clks jitter range

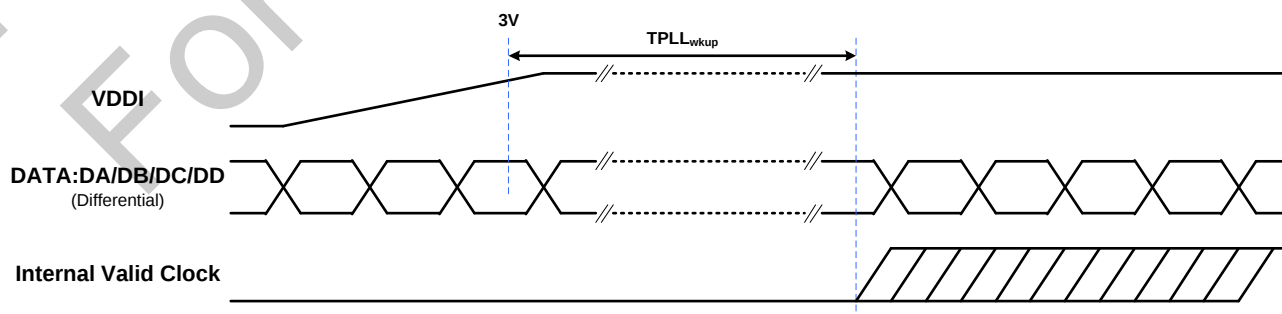
(1)



(2)

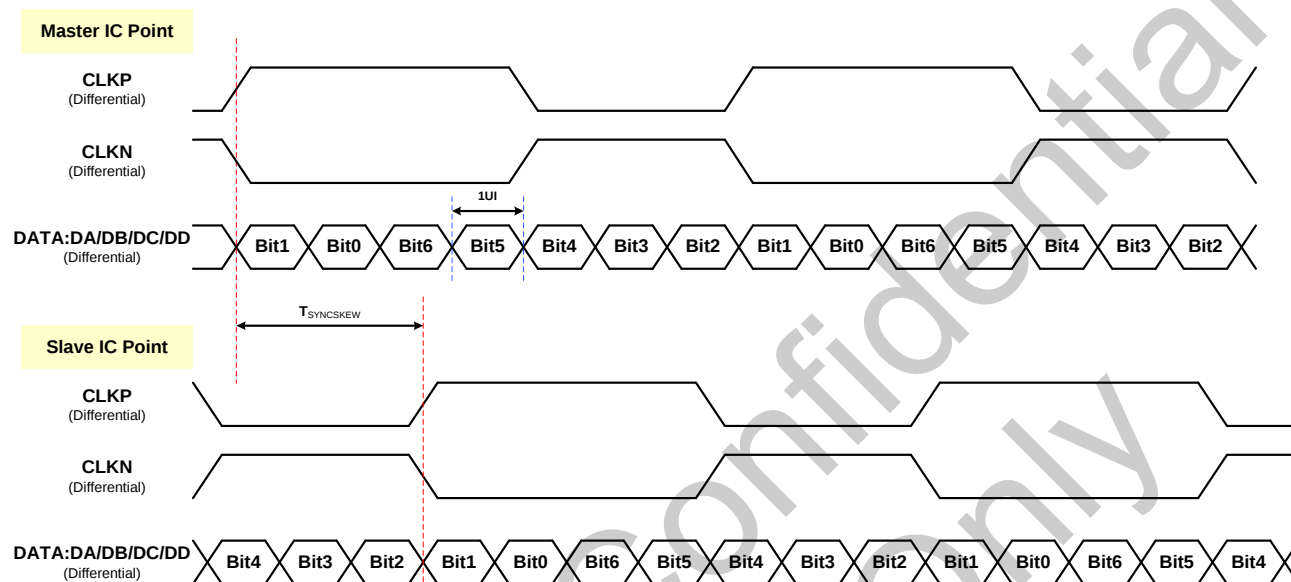


(3)

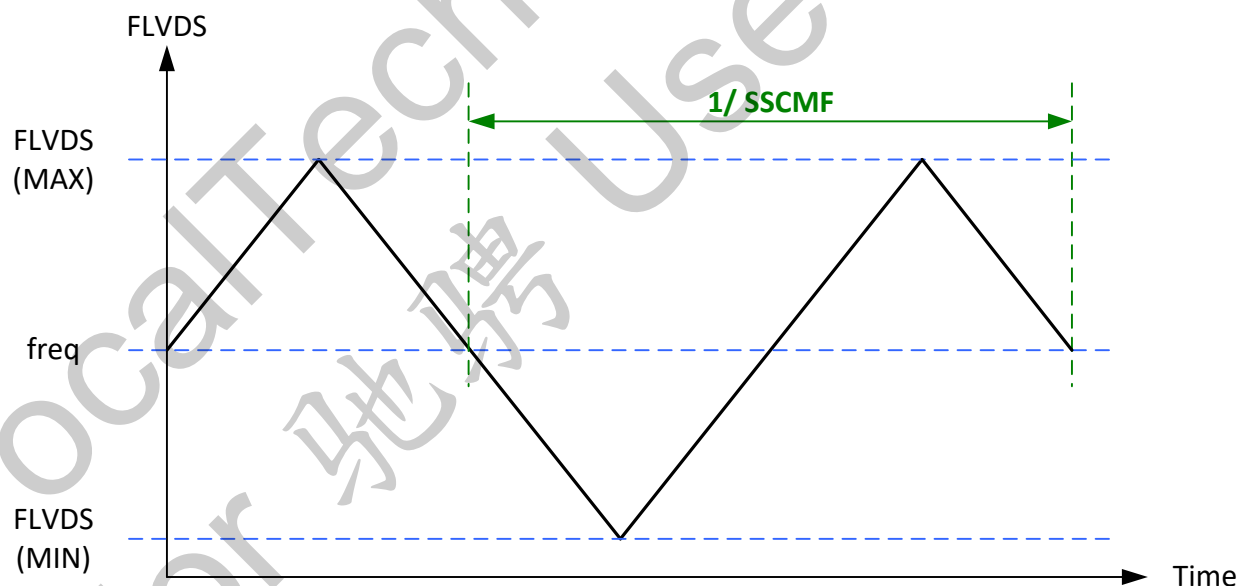


(4) LVDS point to point architecture

T_{SYNCSKEW} must smaller than 7 UIs (1 CLKP/N) between ICs.



(5)



- ※1 : $FLVDS = freq * (1 + SSCMR)$
- ※2 : $FLVDS (MAX) \leq 110MHz$

7.3.6 Power On/Off Sequence

During power on, if LCD is in Sleep Out mode, VDDI must be powered down minimum 120 ms after RESX has been released.

During power off, if LCD is in Sleep In mode, VDDI can be powered down minimum 0 ms after RESX has been released.

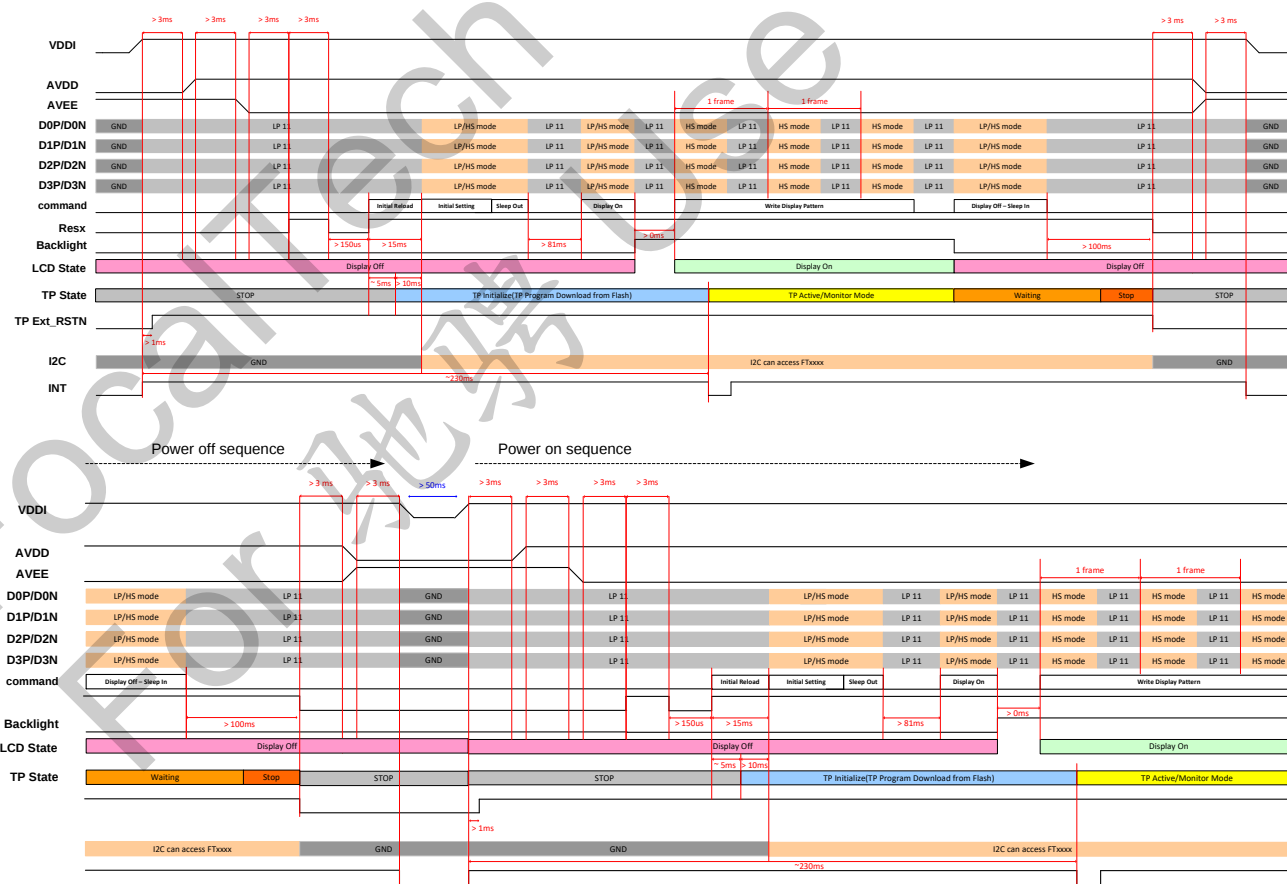
CSX can be applied at any timing or can be permanently grounded. RESX has higher priority than CSX.

Notes:

- 1). There will be no damage to the display module if the power sequences are not met.
- 2). There will be no abnormal visible effects on the display panel during the Power On/Off sequences.
- 3). There will be no abnormal visible effects on the display between end of Power On sequence and before receiving Sleep Out command.
Also between receiving Sleep In command and Power Off sequence.
- 4). If RESX line is not held stable by host during Power On Sequence, then it will be necessary to apply a hardware reset (RESX) after host Power On sequence is complete to ensure correct operation. Otherwise function is not guaranteed.
- 5). There is not a limit for Rise/Fall time on VDDI
- 6). The display module can also initialize and calibrate DSI-CLK +/- and DSI-D0 +/- lanes within 5ms after LP-11 (Clock and Data Channels), VDDI are applied and H/W Reset is not active (5ms is as same as the Reset Cancelling Time).

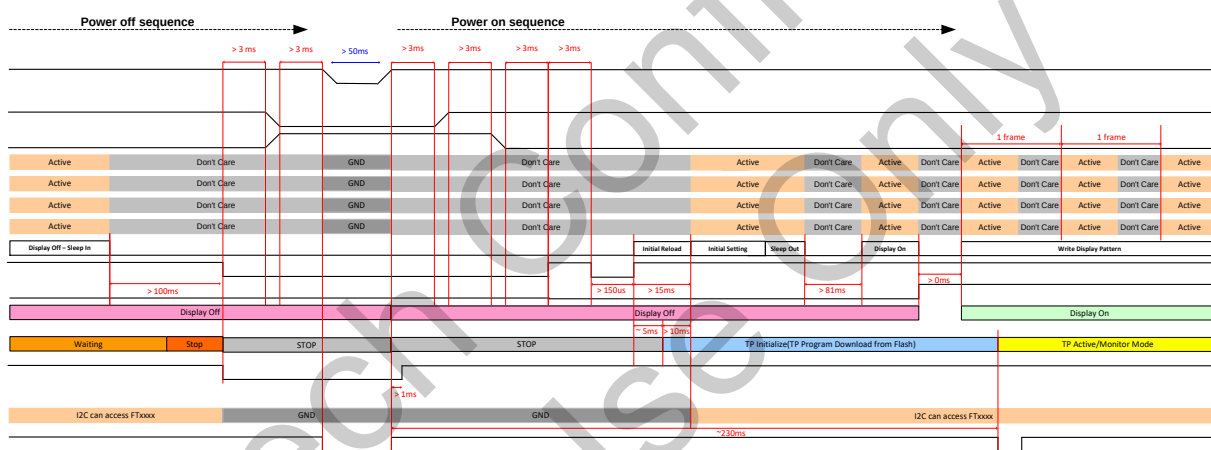
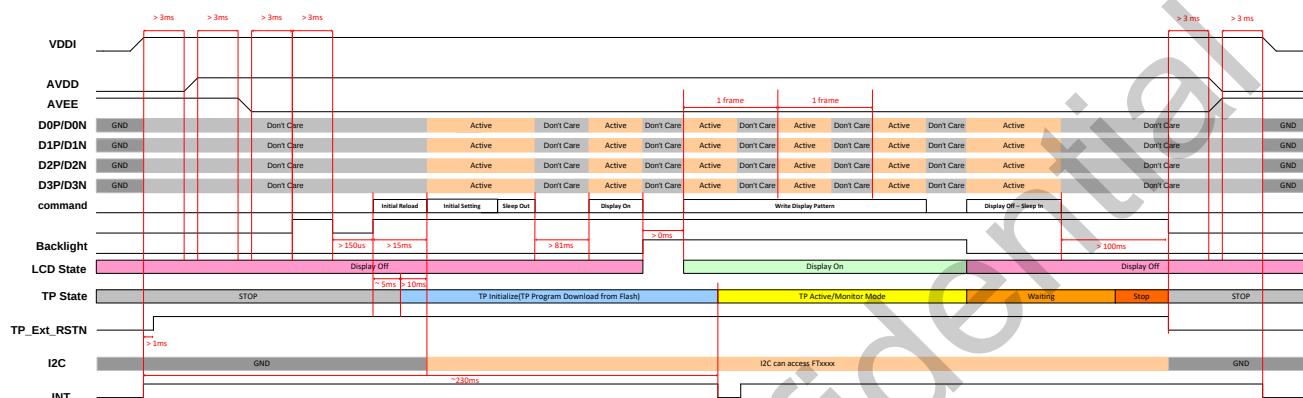
w/i Flash (3 Power mode) (MIPI)

3 Power mode Power on/off sequence

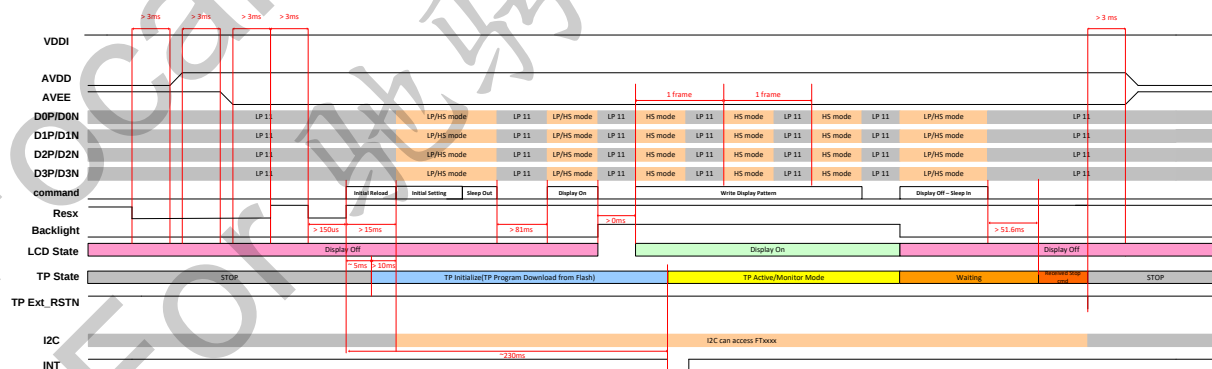


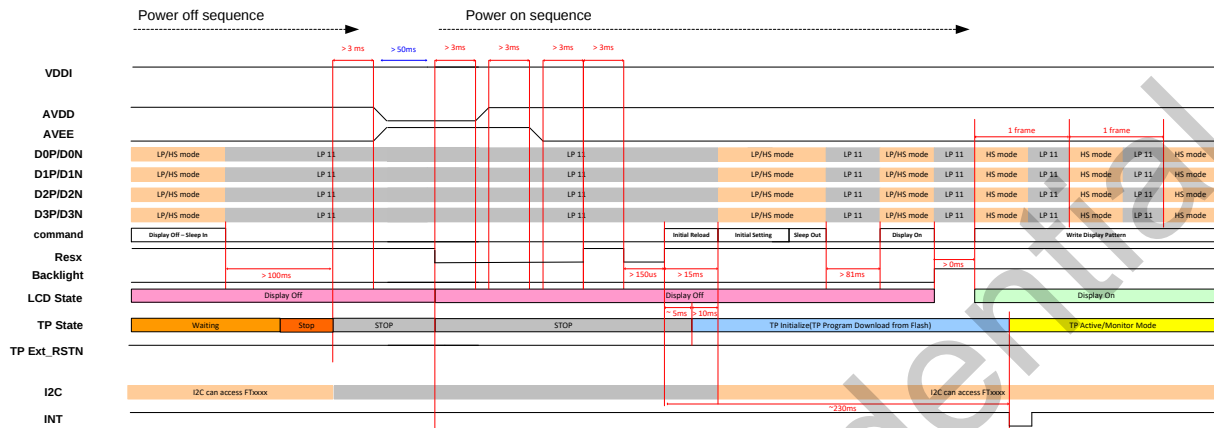
w/i Flash (3 Power mode) (LVDS)

3 Power mode Power on/off sequence

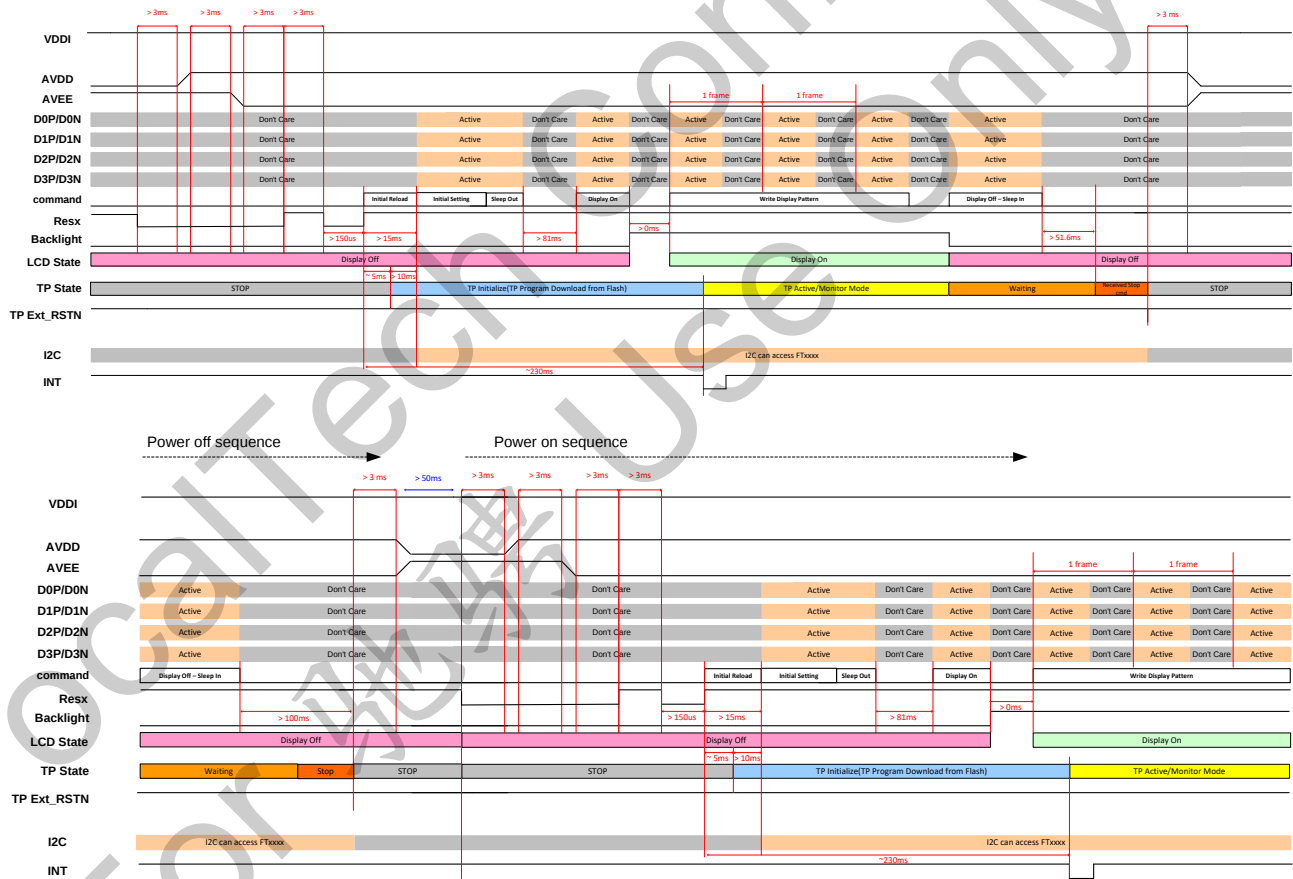


3 Power mode Power on/off sequence(VDDI keep) (MIPI)



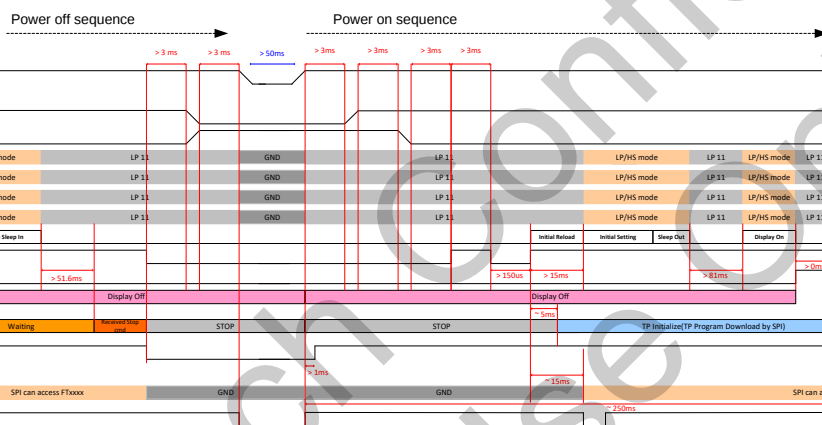
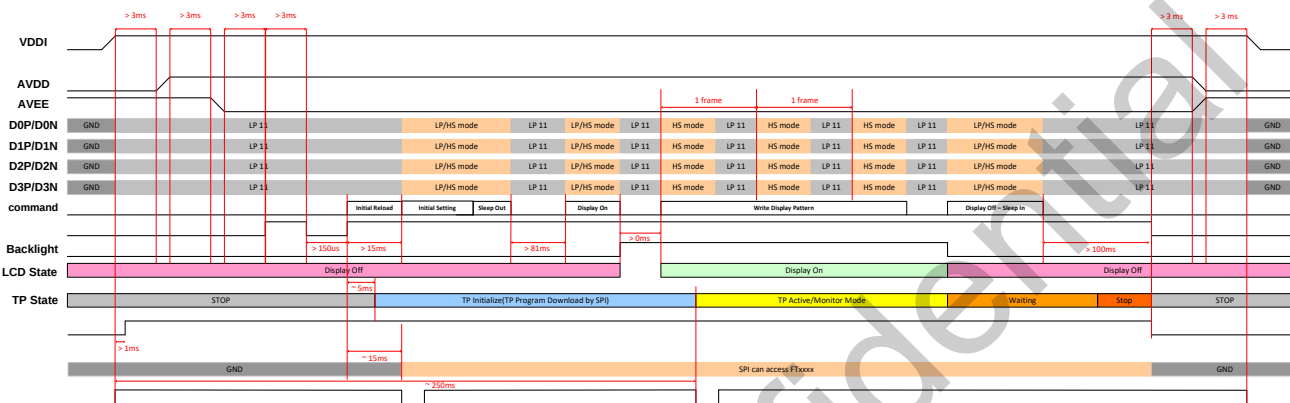


3 Power mode Power on/off sequence(VDDI keep)(LVDS)



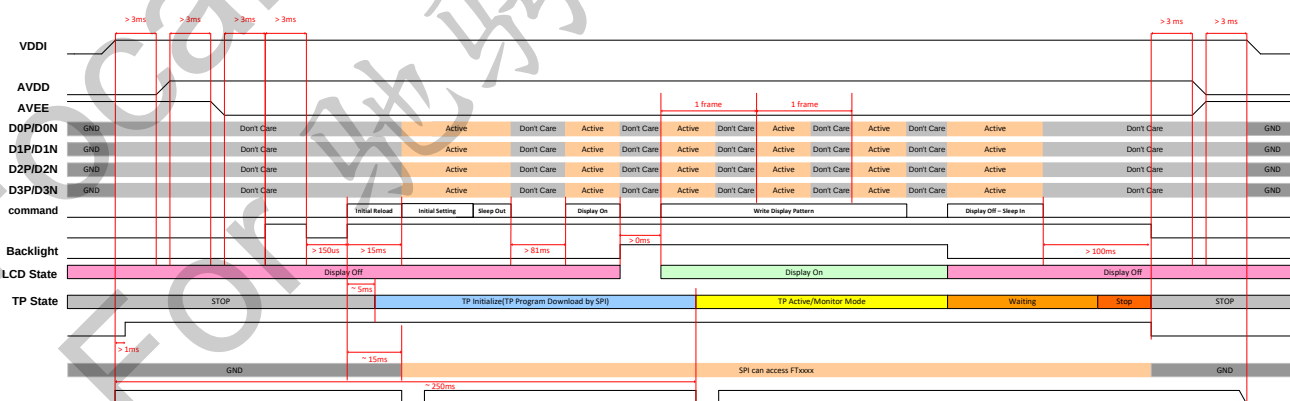
w/o Flash (3 Power mode) (MIPI)

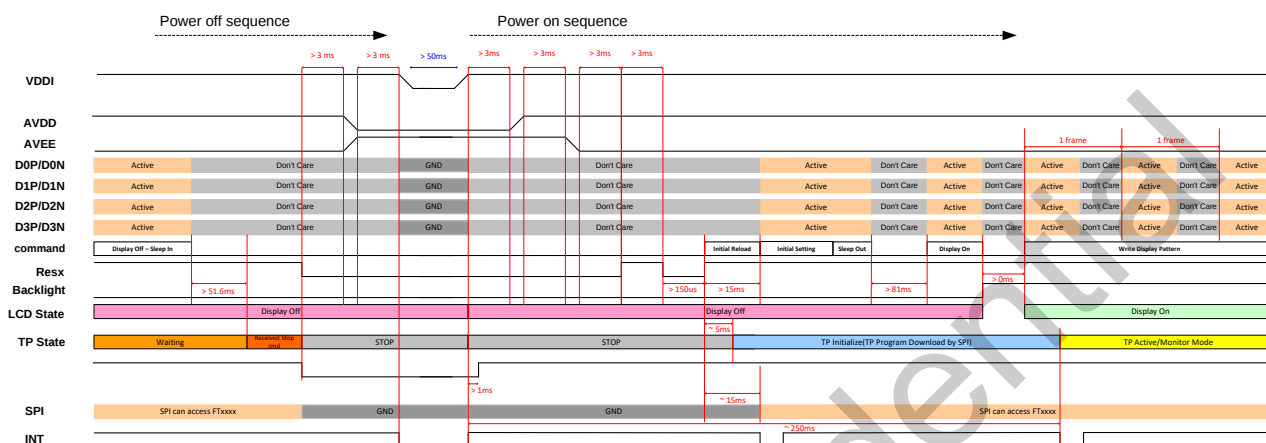
3 Power mode Power on/off sequence



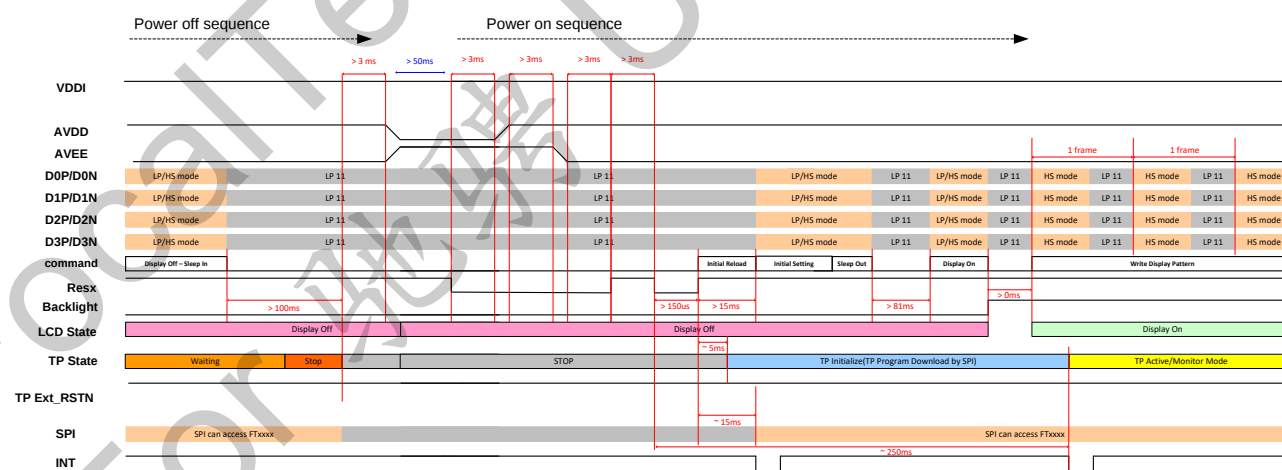
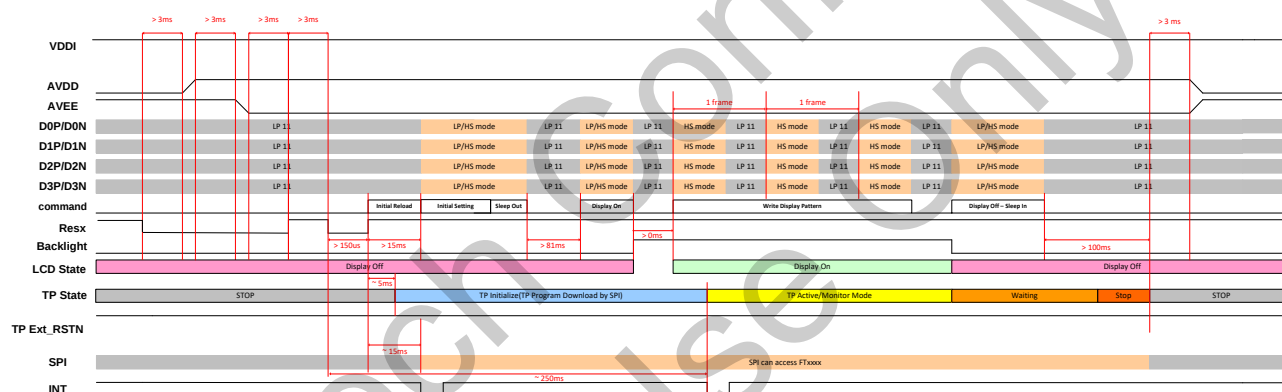
w/o Flash (3 Power mode) (LVDS)

3 Power mode Power on/off sequence

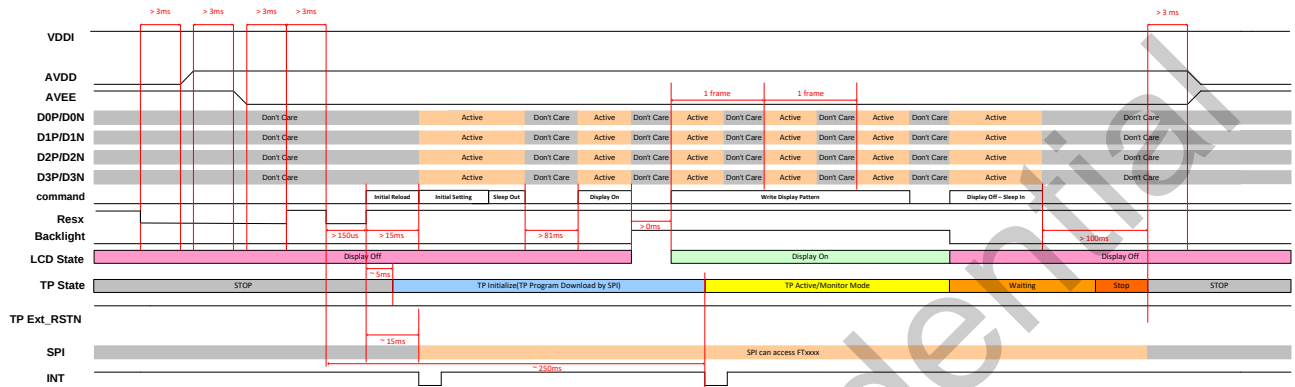




3 Power mode Power on/off sequence(VDDI keep) (MIPI)

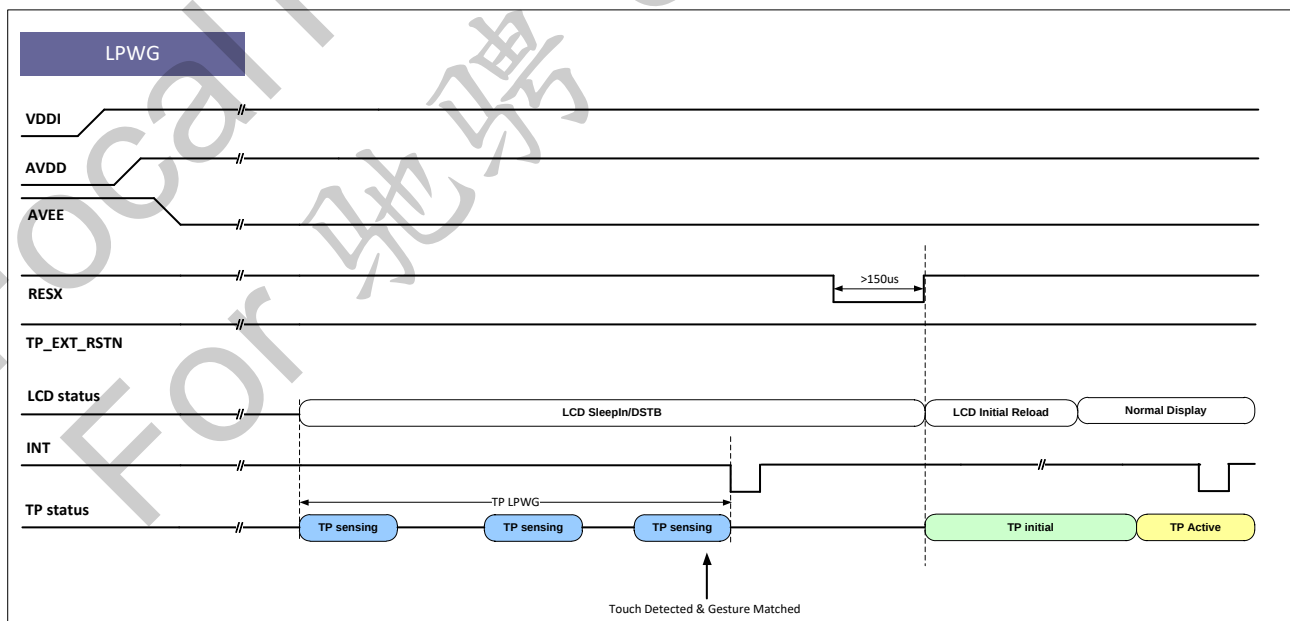
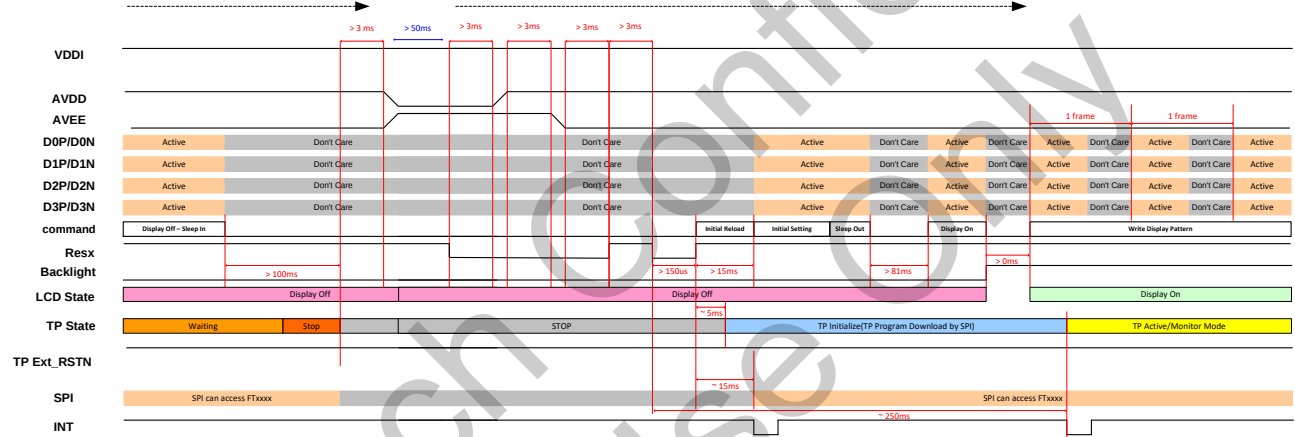


3 Power mode Power on/off sequence(VDDI keep) (LVDS)

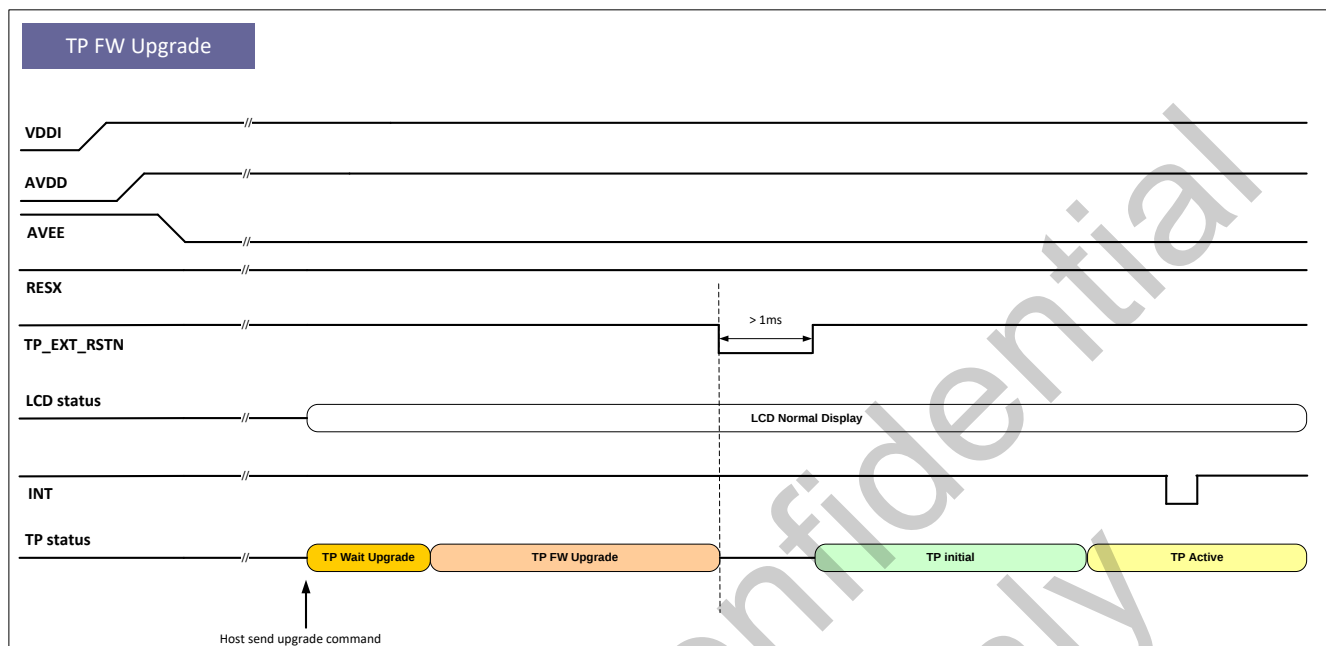


Power off sequence

Power on sequence



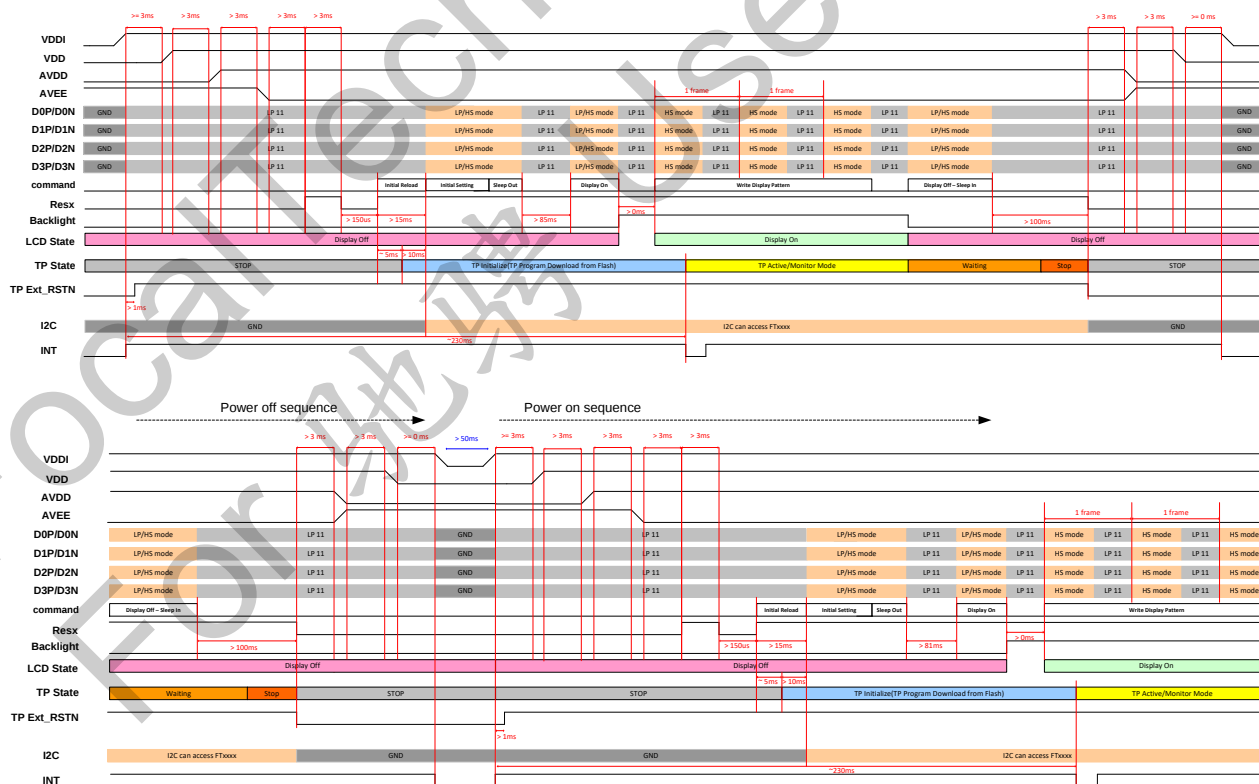
3 Power mode LPWG sequence



3 Power mode TP FW Upgrade

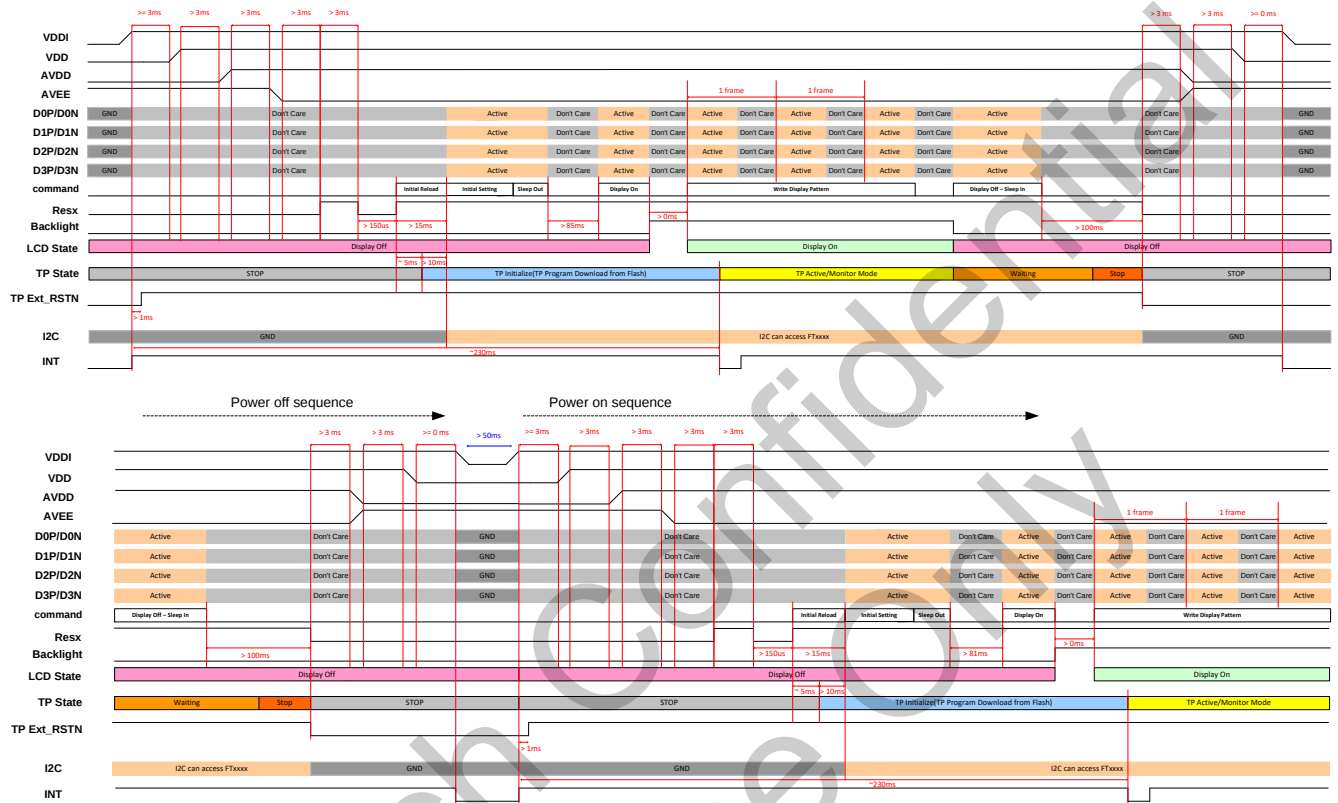
w/i Flash (4 Power mode) (MIPI)

4 Power mode Power on/off sequence

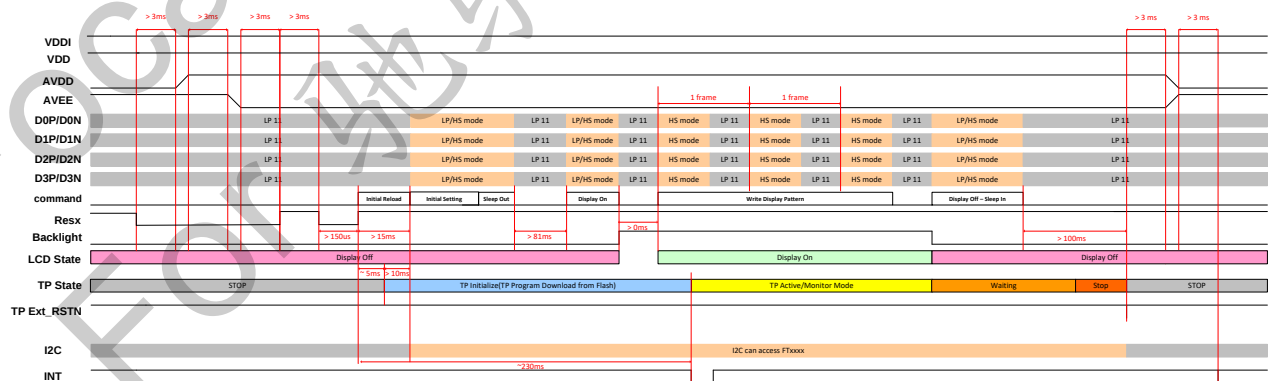


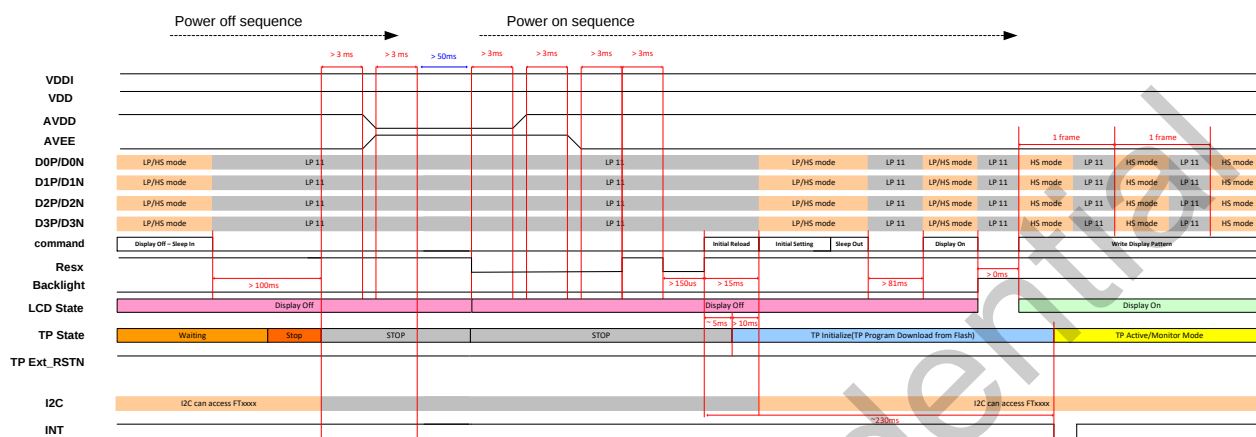
w/i Flash (4 Power mode) (LVDS)

4 Power mode Power on/off sequence

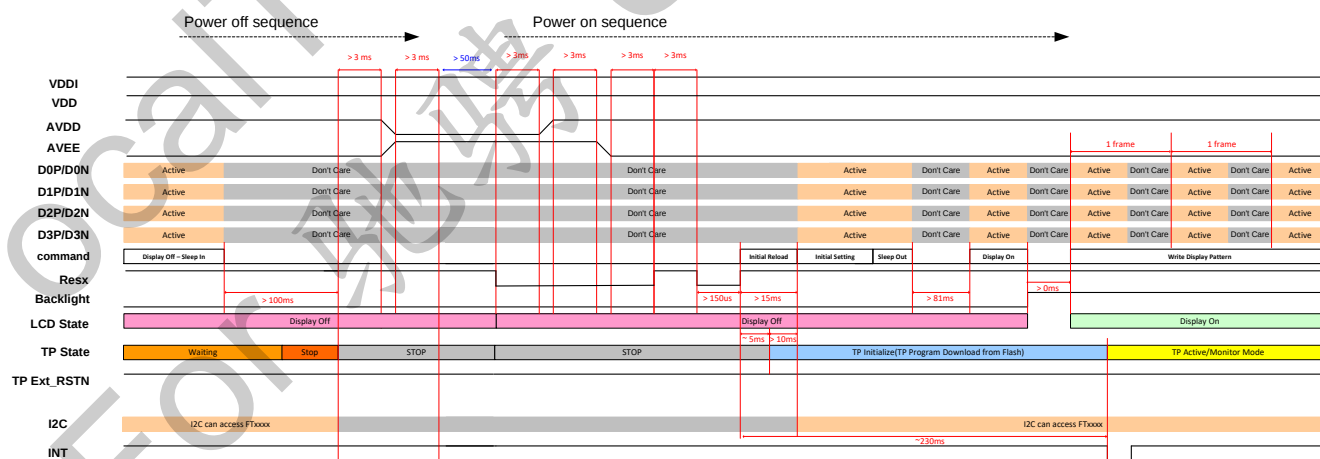
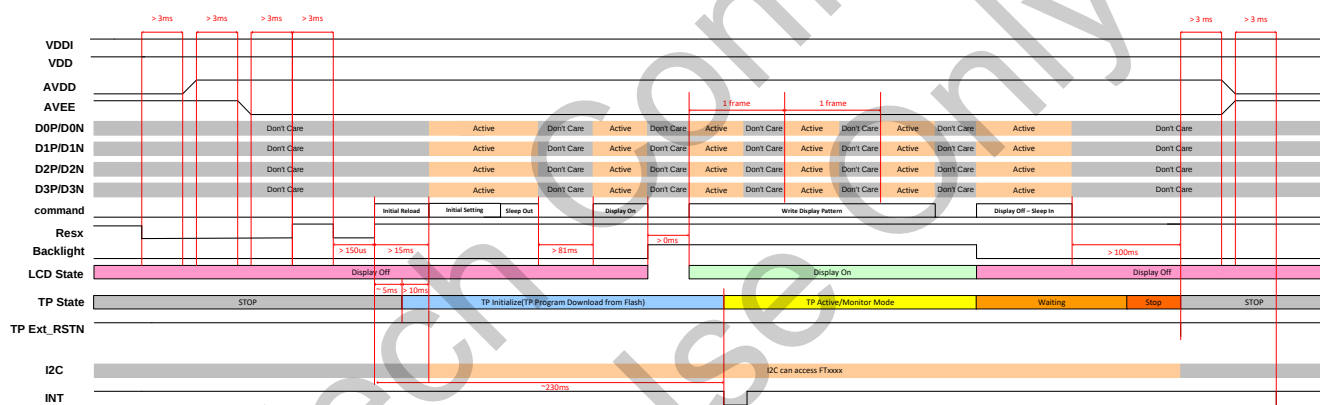


4 Power mode Power on/off sequence(VDDI/VDD keep) (MIPI)



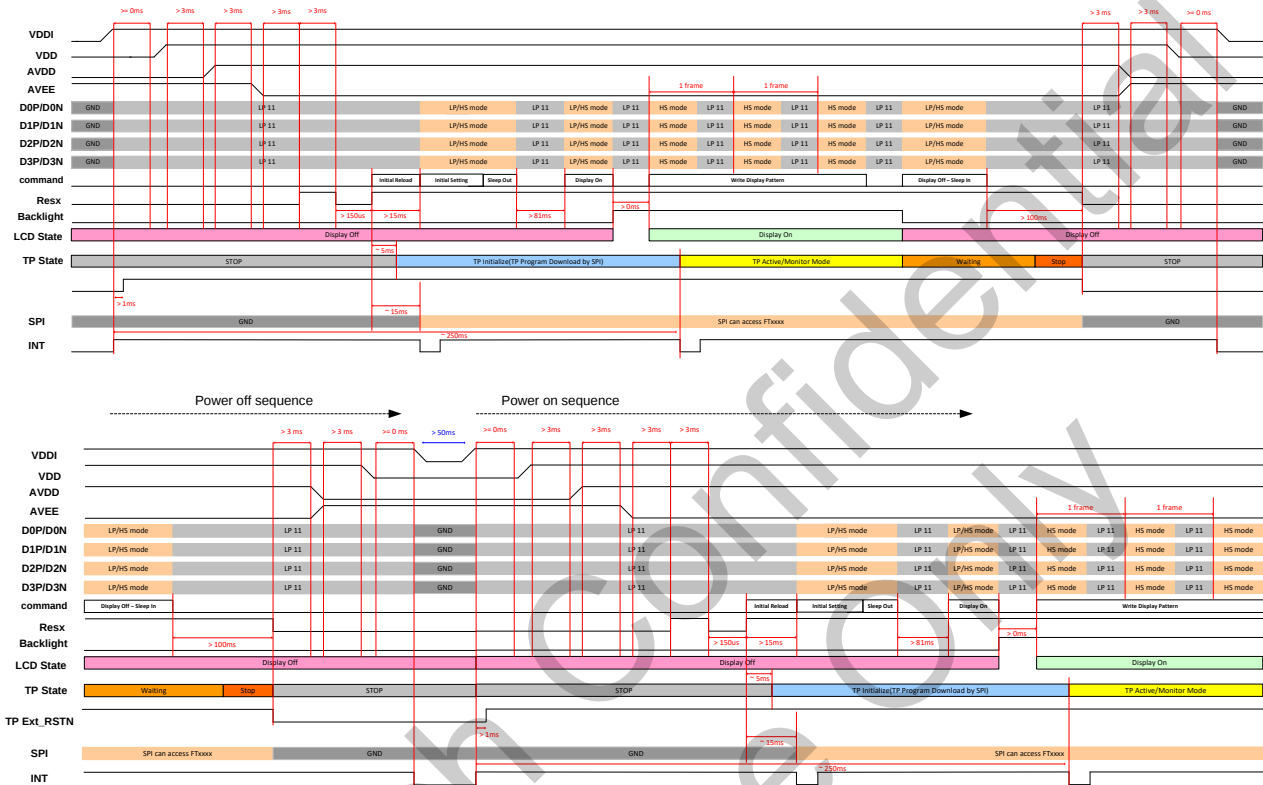


4 Power mode Power on/off sequence(VDDI/VDD keep) (LVDS)



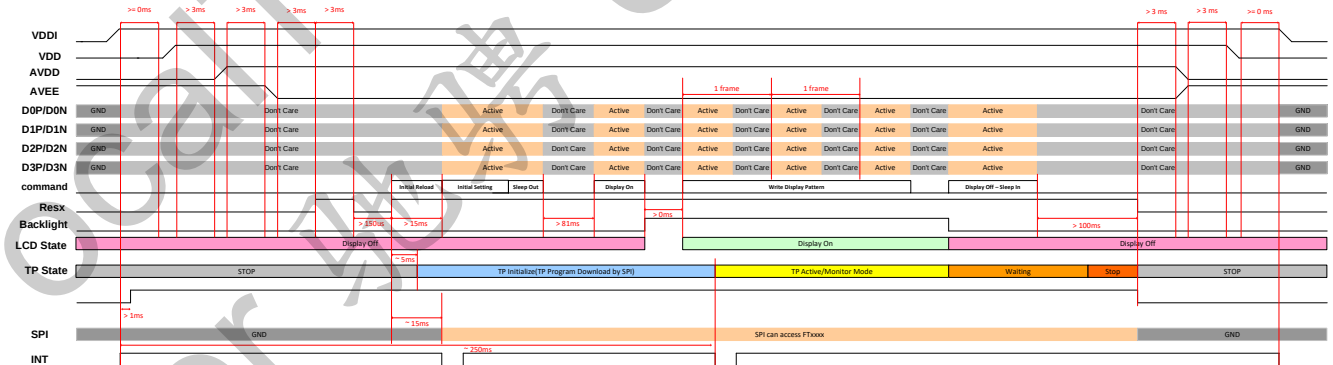
w/o Flash (4 Power mode) (MIPI)

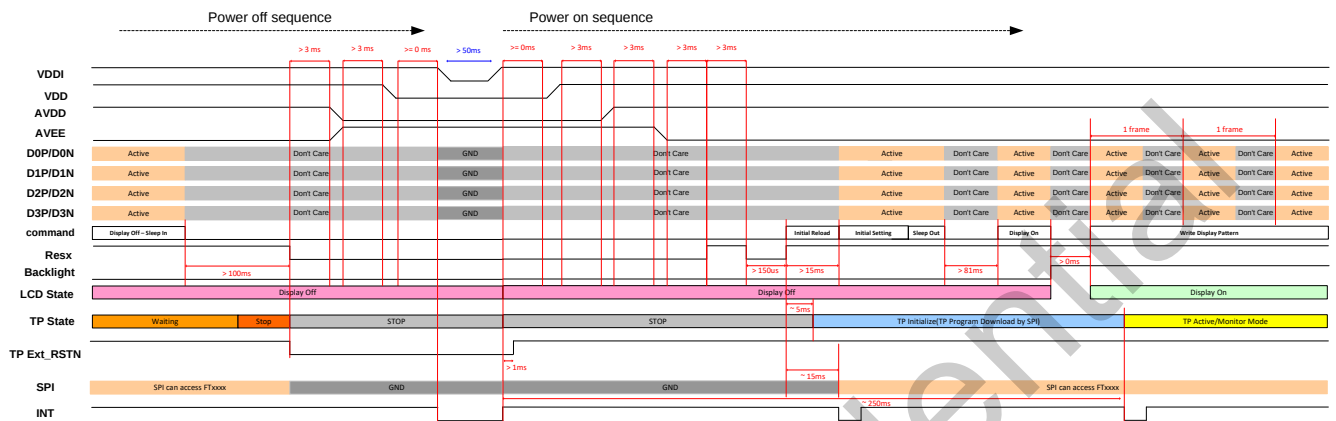
4 Power mode Power on/off sequence



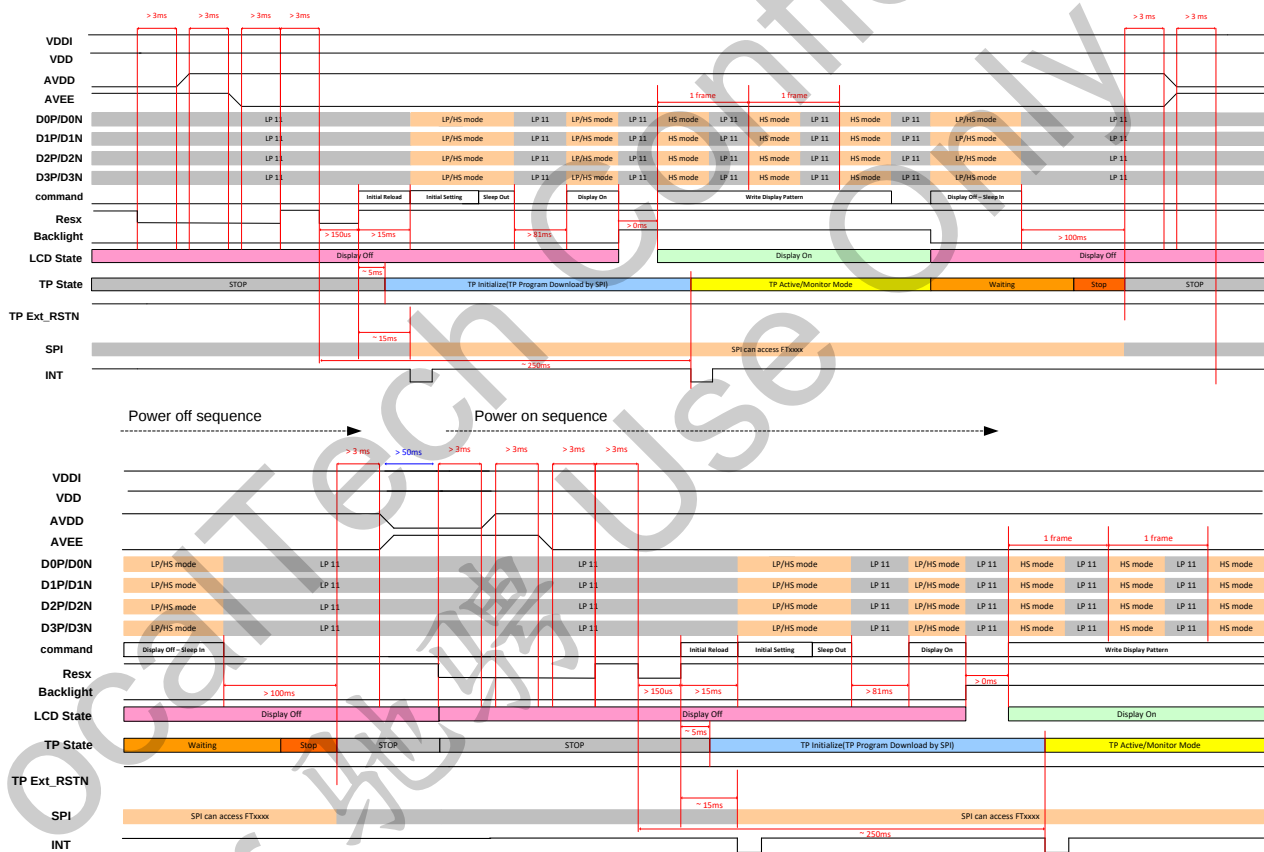
w/o Flash (4 Power mode) (LVDS)

4 Power mode Power on/off sequence

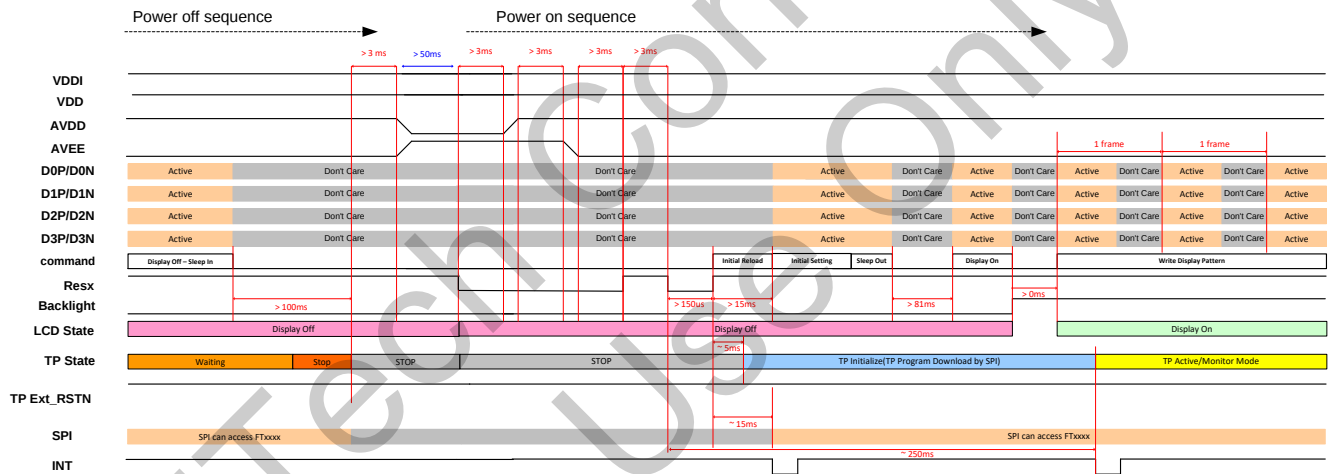
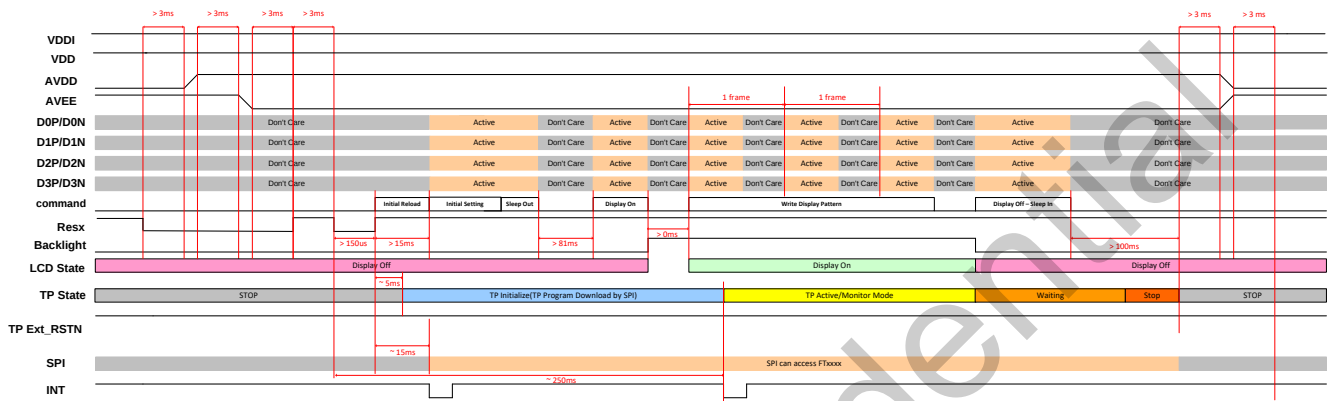


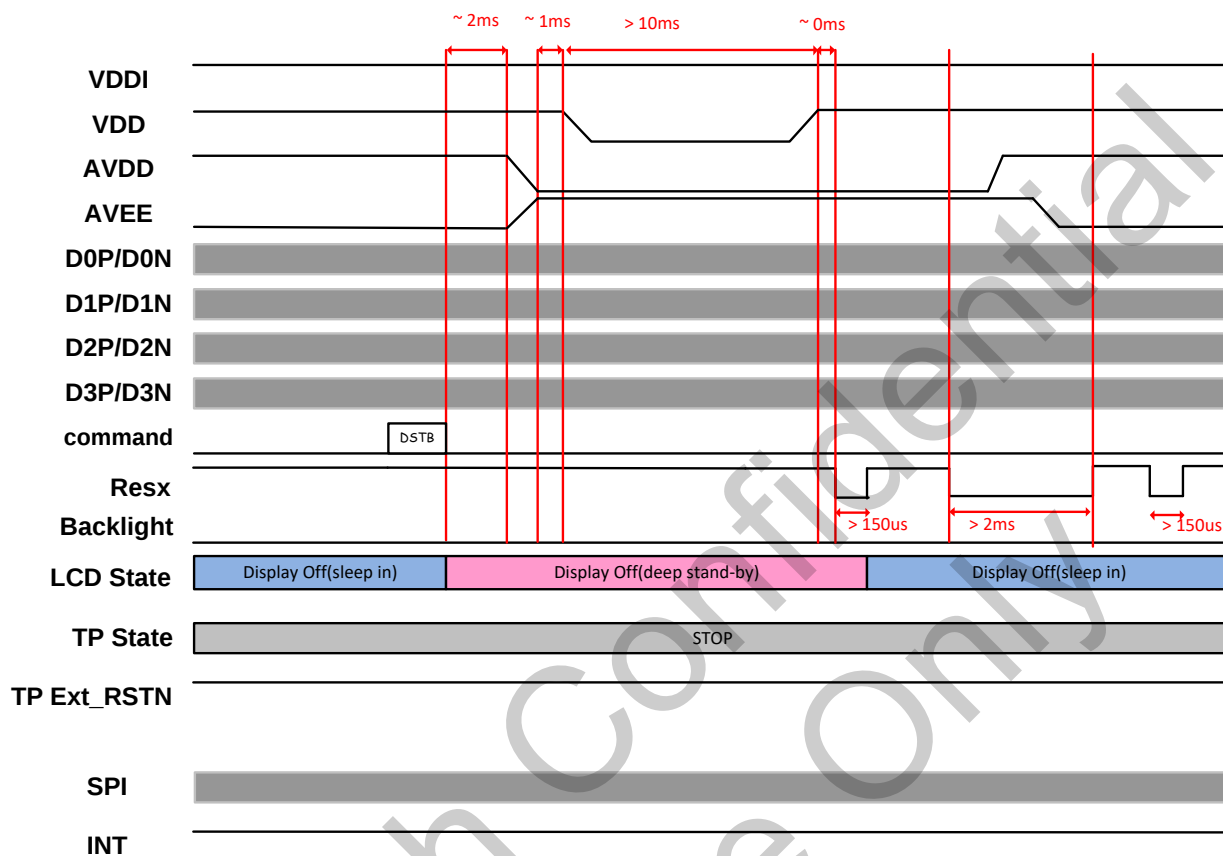


4 Power mode Power on/off sequence(VDDI/VDD keep) (MIPI)

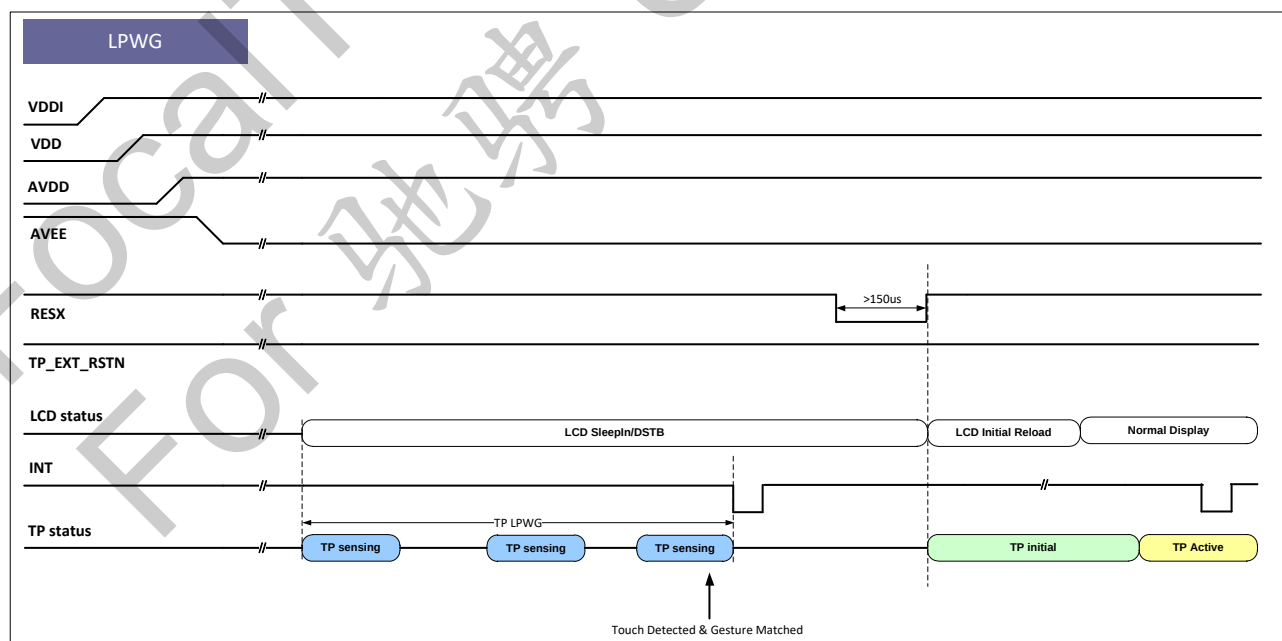


4 Power mode Power on/off sequence(VDDI/VDD keep) (LVDS)

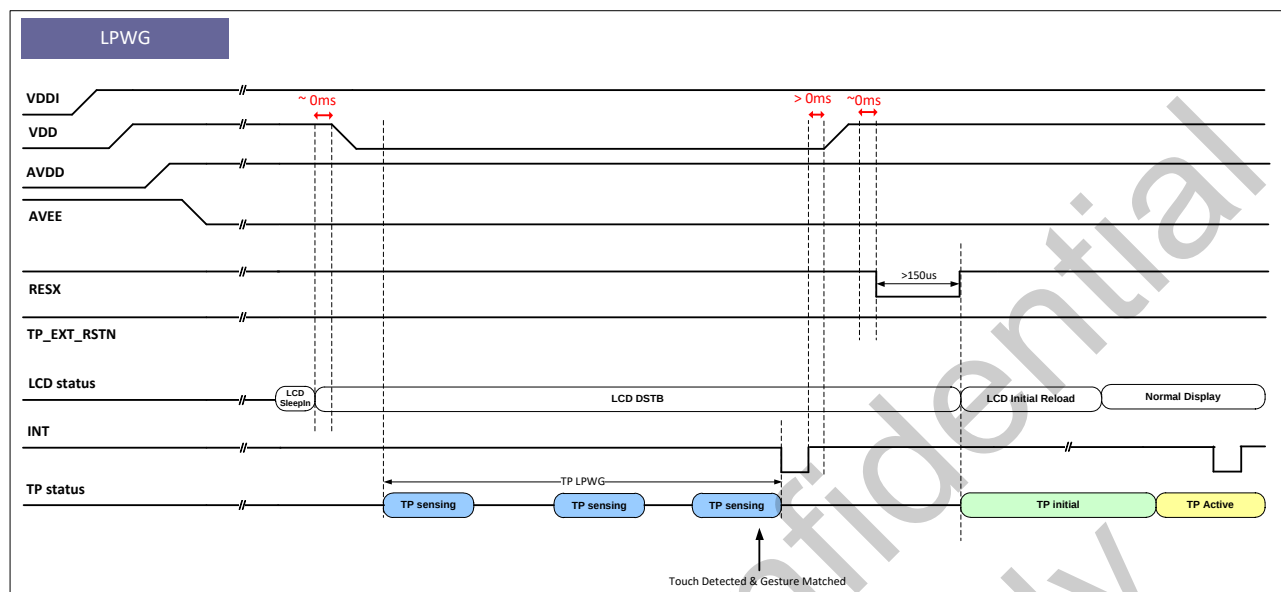




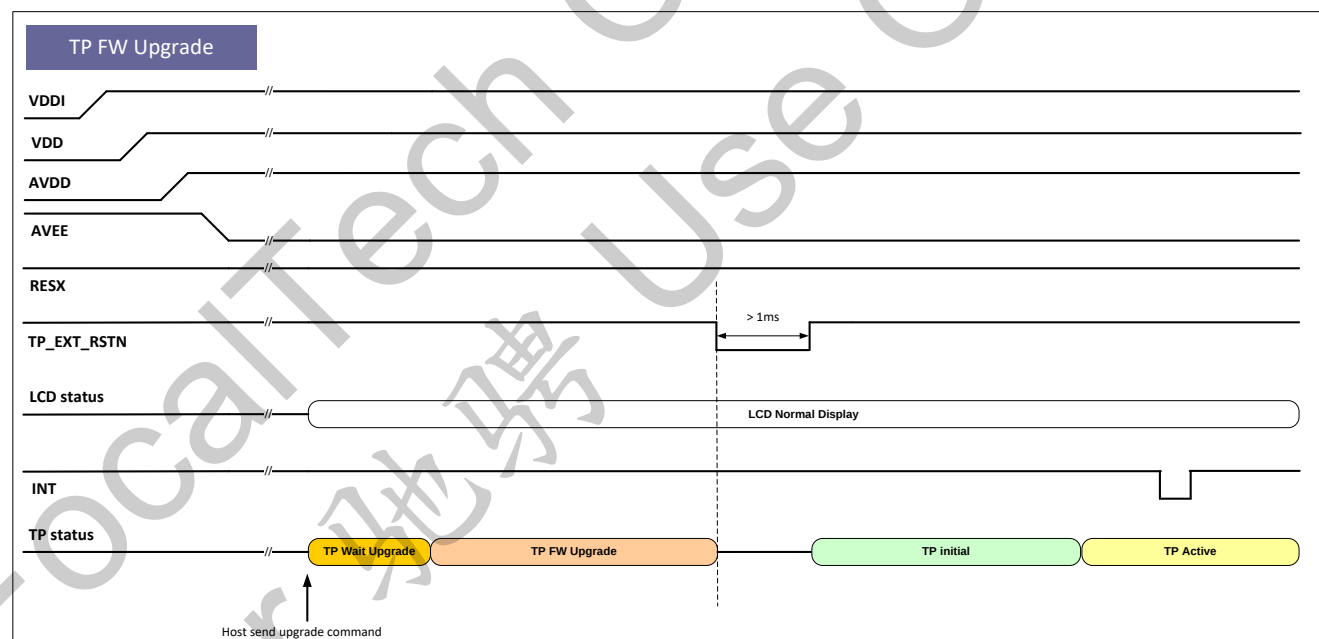
4 Power mode Power on/off sequence(Only VDDI keep)



4 Power mode LPWG sequence(VDD is exist)



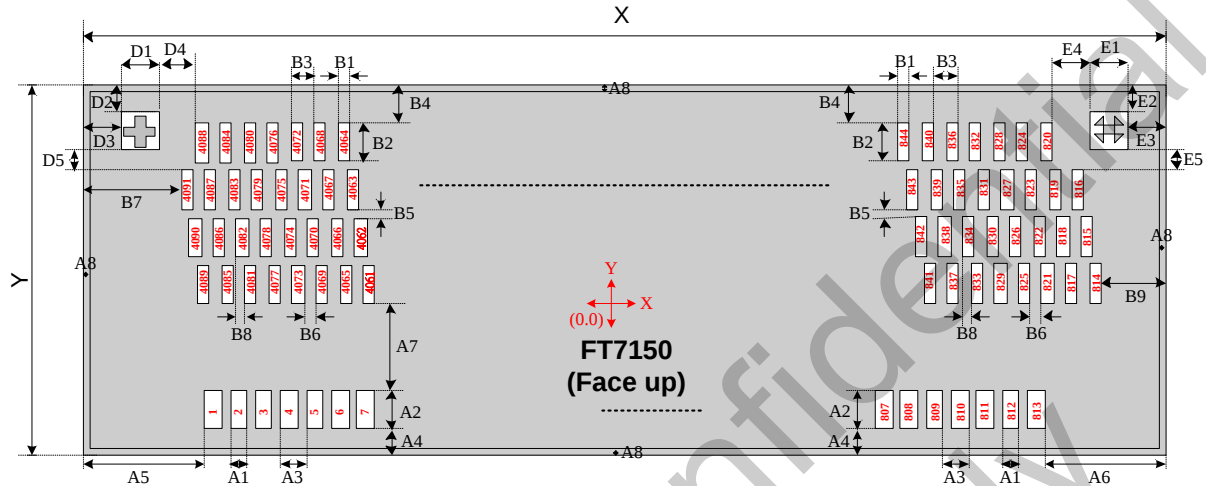
4 Power mode LPWG sequence(VDD is not exist)



4 Power mode TP FW Upgrade

8 CHIP INFORMATION

8.1 PAD Assignment



Symbol	Size	Symbol	Size	Symbol	Size	Symbol	Size
A1	24	B1	15	D1	115	E1	115
A2	100	B2	100	D2	48.2	E2	48.2
A3	39	B3	38.8	D3	113.1	E3	113.1
A4	75	B4	83.2	D4	30.35	E4	78.85
A5	288.5	B5	20	D5	40	E5	40
A6	299.5	B6	23.8				
A7	402	B7	229.35			X	32280
A8	30	B8	9.7			Y	1120.2
		B9	239.05			Unit: um	

Note : Chip Size and Bump space including scribe line

8.2 PAD Dimensions

Item	Pad No.	Size		Unit
		X	Y	
Chip Size	--	32280	1120.2	um
Chip Thickness	--	TBD.		
Pad Pitch	1~813	39	--	
	814~4091	38.8	--	
Pad Size	1~813	24	100	
	814~4091	15	100	

Note1: Chip size included scribe line

No.	PAD Name	X	Y
4007	S[2358]	-15088.35	306.9
4008	RX[15]	-15098.05	426.9
4009	S[2359]	-15107.75	66.9
4010	S[2360]	-15117.45	186.9
4011	S[2361]	-15127.15	306.9
4012	RX[14]	-15136.85	426.9
4013	S[2362]	-15146.55	66.9
4014	S[2363]	-15156.25	186.9
4015	S[2364]	-15165.95	306.9
4016	RX[13]	-15175.65	426.9
4017	S[2365]	-15185.35	66.9
4018	S[2366]	-15195.05	186.9
4019	S[2367]	-15204.75	306.9
4020	RX[12]	-15214.45	426.9
4021	S[2368]	-15224.15	66.9
4022	S[2369]	-15233.85	186.9
4023	S[2370]	-15243.55	306.9
4024	RX[11]	-15253.25	426.9
4025	S[2371]	-15262.95	66.9
4026	S[2372]	-15272.65	186.9
4027	S[2373]	-15282.35	306.9
4028	RX[10]	-15292.05	426.9
4029	S[2374]	-15301.75	66.9
4030	S[2375]	-15311.45	186.9
4031	S[2376]	-15321.15	306.9
4032	RX[9]	-15330.85	426.9
4033	S[2377]	-15340.55	66.9
4034	S[2378]	-15350.25	186.9
4035	S[2379]	-15359.95	306.9
4036	RX[8]	-15369.65	426.9
4037	S[2380]	-15379.35	66.9
4038	S[2381]	-15389.05	186.9
4039	S[2382]	-15398.75	306.9

No.	PAD Name	X	Y
4040	RX[7]	-15408.45	426.9
4041	S[2383]	-15418.15	66.9
4042	S[2384]	-15427.85	186.9
4043	S[2385]	-15437.55	306.9
4044	RX[6]	-15447.25	426.9
4045	S[2386]	-15456.95	66.9
4046	S[2387]	-15466.65	186.9
4047	S[2388]	-15476.35	306.9
4048	RX[5]	-15486.05	426.9
4049	S[2389]	-15495.75	66.9
4050	S[2390]	-15505.45	186.9
4051	S[2391]	-15515.15	306.9
4052	RX[4]	-15524.85	426.9
4053	S[2392]	-15534.55	66.9
4054	S[2393]	-15544.25	186.9
4055	S[2394]	-15553.95	306.9
4056	RX[3]	-15563.65	426.9
4057	S[2395]	-15573.35	66.9
4058	S[2396]	-15583.05	186.9
4059	S[2397]	-15592.75	306.9
4060	RX[2]	-15602.45	426.9
4061	S[2398]	-15612.15	66.9
4062	S[2399]	-15621.85	186.9
4063	S[2400]	-15631.55	306.9
4064	RX[1]	-15641.25	426.9
4065	SDUM[2]	-15650.95	66.9
4066	SDUM[3]	-15660.65	186.9
4067	DUMMY_OL[1]	-15670.35	306.9
4068	SXDUM2	-15680.05	426.9
4069	DUMMY_OL[2]	-15689.75	66.9
4070	DUMMY_OL[3]	-15699.45	186.9
4071	DUMMY_OL[4]	-15709.15	306.9
4072	DUMMY_OL[5]	-15718.85	426.9

No.	PAD Name	X	Y
4073	VCOM_PASS_L	-15728.55	66.9
4074	VCOM_PASS_L	-15738.25	186.9
4075	VCOM_PASS_L	-15747.95	306.9
4076	DUMMY_OL[6]	-15757.65	426.9
4077	VCOM_PASS_L	-15767.35	66.9
4078	VCOM_PASS_L	-15777.05	186.9
4079	VCOM_PASS_L	-15786.75	306.9
4080	DUMMY_OL[7]	-15796.45	426.9
4081	SYNC_GAM_L[5]	-15806.15	66.9
4082	SYNC_GAM_L[4]	-15815.85	186.9
4083	SYNC_GAM_L[3]	-15825.55	306.9
4084	DUMMY_OL[8]	-15835.25	426.9
4085	SYNC_GAM_L[2]	-15844.95	66.9
4086	SYNC_GAM_L[1]	-15854.65	186.9
4087	SYNC_GAM_L[0]	-15864.35	306.9
4088	DUMMY_OL[9]	-15874.05	426.9
4089	DUMMY_OL[10]	-15883.75	66.9
4090	DUMMY_OL[11]	-15893.45	186.9
4091	DUMMY_OL[12]	-15903.15	306.9

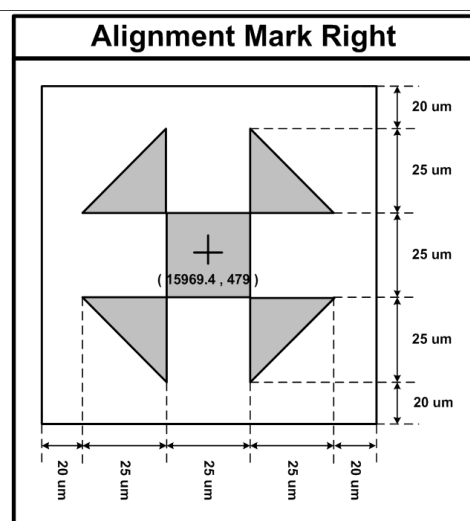
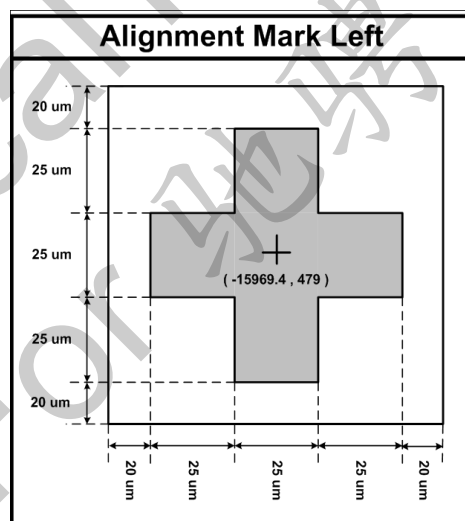
8.4 Alignment Mark

--Alignment Mark coordinate

Left (-15969.4,479)

Right (15969.4,479)

--Alignment Mark size



9 DISCLAIMER

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10 REVISION HISTORY

Date	Revision #	Description	Page	Auditor
Dec. 10, 2025	0.1	ALL	ALL	Willie Chen